DATA SHEET

80C32/87C52
CMOS single-chip 8-bit microcontrollers

Product specification

1996 Aug 16

IC20 Data Handbook

Philips
Semiconductors

PHILIPS

DESCRIPTION

The Philips 80C32/87C52 is a high-performance microcontroller fabricated with Philips high-density CMOS technology. The Philips CMOS technology combines the high speed and density characteristics of HMOS with the low power attributes of CMOS. Philips epitaxial substrate minimizes latch-up sensitivity.

The 87C52 contains an 8k × 8 EPROM and the 80C32 is ROMless. Both contain a 256 × 8 RAM, 32 I/O lines, three 16-bit counter/timers, a six-source, two-priority level nested interrupt structure, a serial I/O port for either multi-processor communications, I/O expansion or full duplex UART, and on-chip oscillator and clock circuits.

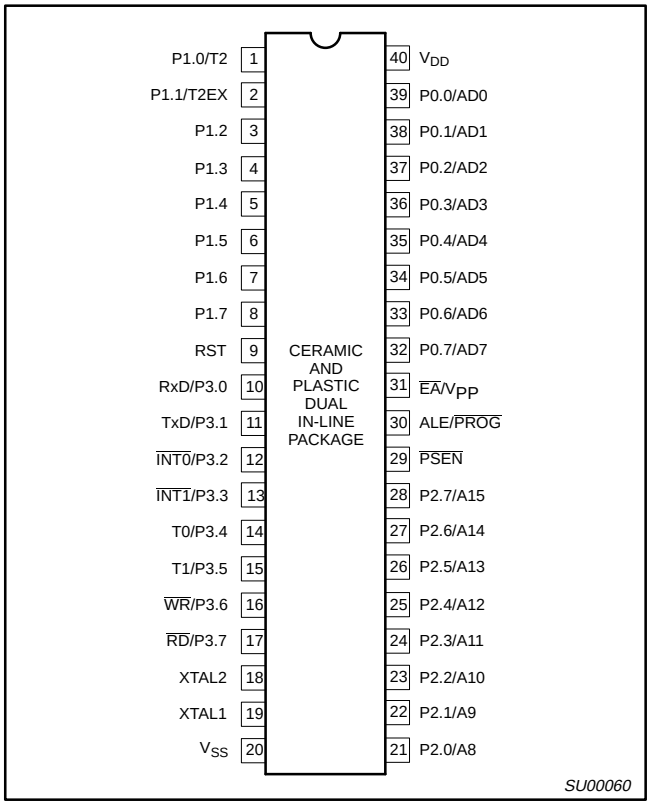
In addition, the 80C32/87C52 has two software selectable modes of power reduction—idle mode and power-down mode. The idle mode freezes the CPU while allowing the RAM, timers, serial port, and interrupt system to continue functioning. The power-down mode saves the RAM contents but freezes the oscillator, causing all other chip functions to be inoperative.

See 80C52/80C54/80C58 datasheet for ROM device specifications.

FEATURES

- 80C51 based architecture
- 8032 compatible
  - 8k × 8 EPROM (87C52)
  - ROMless (80C32)
  - 256 × 8 RAM
  - Three 16-bit counter/timers
  - Full duplex serial channel
  - Boolean processor
- Memory addressing capability
  - 64k ROM and 64k RAM
- Power control modes:
  - Idle mode
  - Power-down mode
- CMOS and TTL compatible
- Three speed ranges:
  - 3.5 to 16MHz
  - 3.5 to 24MHz
  - 3.5 to 33MHz
- Five package styles
- Extended temperature ranges
- OTP package available

PIN CONFIGURATIONS



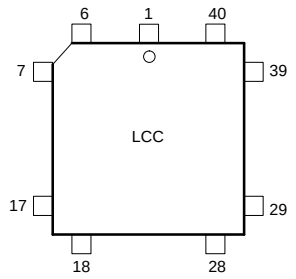
ORDERING INFORMATION

ROMless	EPROM[1]		TEMPERATURE RANGE °C AND PACKAGE	FREQ MHz	DRAWING NUMBER
P80C32EBP N	P87C52EBP N	OTP	0 to +70, Plastic Dual In-line Package	16	SOT129-1
P80C32EBA A	P87C52EBA A	OTP	0 to +70, Plastic Leaded Chip Carrier	16	SOT187-2
	P87C52EBF FA	UV	0 to +70, Ceramic Dual In-line Package	16	0590B
	P87C52EBL KA	UV	0 to +70, Ceramic Leaded Chip Carrier	16	1472A
P80C32EBB B	P87C52EBB B	OTP	0 to +70, Plastic Quad Flat Pack	16	SOT307-2
P80C32EFP N	P87C52EFP N	OTP	–40 to +85, Plastic Dual In-line Package	16	SOT129-1
P80C32EFA A	P87C52EFA A	OTP	–40 to +85, Plastic Leaded Chip Carrier	16	SOT187-2
	P87C52EFF FA	UV	–40 to +85, Ceramic Dual In-line Package	16	0590B
P80C32EFB B	P87C52EFB B	OTP	–40 to +85, Plastic Quad Flat Pack	16	SOT307-2
P80C32IBP N	P87C52IBP N	OTP	0 to +70, Plastic Dual In-line Package	24	SOT129-1
P80C32IBA A	P87C52IBA A	OTP	0 to +70, Plastic Leaded Chip Carrier	24	SOT187-2
P80C32IBB B			0 to +70, Plastic Quad Flat Pack	24	SOT307-2
	P87C52IBF FA	UV	0 to +70, Ceramic Dual In-line Package	24	0590B
	P87C52IBL KA	UV	0 to +70, Ceramic Leaded Chip Carrier	24	1472A
P80C32IFP N	P87C52IFP N	OTP	–40 to +85, Plastic Dual In-line Package	24	SOT129-1
P80C32IFA A	P87C52IFA A	OTP	–40 to +85, Plastic Leaded Chip Carrier	24	SOT187-2
P80C32IFB B			–40 to +85, Plastic Quad Flat Pack	24	SOT307-2
	P87C52IFF FA	UV	–40 to +85, Ceramic Dual In-line Package	24	0590B
P80C32NBA A			0 to +70, Plastic Leaded Chip Carrier	33	SOT187-2
P80C32NBP N			0 to +70, Plastic Dual In-line Package	33	SOT129-1
P80C32NBB B			0 to +70, Plastic Quad Flat Pack	33	SOT307-2
P80C32NFA A			–40 to +85, Plastic Leaded Chip Carrier	33	SOT187-2
P80C32NFP N			–40 to +85, Plastic Dual In-line Package	33	SOT129-1
P80C32NFB B			–40 to +85, Plastic Quad Flat Pack	33	SOT307-2

NOTE:

1. OTP = One Time Programmable EPROM. UV = UV erasable EPROM
2. For 33MHz ROM 80C52 operation, see 80C52/80C54/80C58 data sheet.

CERAMIC AND PLASTIC LEADED CHIP CARRIER PIN FUNCTIONS



Pin	Function	Pin	Function	Pin	Function
1	NC*	16	T0/P3.4	31	P2.7/A15
2	T2/P1.0	17	T1/P3.5	32	$\overline{PSEN}$
3	T2EX/P1.1	18	$\overline{WR}$/P3.6	33	ALE/$\overline{PROG}$
4	P1.2	19	$\overline{RD}$/P3.7	34	NC*
5	P1.3	20	XTAL2	35	$\overline{EA}$/V_{PP}
6	P1.4	21	XTAL1	36	P0.7/AD7
7	P1.5	22	V_{SS}	37	P0.6/AD6
8	P1.6	23	NC*	38	P0.5/AD5
9	P1.7	24	P2.0/A8	39	P0.4/AD4
10	RST	25	P2.1/A9	40	P0.3/AD3
11	RxD/P3.0	26	P2.2/A10	41	P0.2/AD2
12	NC*	27	P2.3/A11	42	P0.1/AD1
13	TxD/P3.1	28	P2.4/A12	43	P0.0/AD0
14	$\overline{INT0}$/P3.2	29	P2.5/A13	44	V_{CC}
15	$\overline{INT1}$/P3.3	30	P2.6/A14		

* DO NOT CONNECT

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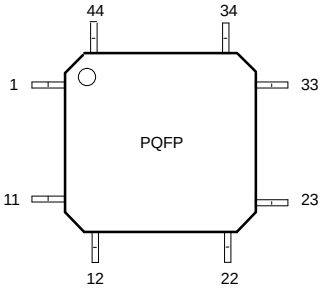
PLASTIC QUAD FLAT PACK PIN FUNCTIONS



Pin	Function	Pin	Function	Pin	Function
1	P1.5	16	V_{SS}	31	P0.6/AD6
2	P1.6	17	NC*	32	P0.5/AD5
3	P1.7	18	P2.0/A8	33	P0.4/AD4
4	RST	19	P2.1/A9	34	P0.3/AD3
5	RxD/P3.0	20	P2.2/A10	35	P0.2/AD2
6	NC*	21	P2.3/A11	36	P0.1/AD1
7	TxD/P3.1	22	P2.4/A12	37	P0.0/AD0
8	$\overline{INT0}$/P3.2	23	P2.5/A13	38	V_{CC}
9	$\overline{INT1}$/P3.3	24	P2.6/A14	39	NC*
10	T0/P3.4	25	P2.7/A15	40	T2/P1.0
11	T1/P3.5	26	$\overline{PSEN}$	41	T2EX/P1.1
12	$\overline{WR}$/P3.6	27	ALE/$\overline{PROG}$	42	P1.2
13	$\overline{RD}$/P3.7	28	NC*	43	P1.3
14	XTAL2	29	$\overline{EA}$/V_{PP}	44	P1.4
15	XTAL1	30	P0.7/AD7		

* DO NOT CONNECT

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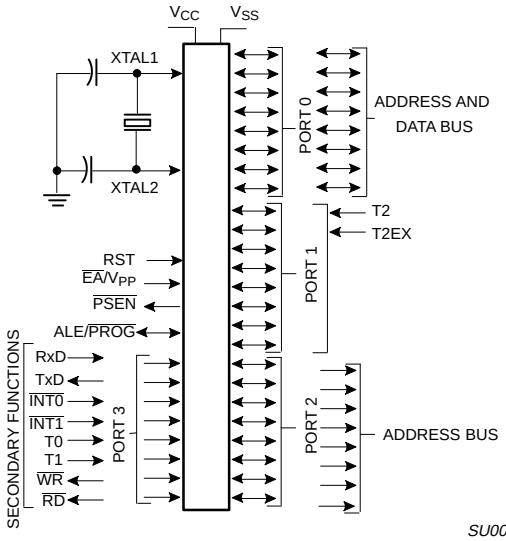
LOGIC SYMBOL



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BLOCK DIAGRAM

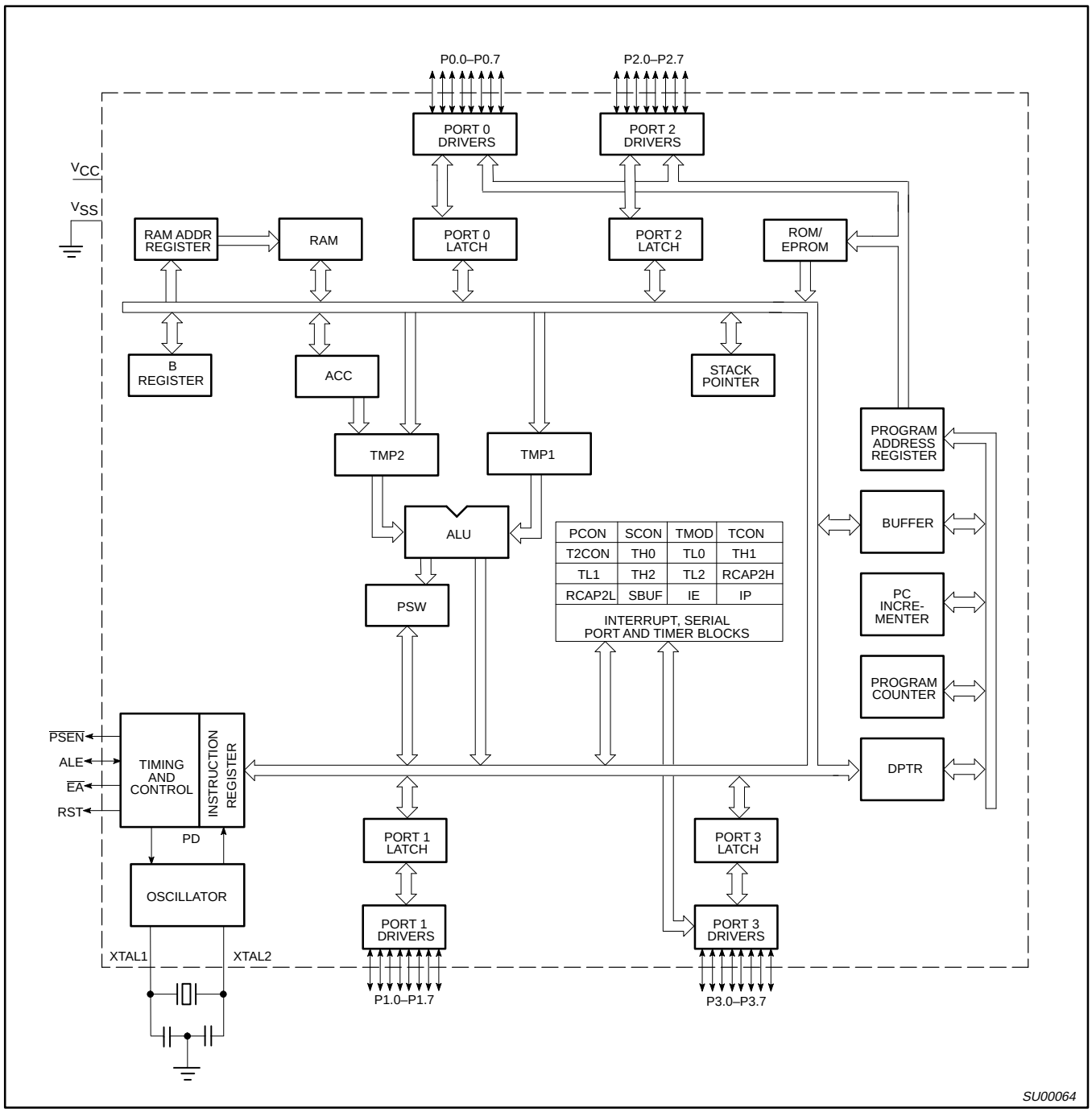


Table 1. 8XC52 Special Function Registers

SYMBOL	DESCRIPTION	DIRECT ADDRESS	BIT ADDRESS, SYMBOL, OR ALTERNATIVE PORT FUNCTION MSB							LSB	RESET VALUE
ACC*	Accumulator	E0H	E7	E6	E5	E4	E3	E2	E1	E0	00H
B*	B register	F0H	F7	F6	F5	F4	F3	F2	F1	F0	00H
DPTR:	Data pointer (2 bytes)										
DPH	Data pointer high	83H									00H
DPL	Data pointer low	82H									00H
			AF	AE	AD	AC	AB	AA	A9	A8	
IE*	Interrupt enable	A8H	EA	–	ET2	ES	ET1	EX1	ET0	EX0	0x000000B
			BF	BE	BD	BC	BB	BA	B9	B8	
IP*	Interrupt priority	B8H	–	–	PT2	PS	PT1	PX1	PT0	PX0	xx000000B
			87	86	85	84	83	82	81	80	
P0*	Port 0	80H	AD7	AD6	AD5	AD4	AD3	AD2	AD1	AD0	FFH
			97	96	95	94	93	92	91	90	
P1*	Port 1	90H	–	–	–	–	–	–	T2EX	T2	FFH
			A7	A6	A5	A4	A3	A2	A1	A0	
P2*	Port 2	A0H	A15	A14	A13	A12	A11	A10	A9	A8	FFH
			B7	B6	B5	B4	B3	B2	B1	B0	
P3*	Port 3	B0H	$\overline{RD}$	$\overline{WR}$	T1	T0	$\overline{INT1}$	$\overline{INT0}$	TxD	RxD	FFH
PCON[1]	Power control	87H	SMOD	–	–	–	GF1	GF0	PD	IDL	0xxxxxxxB
			D7	D6	D5	D4	D3	D2	D1	D0	
PSW*	Program status word	D0H	CY	AC	F0	RS1	RS0	OV	–	P	00H
RCAP2H#	Capture high	CBH									00H
RCAPL#	Capture low	CAH									00H
SBUF	Serial data buffer	99H									xxxxxxxxB
			9F	9E	9D	9C	9B	9A	99	98	
SCON*	Serial controller	98H	SM0	SM1	SM2	REN	TB8	RB8	TI	RI	00H
SP	Stack pointer	81H									07H
			8F	8E	8D	8C	8B	8A	89	88	
TCON*	Timer control	88H	TF1	TR1	TF0	TR0	IE1	IT1	IE0	IT0	00H
			CF	CE	CD	CC	CB	CA	C9	C8	
T2CON*#	Timer 2 control	C8H	TF2	EXF2	RCLK	TCLK	EXEN2	TR2	C/$\overline{T2}$	CP/$\overline{RL2}$	00H
TH0	Timer high 0	8CH									00H
TH1	Timer high 1	8DH									00H
TH2#	Timer high 2	CDH									00H
TL0	Timer low 0	8AH									00H
TL1	Timer low 1	8BH									00H
TL2#	Timer low 2	CCH									00H
TMOD	Timer mode	89H	GATE	C/$\overline{T}$	M1	M0	GATE	C/$\overline{T}$	M1	M0	00H

* Bit addressable

\# SFRs are modified from or added to the 80C51 SFRs.

1. Bits GF1, GF0, PD, and IDL of the PCON register are not implemented in the NMOS 8XC52.

PIN DESCRIPTION

MNEMONIC	PIN NO. DIP	PIN NO. LCC	PIN NO. QFP	TYPE	NAME AND FUNCTION
V_{SS}	20	22	16	I	**Ground:** 0V reference.
V_{CC}	40	44	38	I	**Power Supply:** This is the power supply voltage for normal, idle, and power-down operation.
P0.0–0.7	39–32	43–36	37–30	I/O	**Port 0:** Port 0 is an open-drain, bidirectional I/O port. Port 0 pins that have 1s written to them float and can be used as high-impedance inputs. Port 0 is also the multiplexed low-order address and data bus during accesses to external program and data memory. In this application, it uses strong internal pull-ups when emitting 1s. Port 0 also outputs the code bytes during program verification in the 87C52. External pull-ups are required during program verification.
P1.0–P1.7	1–8	2–9	40–44 1–3	I/O	**Port 1:** Port 1 is an 8-bit bidirectional I/O port with internal pull-ups. Port 1 pins that have 1s written to them are pulled high by the internal pull-ups and can be used as inputs. As inputs, port 1 pins that are externally pulled low will source current because of the internal pull-ups. (See DC Electrical Characteristics: I_{IL}). Pins P1.0 and P1.1 also. Port 1 also receives the low-order address byte during program memory verification. Port 1 also serves alternate functions for timer 2:
	1	2	40	I	**T2 (P1.0):** Timer/counter 2 external count input.
	2	3	41	I	**T2EX (P1.1):** Timer/counter 2 trigger input.
P2.0–P2.7	21–28	24–31	18–25	I/O	**Port 2:** Port 2 is an 8-bit bidirectional I/O port with internal pull-ups. Port 2 pins that have 1s written to them are pulled high by the internal pull-ups and can be used as inputs. As inputs, port 2 pins that are externally being pulled low will source current because of the internal pull-ups. (See DC Electrical Characteristics: I_{IL}). Port 2 emits the high-order address byte during fetches from external program memory and during accesses to external data memory that use 16-bit addresses (MOVX @DPTR). In this application, it uses strong internal pull-ups when emitting 1s. During accesses to external data memory that use 8-bit addresses (MOV @Ri), port 2 emits the contents of the P2 special function register.
P3.0–P3.7	10–17	11, 13–19	5, 7–13	I/O	**Port 3:** Port 3 is an 8-bit bidirectional I/O port with internal pull-ups. Port 3 pins that have 1s written to them are pulled high by the internal pull-ups and can be used as inputs. As inputs, port 3 pins that are externally being pulled low will source current because of the pull-ups. (See DC Electrical Characteristics: I_{IL}). Port 3 also serves the special features of the 80C51 family, as listed below:
	10	11	5	I	**RxD (P3.0):** Serial input port
	11	13	7	O	**TxD (P3.1):** Serial output port
	12	14	8	I	**$\overline{\text{INT0}}$ (P3.2):** External interrupt
	13	15	9	I	**$\overline{\text{INT1}}$ (P3.3):** External interrupt
	14	16	10	I	**T0 (P3.4):** Timer 0 external input
	15	17	11	I	**T1 (P3.5):** Timer 1 external input
	16	18	12	O	**$\overline{\text{WR}}$ (P3.6):** External data memory write strobe
	17	19	13	O	**$\overline{\text{RD}}$ (P3.7):** External data memory read strobe
RST	9	10	4	I	**Reset:** A high on this pin for two machine cycles while the oscillator is running, resets the device. An internal diffused resistor to V_{SS} permits a power-on reset using only an external capacitor to V_{CC}.
ALE/$\overline{\text{PROG}}$	30	33	27	I/O	**Address Latch Enable/Program Pulse:** Output pulse for latching the low byte of the address during an access to external memory. In normal operation, ALE is emitted at a constant rate of 1/6 the oscillator frequency, and can be used for external timing or clocking. Note that one ALE pulse is skipped during each access to external data memory. This pin is also the program pulse input ($\overline{\text{PROG}}$) during EPROM programming.
$\overline{\text{PSEN}}$	29	32	26	O	**Program Store Enable:** The read strobe to external program memory. When the device is executing code from the external program memory, $\overline{\text{PSEN}}$ is activated twice each machine cycle, except that two $\overline{\text{PSEN}}$ activations are skipped during each access to external data memory. $\overline{\text{PSEN}}$ is not activated during fetches from internal program memory.
$\overline{\text{EA}}$/V_{PP}	31	35	29	I	**External Access Enable/Programming Supply Voltage:** $\overline{\text{EA}}$ must be externally held low to enable the device to fetch code from external program memory locations 0000H to 1FFFH. If $\overline{\text{EA}}$ is held high, the device executes from internal program memory unless the program counter contains an address greater than 1FFFH. This pin also receives the 12.75V programming supply voltage (V_{PP}) during EPROM programming.
XTAL1	19	21	15	I	**Crystal 1:** Input to the inverting oscillator amplifier and input to the internal clock generator circuits.
XTAL2	18	20	14	O	**Crystal 2:** Output from the inverting oscillator amplifier.

DIFFERENCES FROM THE 80C51

Special Function Registers

The special function register space is the same as the 80C51 except that the 80C32/87C52 contains the additional special function registers T2CON, RCAP2L, RCAP2H, TL2, and TH2. Since the standard 80C51 on-chip functions are identical in the 8XC52, the SFR locations, bit locations, and operation are likewise identical. The only exceptions are in the interrupt mode and interrupt priority SFRs (see Table 1).

Timer/Counters

In addition to timer/counters 0 and 1 of the 80C51, the 80C32/87C52 contains timer/counter 2. Like timers 0 and 1, timer 2 can operate as either an event timer or as an event counter. This is selected by bit C/T2 in the special function register T2CON (see Figure 1). It has three operating modes: capture, auto-load, and baud rate generator, which are selected by bits in the T2CON as shown in Table 2.

In the Capture Mode there are two options which are selected by bit EXEN2 in T2CON. If EXEN2 = 0, then Timer 2 is a 16-bit timer or counter which upon overflowing sets bit TF2, the Timer 2 overflow bit, which can be used to generate an interrupt. If EXEN2 = 1, then Timer 2 still does the above, but with the added feature that a 1-to-0 transition at external input T2EX causes the current value in the Timer 2 registers, TL2 and TH2, to be captured into registers RCAP2L and RCAP2H, respectively. (RCAP2L and RCAP2H are new special function registers in the 80C52.) In addition, the transition at T2EX causes bit EXF2 in T2CON to be set, and EXF2 like TF2 can generate an interrupt. The Capture Mode is illustrated in Figure 2.

In the auto-reload mode, there are again two options, which are selected by bit EXEN2 in T2CON. If EXEN2 = 0, then when Timer 2 rolls over it not only sets TF2 but also causes the Timer 2 registers to be reloaded with the 16-bit value in registers RCAP2L and RCAP2H, which are preset by software. If EXEN2 = 1, then Timer 2 still does the above, but with the added feature that a 1-to-0 transition at external input T2EX will also trigger the 16-bit reload and set EXF2. The auto-reload mode is illustrated in Figure 3.

The baud rate generation mode is selected by RCLK = 1 and/or TCLK = 1. It will be described in conjunction with the serial port.

Serial Port

The serial port of the 8XC52 is identical to that of the 80C51 except that counter/timer 2 can be used to generate baud rates.

In the 8XC52, Timer 2 is selected as the baud rate generator by setting TCLK and/or RCLK in T2CON (see Figure 1). Note that the baud rate for transmit and receive can be simultaneously different. Setting RCLK and/or TCLK puts Timer into its baud rate generator mode, as shown in Figure 4.

The baud rate generator mode is similar to the auto-reload mode, in that a rollover in TH2 causes the Timer 2 registers to be reloaded with the 16-bit value in registers RCAP2H and RCAP2L, which are preset by software.

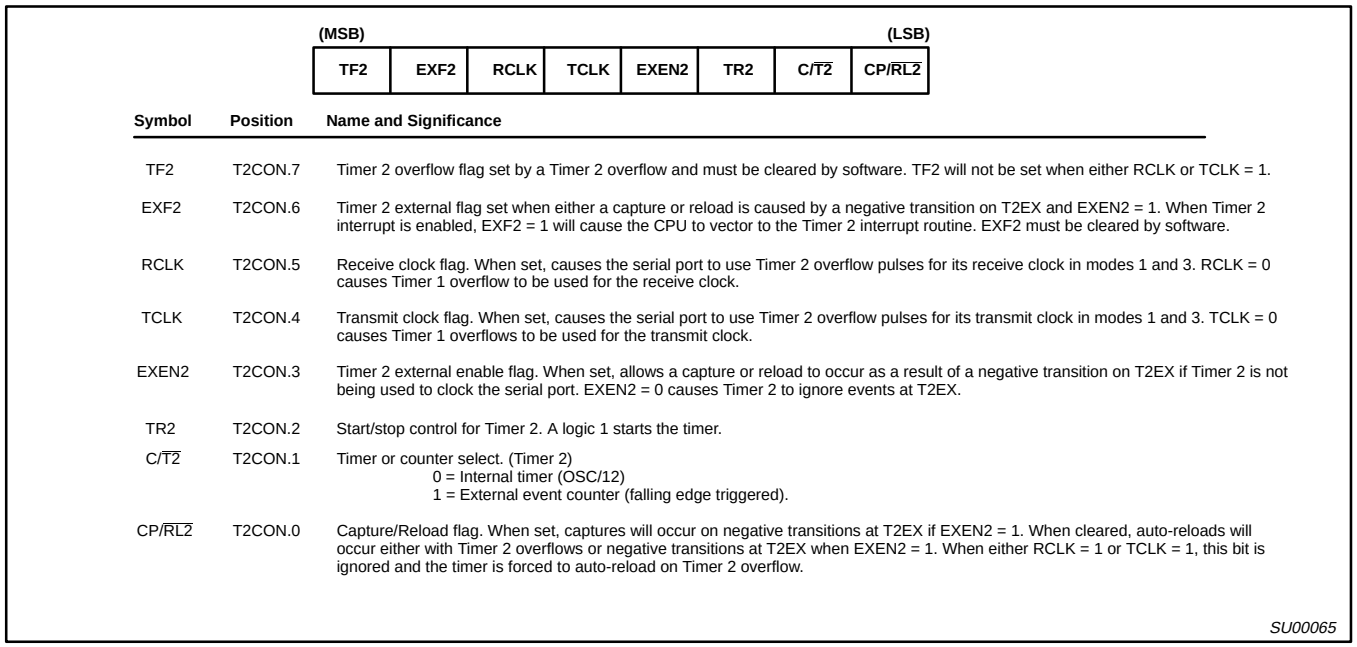
Now, the baud rates in Modes 1 and 3 are determined by Timer 2's overflow rate as follows:

$$\text{Modes 1, 3 Baud Rate} = \frac{\text{Timer 2 Overflow Rate}}{16}$$

The timer can be configured for either "timer" or "counter" operation. In the most typical applications, it is configured for "timer" operation (C/T2 = 0). "Timer" operation is a little different for Timer 2 when it's being used as a baud rate generator. Normally, as a timer it would increment every machine cycle (thus at 1/12 the oscillator frequency). As a baud rate generator, however, it increments every state time (thus at 1/2 the oscillator frequency). In that case the baud rate is given by the formula:

$$\text{Modes 1, 3 Baud Rate} = \frac{\text{Oscillator Frequency}}{32 \times [65536 - (\text{RCAP2H, RCAP2L})]}$$

where (RCAP2H, RCAP2L) is the content of RCAP2H and RCAP2L taken as a 16-bit unsigned integer.



Symbol	Position	Name and Significance
TF2	T2CON.7	Timer 2 overflow flag set by a Timer 2 overflow and must be cleared by software. TF2 will not be set when either RCLK or TCLK = 1.
EXF2	T2CON.6	Timer 2 external flag set when either a capture or reload is caused by a negative transition on T2EX and EXEN2 = 1. When Timer 2 interrupt is enabled, EXF2 = 1 will cause the CPU to vector to the Timer 2 interrupt routine. EXF2 must be cleared by software.
RCLK	T2CON.5	Receive clock flag. When set, causes the serial port to use Timer 2 overflow pulses for its receive clock in modes 1 and 3. RCLK = 0 causes Timer 1 overflow to be used for the receive clock.
TCLK	T2CON.4	Transmit clock flag. When set, causes the serial port to use Timer 2 overflow pulses for its transmit clock in modes 1 and 3. TCLK = 0 causes Timer 1 overflows to be used for the transmit clock.
EXEN2	T2CON.3	Timer 2 external enable flag. When set, allows a capture or reload to occur as a result of a negative transition on T2EX if Timer 2 is not being used to clock the serial port. EXEN2 = 0 causes Timer 2 to ignore events at T2EX.
TR2	T2CON.2	Start/stop control for Timer 2. A logic 1 starts the timer.
C/$\overline{T2}$	T2CON.1	Timer or counter select. (Timer 2) 0 = Internal timer (OSC/12) 1 = External event counter (falling edge triggered).
CP/$\overline{RL2}$	T2CON.0	Capture/Reload flag. When set, captures will occur on negative transitions at T2EX if EXEN2 = 1. When cleared, auto-reloads will occur either with Timer 2 overflows or negative transitions at T2EX when EXEN2 = 1. When either RCLK = 1 or TCLK = 1, this bit is ignored and the timer is forced to auto-reload on Timer 2 overflow.

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Figure 1. Timer/Counter 2 (T2CON) Control Register

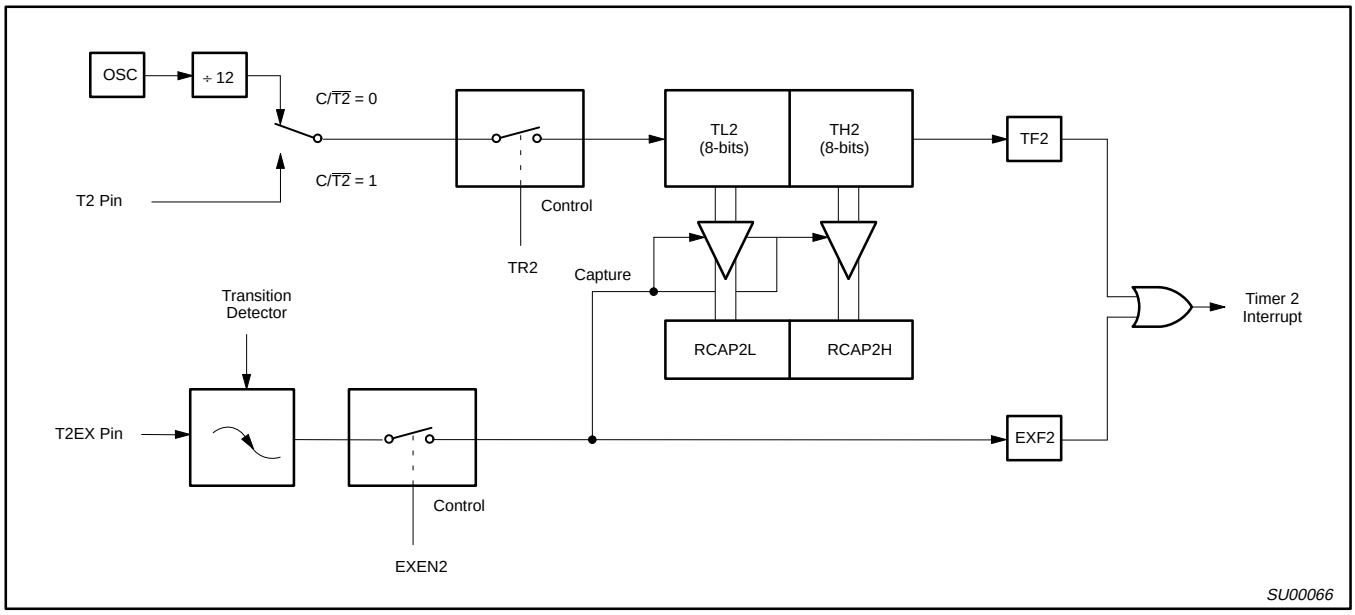


Figure 2. Timer 2 in Capture Mode

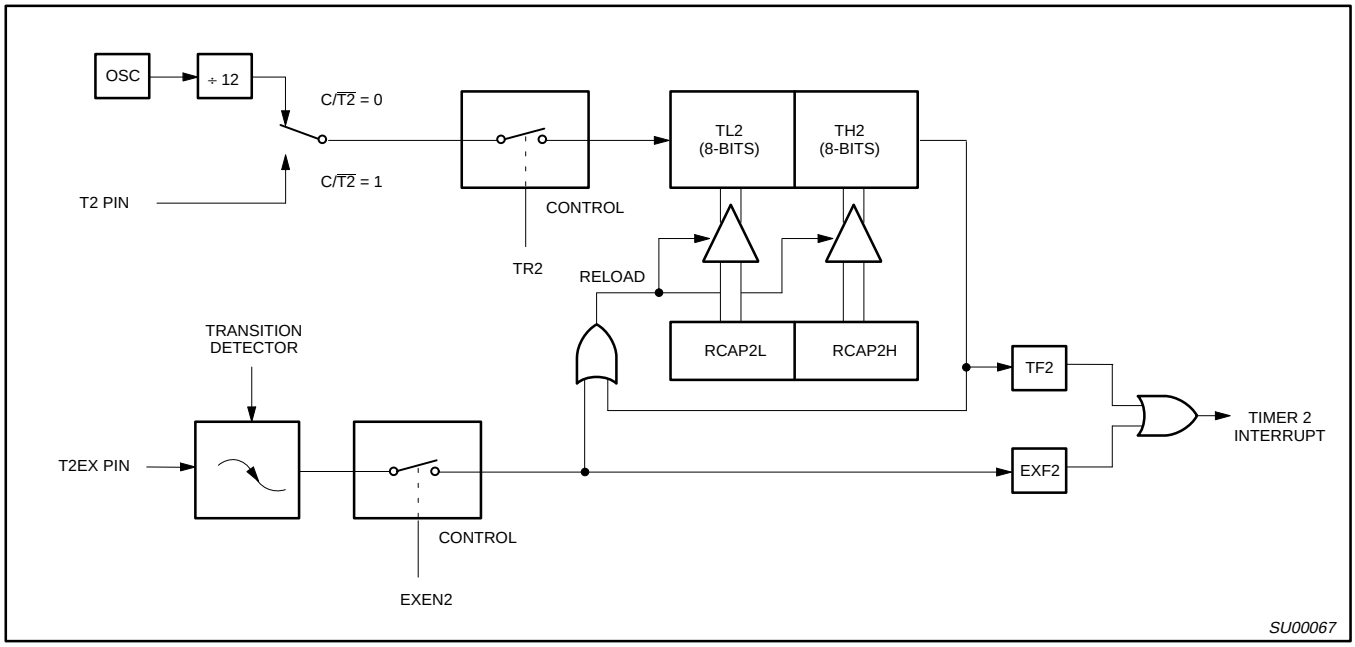


Figure 3. Timer 2 in Auto-Reload Mode

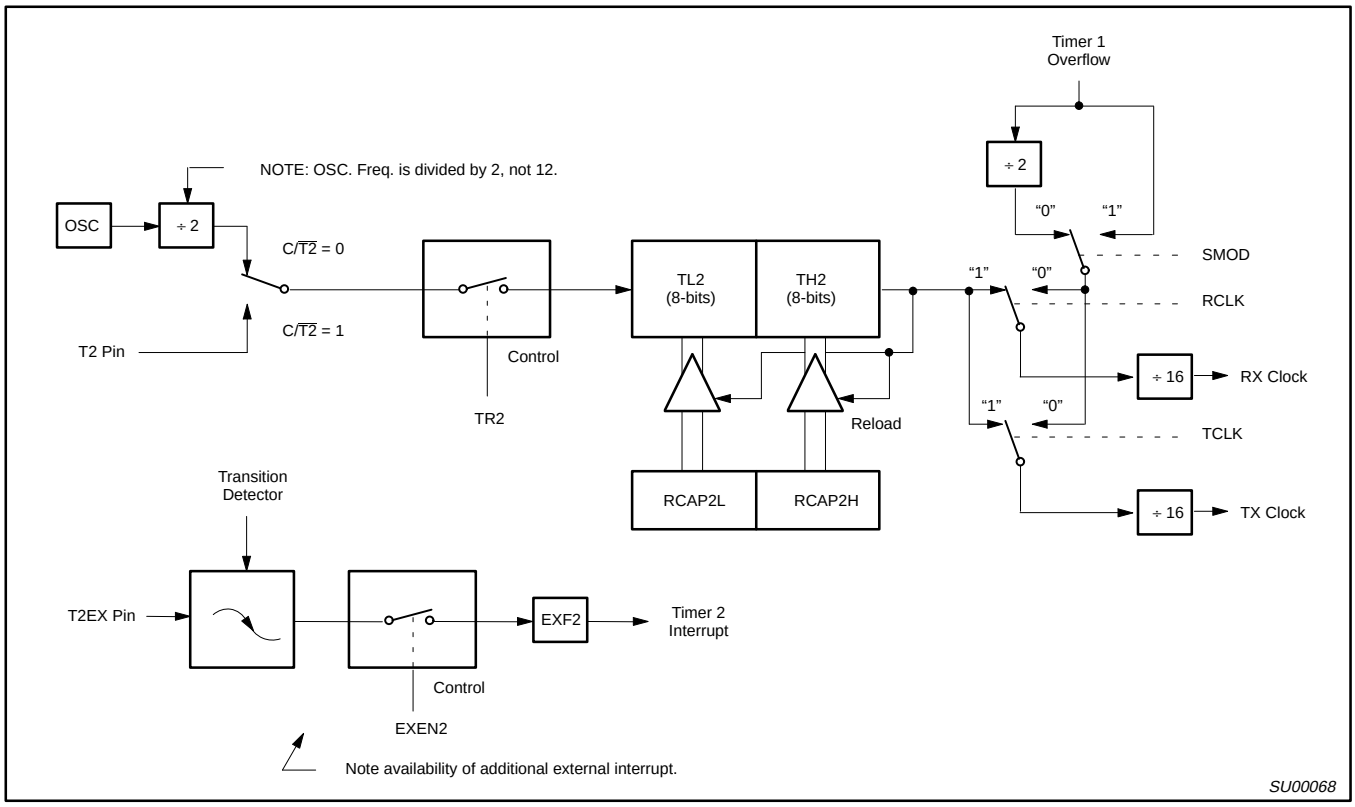


Figure 4. Timer 2 in Baud Rate Generator Mode

Table 2. Timer 2 Operating Modes

RCLK + TCLK	CP/$\overline{RL2}$	TR2	MODE
0	0	1	16-bit Auto-reload
0	1	1	16-bit Capture
1	X	1	Baud rate generator
X	X	0	(off)

Timer 2 as a baud rate generator is shown in Figure 4. This figure is valid only if RCLK + TCLK = 1 in T2CON. Note that a rollover in TH2 does not set TF2, and will not generate an interrupt. Therefore, the Timer 2 interrupt does not have to be disabled when Timer 2 is in the baud rate generator mode. Note too, that if EXEN2 is set, a 1-to-0 transition in T2EX will set EXF2 but will not cause a reload from (RCAP2H, RCAP2L) to (TH2, TL2). Thus when Timer 2 is in use as a baud rate generator, T2EX can be used as an extra external interrupt, if desired.

It should be noted that when Timer 2 is running (TR2 = 1) in "timer" function in the baud rate generator mode, one should not try to read or write TH2 or TL2. Under these conditions the timer is being incremented every state time, and the results of a read or write may not be accurate. The RCAP registers may be read, but should not be written to, because a write might overlap a reload and cause write and/or reload errors. Turn the timer off (clear TR2) before accessing the Timer 2 or RCAP registers, in this case.

Timer/Counter 2 Set-up

Except for the baud rate generator mode, the values given for T2CON do not include the setting of the TR2 bit. Therefore, bit TR2 must be set, separately, to turn the timer on. See Table 3 for set-up of timer 2 as a timer. See Table 4 for set-up of timer 2 as a counter.

Using Timer/Counter 2 to Generate Baud Rates

For this purpose, Timer 2 must be used in the baud rate generating mode. If Timer 2 is being clocked through pin T2 (P1.0) the baud rate is:

$$\text{Baud Rate} = \frac{\text{Timer 2 Overflow Rate}}{16}$$

And if it is being clocked internally, the baud rate is:

$$\text{Baud Rate} = \frac{\text{Oscillator Frequency}}{32 \times [65536 - (\text{RCAP2H, RCAP2L})]}$$

To obtain the reload value for RCAP2H and RCA02L, the above equation can be rewritten as:

$$\text{RCAP2H, RCAP2L} = 65536 - \frac{\text{Oscillator Frequency}}{32 \times \text{Baud Rate}}$$

Interrupts

The 80C32/87C52 has 6 interrupt sources. All except TF2 and EXF2 are identical sources to those in the 80C51.

The Interrupt Enable Register and the Interrupt Priority Register are modified to include the additional 80C32/87C52 interrupt sources. The operation of these registers is identical to the 80C51.

In the 80C32/87C52, the Timer 2 Interrupt is generated by the logical OR of TF2 and EXF2. Neither of these flags is cleared by hardware when the service routine is vectored to. In fact, the service routine may have to determine whether it was TF2 or EXF2 that generated the interrupt, and the bit will have to be cleared in software.

All of the bits that generate interrupts can be set or cleared by software, with the same result as though it has been set or cleared by hardware. That is, interrupts can be generated or pending interrupts can be canceled in software.

The interrupt vector addresses and the interrupt priority for requests in the same priority level are given in the following:

Source	Vector Address	Priority Within Level
1. IE0	0003H	(highest)
2. TF0	000BH	
3. IE1	0013H	
4. TF1	001BH	
5. RI + TI	0023H	
6. TF2 + EXF2	002BH	(lowest)

Note that they are identical to those in the 80C51 except for the addition of the Timer 2 (TF1 and EXF2) interrupt at 002BH and at the lowest priority within a level.

Table 3. Timer 2 as a Timer

MODE	T2CON	
	INTERNAL CONTROL (Note 1)	EXTERNAL CONTROL (Note 2)
16-bit Auto-Reload	00H	08H
16-bit Capture	01H	09H
Baud rate generator receive and transmit same baud rate	34H	36H
Receive only	24H	26H
Transmit only	14H	16H

Table 4. Timer 2 as a Counter

MODE	TMOD	
	INTERNAL CONTROL (Note 1)	EXTERNAL CONTROL (Note 2)
16-bit	02H	0AH
Auto-Reload	03H	0BH

NOTES:
1. Capture/reload occurs only on timer/counter overflow.
2. Capture/reload occurs on timer/counter overflow and a 1-to-0 transition on T2EX (P1.1) pin except when timer 2 is used in the baud rate generator mode.

OSCILLATOR CHARACTERISTICS

XTAL1 and XTAL2 are the input and output, respectively, of an inverting amplifier. The pins can be configured for use as an on-chip oscillator, as shown in the Logic Symbol, page 4.

To drive the device from an external clock source, XTAL1 should be driven while XTAL2 is left unconnected. There are no requirements on the duty cycle of the external clock signal, because the input to the internal clock circuitry is through a divide-by-two flip-flop. However, minimum and maximum high and low times specified in the data sheet must be observed.

RESET

A reset is accomplished by holding the RST pin high for at least two machine cycles (24 oscillator periods), while the oscillator is running. To insure a good power-up reset, the RST pin must be high long enough to allow the oscillator time to start up (normally a few milliseconds) plus two machine cycles.

IDLE MODE

In idle mode, the CPU puts itself to sleep while all of the on-chip peripherals stay active. The instruction to invoke the idle mode is the last instruction executed in the normal operating mode before the idle mode is activated. The CPU contents, the on-chip RAM, and all of the special function registers remain intact during this mode. The idle mode can be terminated either by any enabled interrupt (at which time the process is picked up at the interrupt service routine and continued), or by a hardware reset which starts the processor in the same manner as a power-on reset.

POWER-DOWN MODE

In the power-down mode, the oscillator is stopped and the instruction to invoke power-down is the last instruction executed. Only the contents of the on-chip RAM are preserved. A hardware reset is the only way to terminate the power-down mode. the control bits for the reduced power modes are in the special function register PCON.

DESIGN CONSIDERATIONS

At power-on, the voltage on V_{CC} and RST must come up at the same time for a proper start-up.

Table 5 shows the state of I/O ports during low current operating modes.

As a precaution to coming out of an unexpected power down, $\overline{INT0}$ and $\overline{INT1}$ should be disabled prior to enterring power down.

Table 5. External Pin Status During Idle and Power-Down Modes

MODE	PROGRAM MEMORY	ALE	$\overline{PSEN}$	PORT 0	PORT 1	PORT 2	PORT 3
Idle	Internal	1	1	Data	Data	Data	Data
Idle	External	1	1	Float	Data	Address	Data
Power-down	Internal	0	0	Data	Data	Data	Data
Power-down	External	0	0	Float	Data	Data	Data

Electrical Deviations from Commercial Specifications for Extended Temperature Range (87C52)
DC and AC parameters not included here are the same as in the commercial temperature range table.

DC ELECTRICAL CHARACTERISTICS

T_{amb} = –40°C to +85°C, V_{CC} = 5V ±10%, V_{SS} = 0V

SYMBOL	PARAMETER	TEST CONDITIONS	LIMITS		UNIT
			MIN	MAX	
V_{IL}	Input low voltage, except $\overline{EA}$		–0.5	$0.2V_{CC}$–0.15	V
V_{IL1}	Input low voltage to $\overline{EA}$		0	$0.2V_{CC}$–0.35	V
V_{IH}	Input high voltage, except XTAL1, RST		$0.2V_{CC}$+1	V_{CC}+0.5	V
V_{IH1}	Input high voltage to XTAL1, RST		$0.7V_{CC}$+0.1	V_{CC}+0.5	V
I_{IL}	Logical 0 input current, ports 1, 2, 3	V_{IN} = 0.45V		–75	µA
I_{TL}	Logical 1-to-0 transition current, ports 1, 2, 3	V_{IN} = 2.0V		–750	µA
I_{CC}	Power supply current: Active mode Idle mode Power-down mode	V_{CC} = 4.5–5.5V, Frequency range = 3.5 to 16MHz		 32 5 50	 mA mA µA

ABSOLUTE MAXIMUM RATINGS[1, 2, 3]

PARAMETER	RATING	UNIT
Operating temperature under bias	0 to +70 or –40 to +85	°C
Storage temperature range	–65 to +150	°C
Voltage on $\overline{EA}$/V_{PP} pin to V_{SS}	0 to +13.0	V
Voltage on any other pin to V_{SS}	–0.5 to +6.5	V
Maximum I_{OL} per I/O pin	15	mA
Power dissipation (based on package heat transfer limitations, not device power consumption)	1.5	W

NOTES:

1. Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any conditions other than those described in the AC and DC Electrical Characteristics section of this specification is not implied.
2. This product includes circuitry specifically designed for the protection of its internal devices from the damaging effects of excessive static charge. Nonetheless, it is suggested that conventional precautions be taken to avoid applying greater than the rated maxima.
3. Parameters are valid over operating temperature range unless otherwise specified. All voltages are with respect to V_{SS} unless otherwise noted.

DC ELECTRICAL CHARACTERISTICS

T_{amb} = 0°C to +70°C or –40°C to +85°C, V_{CC} = 5V ±10%, V_{SS} = 0V (87C52)
T_{amb} = 0°C to +70°C or –40°C to +85°C, V_{CC} = 5V ±10%, V_{SS} = 0V (80C32)

SYMBOL	PARAMETER	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP[1]	MAX	
V_{IL}	Input low voltage, except $\overline{EA}$[7]		–0.5		$0.2V_{CC}$–0.1	V
V_{IL1}	Input low voltage to $\overline{EA}$[7]		0		$0.2V_{CC}$–0.3	V
V_{IH}	Input high voltage, except XTAL1, RST[7]		$0.2V_{CC}$+0.9		V_{CC}+0.5	V
V_{IH1}	Input high voltage, XTAL1, RST[7]		$0.7V_{CC}$		V_{CC}+0.5	V
V_{OL}	Output low voltage, ports 1, 2, 3[9]	I_{OL} = 1.6mA[2]			0.45	V
V_{OL1}	Output low voltage, port 0, ALE, $\overline{PSEN}$[9]	I_{OL} = 3.2mA[2]			0.45	V
V_{OH}	Output high voltage, ports 1, 2, 3, ALE, $\overline{PSEN}$[3]	I_{OH} = –60µA, I_{OH} = –25µA I_{OH} = –10µA	2.4 $0.75V_{CC}$ $0.9V_{CC}$			V V V
V_{OH1}	Output high voltage (port 0 in external bus mode)	I_{OH} = –800µA, I_{OH} = –300µA I_{OH} = –80µA	2.4 $0.75V_{CC}$ $0.9V_{CC}$			V V V
I_{IL}	Logical 0 input current, ports 1, 2, 3[7]	V_{IN} = 0.45V			–50	µA
I_{TL}	Logical 1-to-0 transition current, ports 1, 2, 3[7]	See note 4			–650	µA
I_{LI}	Input leakage current, port 0	V_{IN} = V_{IL} or V_{IH}			±10	µA
I_{CC}	Power supply current:[7] Active mode @ 16MHz[5] Idle mode @ 16MHz Power-down mode T_{amb} = 0 to 70°C Power-down mode T_{amb} = –40 to +85°C	See note 6		 11.5 1.3 3	 32 5 50 75	 mA mA µA µA
R_{RST}	Internal reset pull-down resistor		50		300	kΩ
C_{IO}	Pin capacitance[10]				15	pF

NOTES:

1. Typical ratings are not guaranteed. The values listed are at room temperature, 5V.
2. Capacitive loading on ports 0 and 2 may cause spurious noise to be superimposed on the V_{OL}s of ALE and ports 1 and 3. The noise is due to external bus capacitance discharging into the port 0 and port 2 pins when these pins make 1-to-0 transitions during bus operations. In the worst cases (capacitive loading > 100pF), the noise pulse on the ALE pin may exceed 0.8V. In such cases, it may be desirable to qualify ALE with a Schmitt Trigger, or use an address latch with a Schmitt Trigger STROBE input. I_{OL} can exceed these conditions provided that no single output sinks more than 5mA and no more than two outputs exceed the test conditions.
3. Capacitive loading on ports 0 and 2 may cause the V_{OH} on ALE and $\overline{PSEN}$ to momentarily fall below the $0.9V_{CC}$ specification when the address bits are stabilizing.
4. Pins of ports 1, 2 and 3 source a transition current when they are being externally driven from 1 to 0. The transition current reaches its maximum value when V_{IN} is approximately 2V.
5. I_{CCMAX} at other frequencies is given by: Active mode: $I_{CCMAX} = 1.5 \times FREQ + 8.0$: Idle mode: $I_{CCMAX} = 0.14 \times FREQ + 2.31$, where FREQ is the external oscillator frequency in MHz. I_{CCMAX} is given in mA. See Figure 12.
6. See Figures 13 through 16 for I_{CC} test conditions.
7. These values apply only to T_{amb} = 0°C to +70°C. For T_{amb} = –40°C to +85°C, see table on previous page.
8. Load capacitance for port 0, ALE, and $\overline{PSEN}$ = 100pF, load capacitance for all other outputs = 80pF.
9. Under steady state (non-transient) conditions, I_{OL} must be externally limited as follows:
   Maximum I_{OL} per port pin: 15mA (*NOTE: This is 85°C specification.)
   Maximum I_{OL} per 8-bit port: 26mA
   Maximum total I_{OL} for all outputs: 67mA
   If I_{OL} exceeds the test condition, V_{OL} may exceed the related specification. Pins are not guaranteed to sink current greater than the listed test conditions.
10. This limit is for plastic packages. For ceramic packages, the maximum limit is 20pF.

AC ELECTRICAL CHARACTERISTICS

T_{amb} = 0°C to +70°C or –40°C to +85°C, V_{CC} = 5V ±10%, V_{SS} = 0V (87C52)[1, 2, 3]

SYMBOL	FIGURE	PARAMETER	16MHz CLOCK		VARIABLE CLOCK		UNIT
			MIN	MAX	MIN	MAX	
$1/t_{CLCL}$	5	Oscillator frequency Speed versions : E			3.5	16	MHz
t_{LHLL}	5	ALE pulse width	85		$2t_{CLCL}$–40		ns
t_{AVLL}	5	Address valid to ALE low	22		t_{CLCL}–40		ns
t_{LLAX}	5	Address hold after ALE low	32		t_{CLCL}–30		ns
t_{LLIV}	5	ALE low to valid instruction in		150		$4t_{CLCL}$–100	ns
t_{LLPL}	5	ALE low to $\overline{PSEN}$ low	32		t_{CLCL}–30		ns
t_{PLPH}	5	$\overline{PSEN}$ pulse width	142		$3t_{CLCL}$–45		ns
t_{PLIV}	5	$\overline{PSEN}$ low to valid instruction in		82		$3t_{CLCL}$–105	ns
t_{PXIX}	5	Input instruction hold after $\overline{PSEN}$	0		0		ns
t_{PXIZ}	5	Input instruction float after $\overline{PSEN}$		37		t_{CLCL}–25	ns
t_{AVIV}	5	Address to valid instruction in		207		$5t_{CLCL}$–105	ns
t_{PLAZ}	5	$\overline{PSEN}$ low to address float		10		10	ns
Data Memory							
t_{RLRH}	6, 7	$\overline{RD}$ pulse width	275		$6t_{CLCL}$–100		ns
t_{WLWH}	6, 7	$\overline{WR}$ pulse width	275		$6t_{CLCL}$–100		ns
t_{RLDV}	6, 7	$\overline{RD}$ low to valid data in		147		$5t_{CLCL}$–165	ns
t_{RHDX}	6, 7	Data hold after $\overline{RD}$	0		0		ns
t_{RHDZ}	6, 7	Data float after $\overline{RD}$		65		$2t_{CLCL}$–60	ns
t_{LLDV}	6, 7	ALE low to valid data in		350		$8t_{CLCL}$–150	ns
t_{AVDV}	6, 7	Address to valid data in		397		$9t_{CLCL}$–165	ns
t_{LLWL}	6, 7	ALE low to $\overline{RD}$ or $\overline{WR}$ low	137	239	$3t_{CLCL}$–50	$3t_{CLCL}$+50	ns
t_{AVWL}	6, 7	Address valid to $\overline{WR}$ low or $\overline{RD}$ low	122		$4t_{CLCL}$–130		ns
t_{QVWX}	6, 7	Data valid to $\overline{WR}$ transition	13		t_{CLCL}–50		ns
t_{WHQX}	6, 7	Data hold after $\overline{WR}$	13		t_{CLCL}–50		ns
t_{QVWH}	7	Data valid to $\overline{WR}$ high	287		$7t_{CLCL}$–150		ns
t_{RLAZ}	6, 7	$\overline{RD}$ low to address float		0		0	ns
t_{WHLH}	6, 7	$\overline{RD}$ or $\overline{WR}$ high to ALE high	23	103	t_{CLCL}–40	t_{CLCL}+40	ns
External Clock							
t_{CHCX}	9	High time	20		20	t_{CLCL}–t_{CLCX}	ns
t_{CLCX}	9	Low time	20		20	t_{CLCL}–t_{CHCX}	ns
t_{CLCH}	9	Rise time		20		20	ns
t_{CHCL}	9	Fall time		20		20	ns
Shift Register							
t_{XLXL}	8	Serial port clock cycle time	750		$12t_{CLCL}$		ns
t_{QVXH}	8	Output data setup to clock rising edge	492		$10t_{CLCL}$–133		ns
t_{XHQX}	8	Output data hold after clock rising edge	8		$2t_{CLCL}$–117		ns
t_{XHDX}	8	Input data hold after clock rising edge	0		0		ns
t_{XHDV}	8	Clock rising edge to input data valid		492		$10t_{CLCL}$–133	ns

NOTES:

1. Parameters are valid over operating temperature range unless otherwise specified.
2. Load capacitance for port 0, ALE, and $\overline{PSEN}$ = 100pF, load capacitance for all other outputs = 80pF.
3. Interfacing the 80C32/52 to devices with float times up to 45ns is permitted. This limited bus contention will not cause damage to Port 0 drivers.
4. See application note AN457 for external memory interface.

AC ELECTRICAL CHARACTERISTICS

T_{amb} = 0°C to +70°C or –40°C to +85°C, V_{CC} = 5V ±10%, V_{SS} = 0V[1, 2, 3]

SYMBOL	FIGURE	PARAMETER	24MHz CLOCK		VARIABLE CLOCK		33MHz CLOCK		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
$1/t_{CLCL}$	5	Oscillator frequency Speed versions : I : N			3.5	24	 3.5	 33	MHz
t_{LHLL}	5	ALE pulse width	43		$2t_{CLCL}$–40		21		ns
t_{AVLL}	5	Address valid to ALE low	17		t_{CLCL}–25		5		ns
t_{LLAX}	5	Address hold after ALE low	17		t_{CLCL}–25		5		ns
t_{LLIV}	5	ALE low to valid instruction in		102		$4t_{CLCL}$–65		56	ns
t_{LLPL}	5	ALE low to $\overline{PSEN}$ low	17		t_{CLCL}–25		5		ns
t_{PLPH}	5	$\overline{PSEN}$ pulse width	80		$3t_{CLCL}$–45			46	ns
t_{PLIV}	5	$\overline{PSEN}$ low to valid instruction in		65		$3t_{CLCL}$–60		31	ns
t_{PXIX}	5	Input instruction hold after $\overline{PSEN}$	0		0		0		ns
t_{PXIZ}	5	Input instruction float after $\overline{PSEN}$		17		t_{CLCL}–25		5	ns
t_{AVIV}	5	Address to valid instruction in		128		$5t_{CLCL}$–80		72	ns
t_{PLAZ}	5	$\overline{PSEN}$ low to address float		10		10		10	ns
Data Memory									
t_{RLRH}	6, 7	$\overline{RD}$ pulse width	150		$6t_{CLCL}$–100		82		ns
t_{WLWH}	6, 7	$\overline{WR}$ pulse width	150		$6t_{CLCL}$–100		82		ns
t_{RLDV}	6, 7	$\overline{RD}$ low to valid data in		118		$5t_{CLCL}$–90		62	ns
t_{RHDX}	6, 7	Data hold after $\overline{RD}$	0		0		0		ns
t_{RHDZ}	6, 7	Data float after $\overline{RD}$		55		$2t_{CLCL}$–28		33	ns
t_{LLDV}	6, 7	ALE low to valid data in		183		$8t_{CLCL}$–150		92	ns
t_{AVDV}	6, 7	Address to valid data in		210		$9t_{CLCL}$–165		108	ns
t_{LLWL}	6, 7	ALE low to $\overline{RD}$ or $\overline{WR}$ low	75	175	$3t_{CLCL}$–50	$3t_{CLCL}$+50	41	141	ns
t_{AVWL}	6, 7	Address valid to $\overline{WR}$ low or $\overline{RD}$ low	92		$4t_{CLCL}$–75		46		ns
t_{QVWX}	6, 7	Data valid to $\overline{WR}$ transition	12		t_{CLCL}–30		0.3		ns
t_{WHQX}	6, 7	Data hold after $\overline{WR}$	17		t_{CLCL}–25		5		ns
t_{QVWH}	7	Data valid to $\overline{WR}$ high	162		$7t_{CLCL}$–130		82		ns
t_{RLAZ}	6, 7	$\overline{RD}$ low to address float		0		0		0	ns
t_{WHLH}	6, 7	$\overline{RD}$ or $\overline{WR}$ high to ALE high	17	67	t_{CLCL}–25	t_{CLCL}+25	5	5	ns
External Clock									
t_{CHCX}	9	High time	17		17	t_{CLCL}–t_{CLCX}			ns
t_{CLCX}	9	Low time	17		17	t_{CLCL}–t_{CHCX}			ns
t_{CLCH}	9	Rise time		5		5			ns
t_{CHCL}	9	Fall time		5		5			ns
Shift Register									
t_{XLXL}	8	Serial port clock cycle time	505		$12t_{CLCL}$		363		ns
t_{QVXH}	8	Output data setup to clock rising edge	283		$10t_{CLCL}$–133		170		ns
t_{XHQX}	8	Output data hold after clock rising edge	3		$2t_{CLCL}$–80		19		ns
t_{XHDX}	8	Input data hold after clock rising edge	0		0		0		ns
t_{XHDV}	8	Clock rising edge to input data valid		283		$10t_{CLCL}$–133		170	ns

NOTES:
1. Parameters are valid over operating temperature range unless otherwise specified.
2. Load capacitance for port 0, ALE, and $\overline{PSEN}$ = 100pF, load capacitance for all other outputs = 80pF.
3. Interfacing the 8XC52 to devices with float times up to 45ns is permitted. This limited bus contention will not cause damage to Port 0 drivers.
4. Variable clock is specified for oscillator frequencies greater than 16MHz to 33MHz. For frequencies equal or less than 16MHz, see 16MHz "AC Electrial Characteristics", page 15.

EXPLANATION OF THE AC SYMBOLS

Each timing symbol has five characters. The first character is always 't' (= time). The other characters, depending on their positions, indicate the name of a signal or the logical status of that signal. The designations are:

A – Address
C – Clock
D – Input data
H – Logic level high
I – Instruction (program memory contents)
L – Logic level low, or ALE
P – $\overline{\text{PSEN}}$
Q – Output data
R – $\overline{\text{RD}}$ signal
t – Time
V – Valid
W – $\overline{\text{WR}}$ signal
X – No longer a valid logic level
Z – Float

Examples: t_{AVLL} = Time for address valid to ALE low.
t_{LLPL} = Time for ALE low to $\overline{\text{PSEN}}$ low.

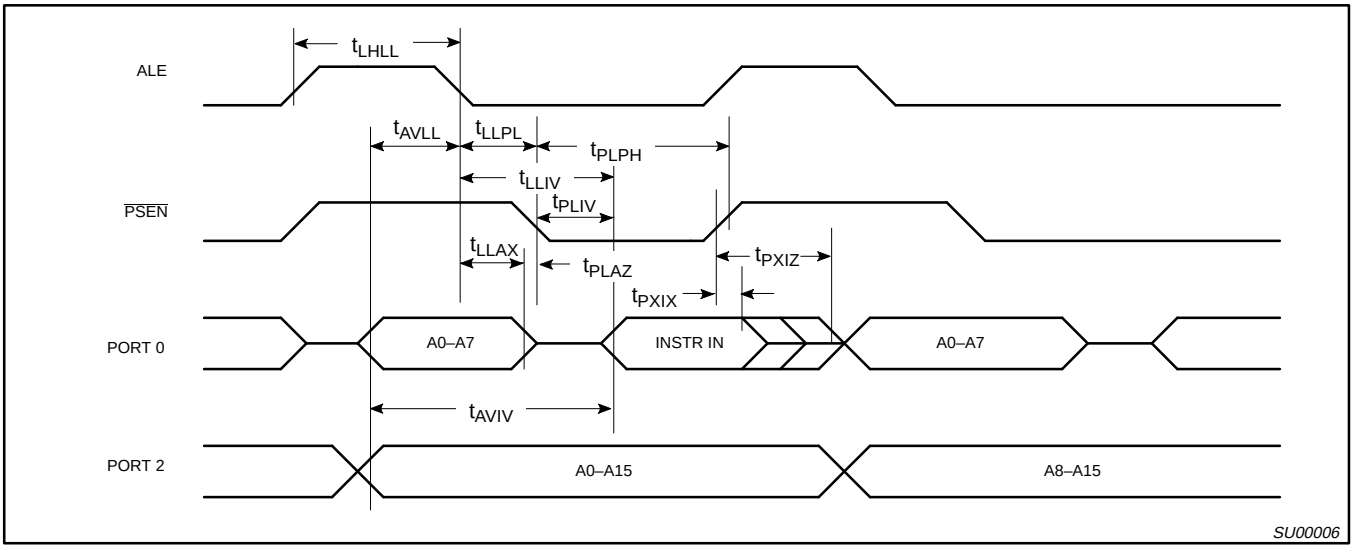


Figure 5. External Program Memory Read Cycle

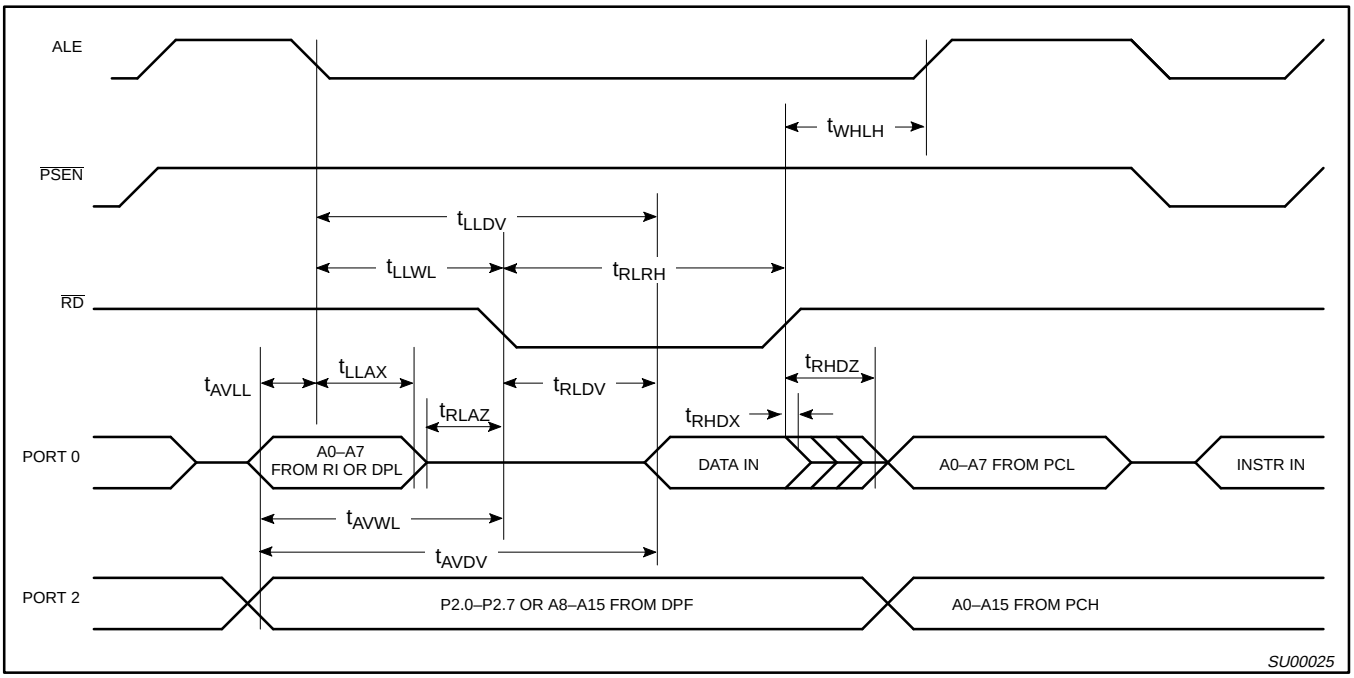


Figure 6. External Data Memory Read Cycle

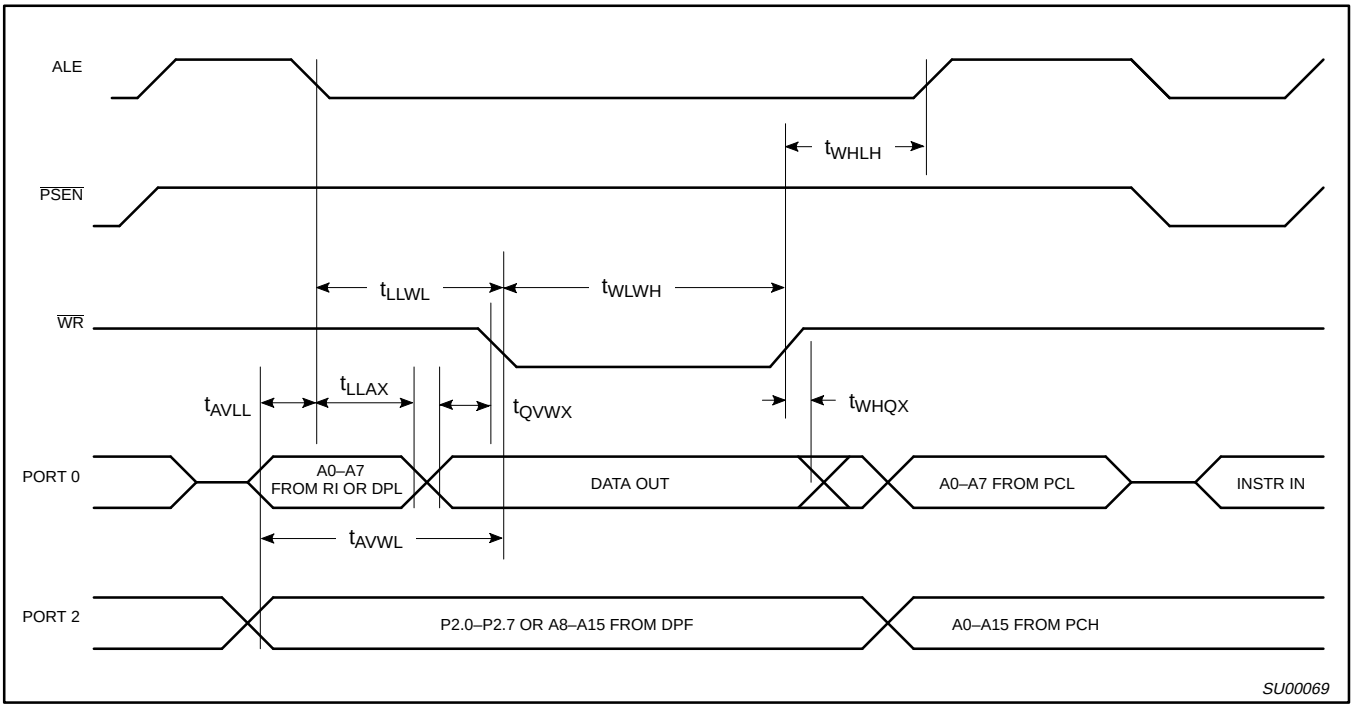


Figure 7. External Data Memory Write Cycle

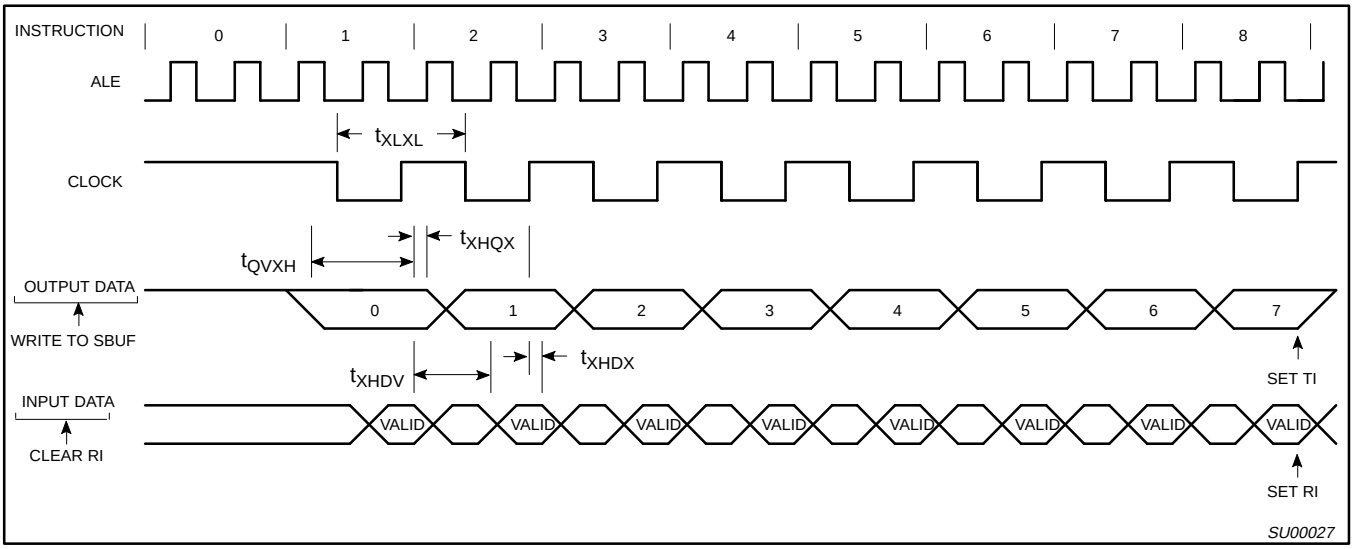


Figure 8. Shift Register Mode Timing

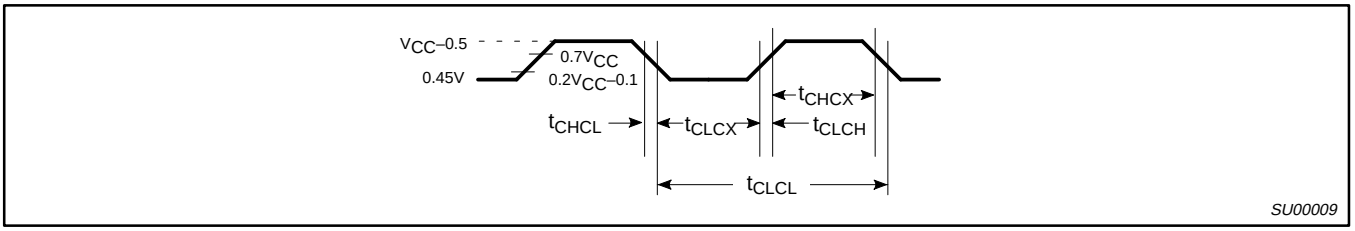
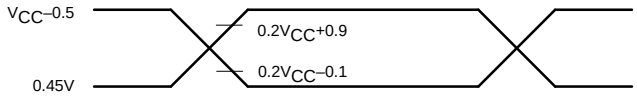


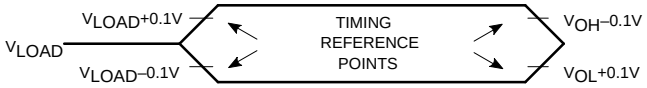
Figure 9. External Clock Drive



NOTE:
AC inputs during testing are driven at V_{CC} –0.5 for a logic '1' and 0.45V for a logic '0'.
Timing measurements are made at V_{IH} min for a logic '1' and V_{IL} max for a logic '0'.

SU00010

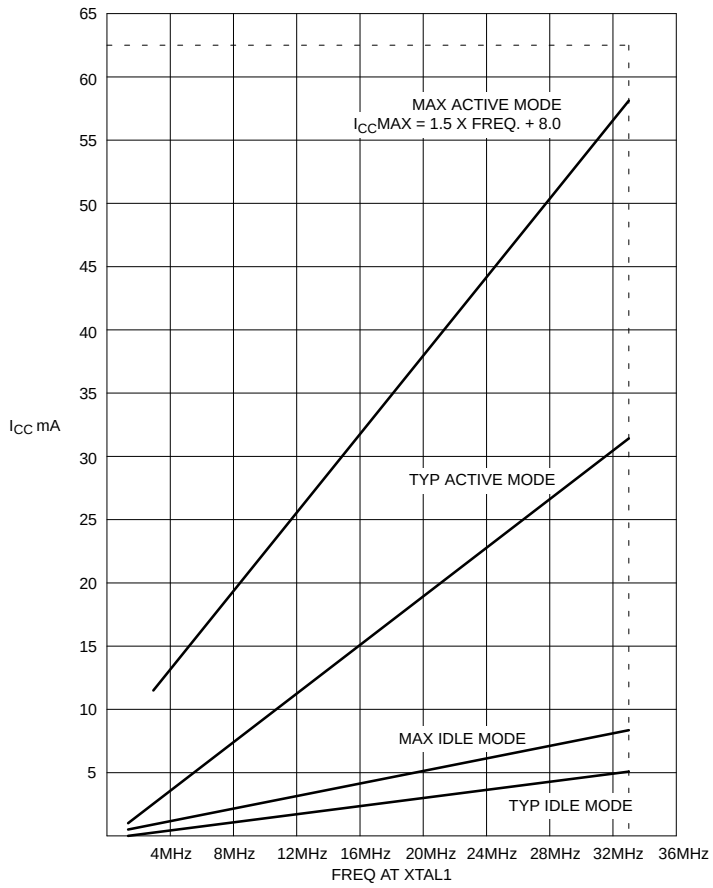
Figure 10. AC Testing Input/Output



NOTE:
For timing purposes, a port is no longer floating when a 100mV change from load voltage occurs, and begins to float when a 100mV change from the loaded V_{OH}/V_{OL} level occurs. $I_{OH}/I_{OL} \geq \pm 20$mA.

SU00011

Figure 11. Float Waveform



SU00070B

Figure 12. I_{CC} vs. FREQ
Valid only within frequency specifications of the device under test

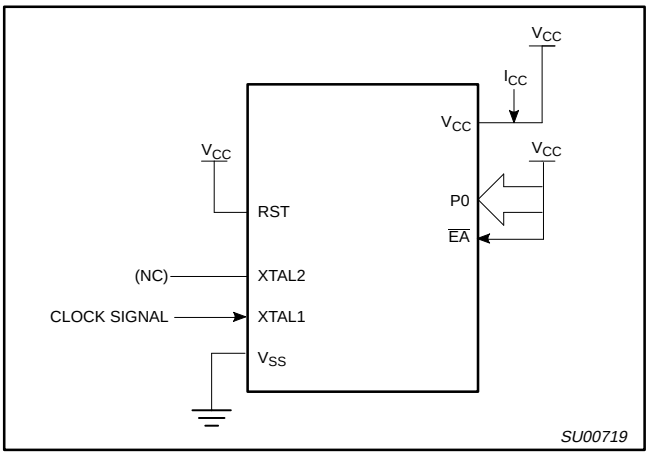


Figure 13. I_{CC} Test Condition, Active Mode
All other pins are disconnected

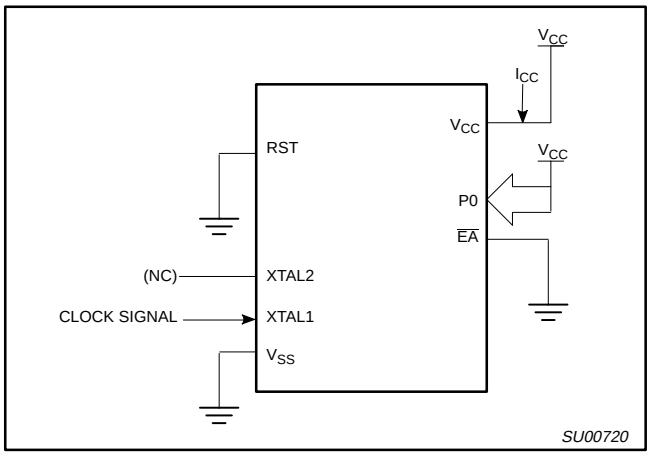


Figure 14. I_{CC} Test Condition, Idle Mode
All other pins are disconnected

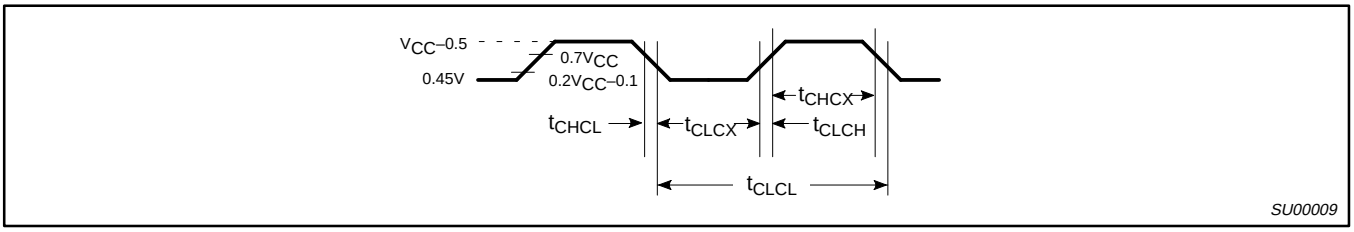


Figure 15. Clock Signal Waveform for I_{CC} Tests in Active and Idle Modes
$t_{CLCH} = t_{CHCL} = 5ns$

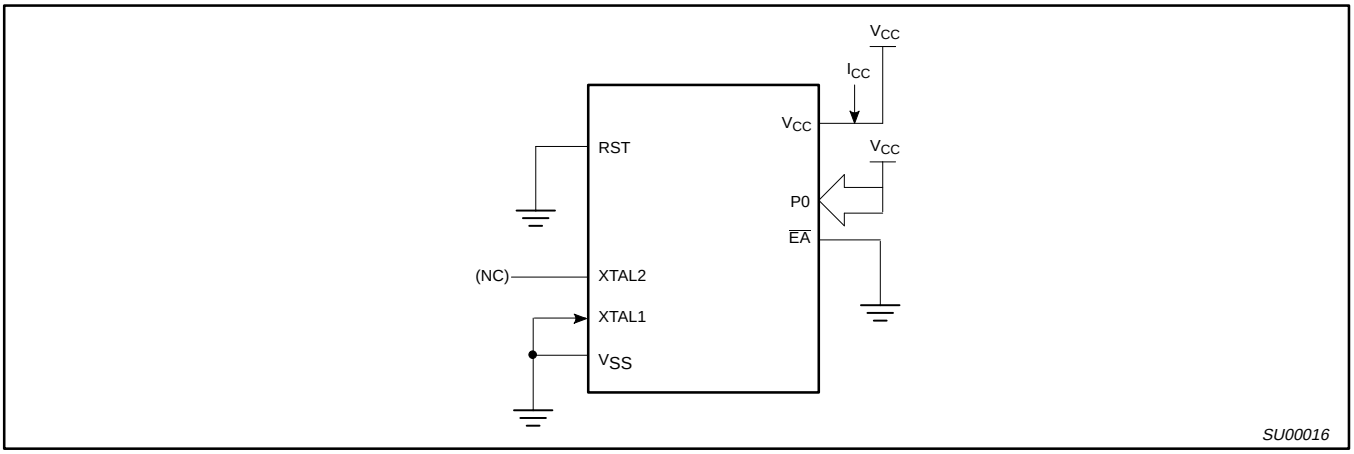


Figure 16. I_{CC} Test Condition, Power Down Mode
All other pins are disconnected. V_{CC} = 2V to 5.5V

EPROM CHARACTERISTICS

The 87C52 is programmed by using a modified Quick-Pulse Programming™ algorithm. It differs from older methods in the value used for V_{PP} (programming supply voltage) and in the width and number of the ALE/$\overline{PROG}$ pulses.

The 87C52 contains two signature bytes that can be read and used by an EPROM programming system to identify the device. The signature bytes identify the device as an 87C52 manufactured by Philips.

Table 6 shows the logic levels for reading the signature byte, and for programming the program memory, the encryption table, and the security bits. The circuit configuration and waveforms for quick-pulse programming are shown in Figures 17 and 18. Figure 19 shows the circuit configuration for normal program memory verification.

Quick-Pulse Programming

The setup for microcontroller quick-pulse programming is shown in Figure 17. Note that the 87C52 is running with a 4 to 6MHz oscillator. The reason the oscillator needs to be running is that the device is executing internal address and program data transfers.

The address of the EPROM location to be programmed is applied to ports 1 and 2, as shown in Figure 17. The code byte to be programmed into that location is applied to port 0. RST, $\overline{PSEN}$ and pins of ports 2 and 3 specified in Table 6 are held at the 'Program Code Data' levels indicated in Table 6. The ALE/$\overline{PROG}$ is pulsed low 25 times as shown in Figure 18.

To program the encryption table, repeat the 25 pulse programming sequence for addresses 0 through 1FH, using the 'Pgm Encryption Table' levels. Do not forget that after the encryption table is programmed, verification cycles will produce only encrypted data.

To program the security bits, repeat the 25 pulse programming sequence using the 'Pgm Security Bit' levels. After one security bit is programmed, further programming of the code memory and encryption table is disabled. However, the other security bit can still be programmed.

Note that the $\overline{EA}$/V_{PP} pin must not be allowed to go above the maximum specified V_{PP} level for any amount of time. Even a narrow glitch above that voltage can cause permanent damage to the device. The V_{PP} source should be well regulated and free of glitches and overshoot.

Program Verification

If security bit 2 has not been programmed, the on-chip program memory can be read out for program verification. The address of the program memory locations to be read is applied to ports 1 and 2 as shown in Figure 19. The other pins are held at the 'Verify Code Data' levels indicated in Table 6. The contents of the address location will be emitted on port 0. External pull-ups are required on port 0 for this operation.

If the encryption table has been programmed, the data presented at port 0 will be the exclusive NOR of the program byte with one of the encryption bytes. The user will have to know the encryption table contents in order to correctly decode the verification data. The encryption table itself cannot be read out.

Reading the Signature Bytes

The signature bytes are read by the same procedure as a normal verification of locations 030H and 031H, except that P3.6 and P3.7 need to be pulled to a logic low. The values are:
(030H) = 15H indicates manufactured by Philips
(031H) = 97H indicates 87C52

Program/Verify Algorithms

Any algorithm in agreement with the conditions listed in Table 6, and which satisfies the timing specifications, is suitable.

Erasure Characteristics

Erasure of the EPROM begins to occur when the chip is exposed to light with wavelengths shorter than approximately 4,000 angstroms. Since sunlight and fluorescent lighting have wavelengths in this range, exposure to these light sources over an extended time (about 1 week in sunlight, or 3 years in room level fluorescent lighting) could cause inadvertent erasure. **For this and secondary effects, it is recommended that an opaque label be placed over the window.** For elevated temperature or environments where solvents are being used, apply Kapton tape Fluorglas part number 2345–5, or equivalent.

The recommended erasure procedure is exposure to ultraviolet light (at 2537 angstroms) to an integrated dose of at least 15W-s/cm^2. Exposing the EPROM to an ultraviolet lamp of 12,000µW/cm^2 rating for 20 to 39 minutes, at a distance of about 1 inch, should be sufficient.

Erasure leaves the array in an all 1s state.

Table 6. EPROM Programming Modes

MODE	RST	$\overline{PSEN}$	ALE/$\overline{PROG}$	$\overline{EA}$/V_{PP}	P2.7	P2.6	P3.7	P3.6
Read signature	1	0	1	1	0	0	0	0
Program code data	1	0	0*	V_{PP}	1	0	1	1
Verify code data	1	0	1	1	0	0	1	1
Pgm encryption table	1	0	0*	V_{PP}	1	0	1	0
Pgm security bit 1	1	0	0*	V_{PP}	1	1	1	1
Pgm security bit 2	1	0	0*	V_{PP}	1	1	0	0

NOTES:
1. '0' = Valid low for that pin, '1' = valid high for that pin.
2. V_{PP} = 12.75V ±0.25V.
3. V_{CC} = 5V±10% during programming and verification.
4. *ALE/$\overline{PROG}$ receives 25 programming pulses while V_{PP} is held at 12.75V. Each programming pulse is low for 100µs (±10µs) and high for a minimum of 10µs.

™Trademark phrase of Intel Corporation.

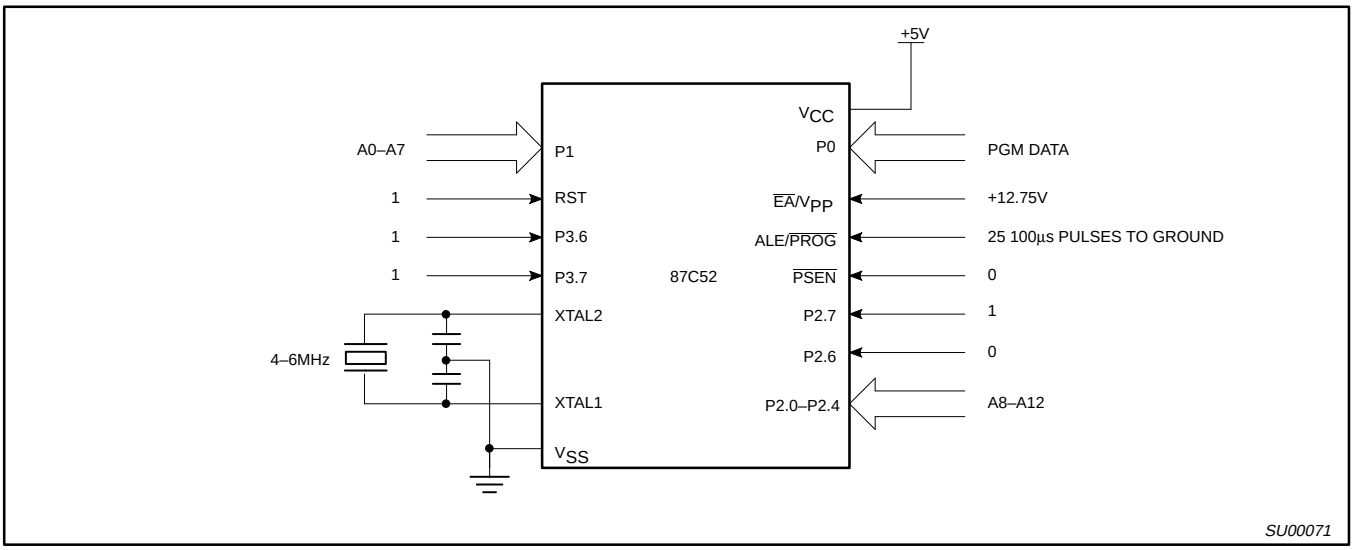


Figure 17. Programming Configuration

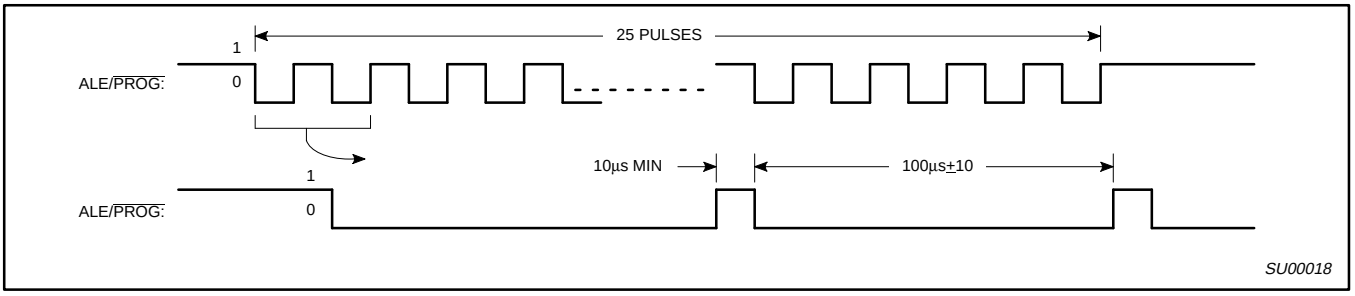


Figure 18. $\overline{\text{PROG}}$ Waveform

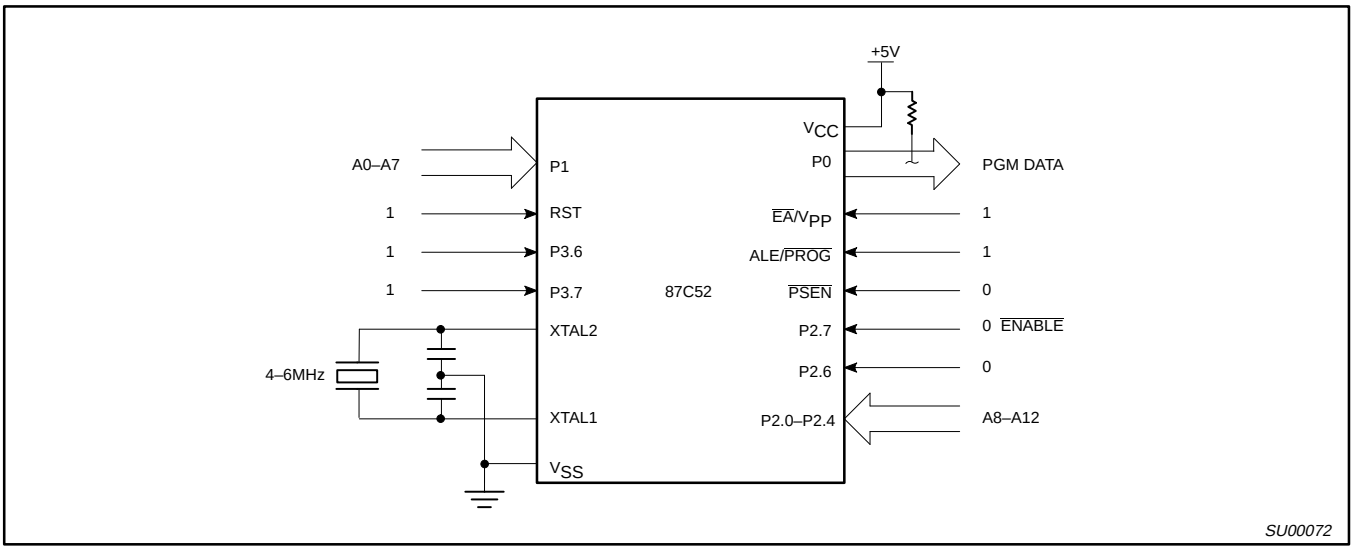
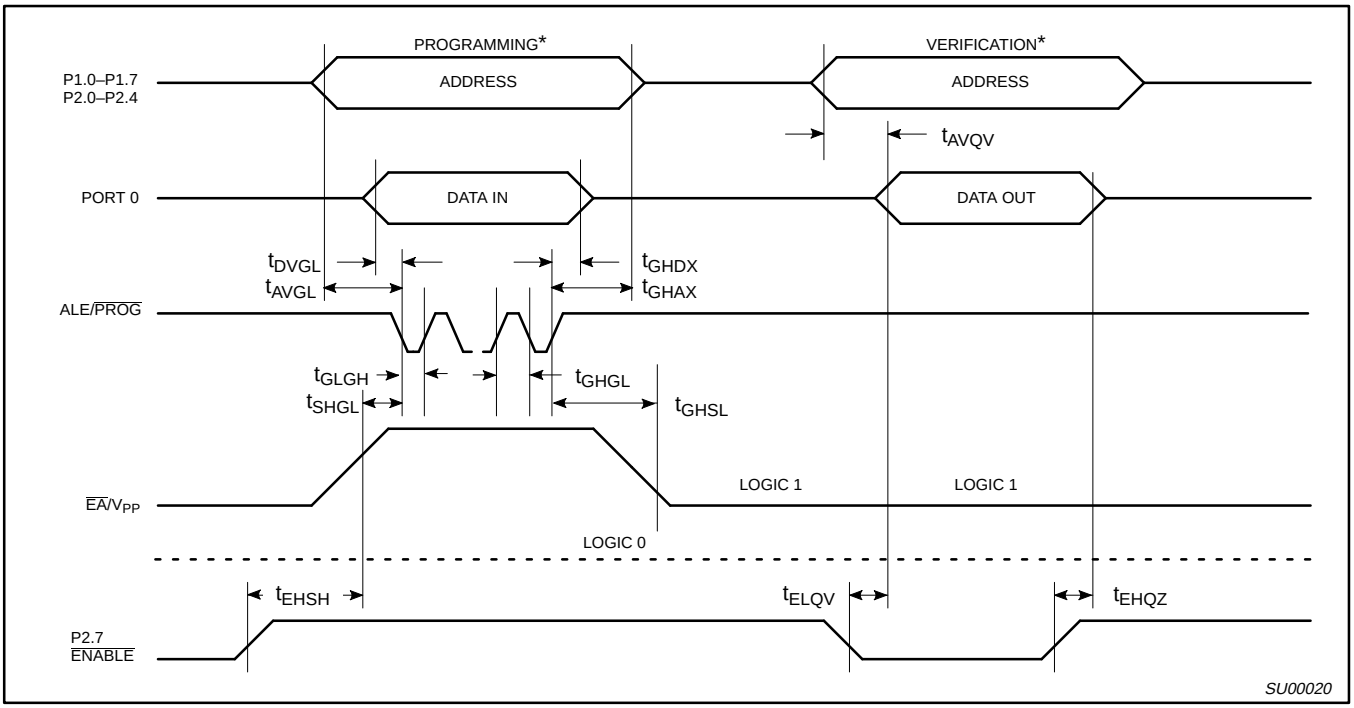


Figure 19. Program Verification

EPROM PROGRAMMING AND VERIFICATION CHARACTERISTICS

T_{amb} = 21°C to +27°C, V_{CC} = 5V±10%, V_{SS} = 0V (See Figure 20)

SYMBOL	PARAMETER	MIN	MAX	UNIT
V_{PP}	Programming supply voltage	12.5	13.0	V
I_{PP}	Programming supply current		50	mA
$1/t_{CLCL}$	Oscillator frequency	4	6	MHz
t_{AVGL}	Address setup to $\overline{PROG}$ low	$48t_{CLCL}$		
t_{GHAX}	Address hold after $\overline{PROG}$	$48t_{CLCL}$		
t_{DVGL}	Data setup to $\overline{PROG}$ low	$48t_{CLCL}$		
t_{GHDX}	Data hold after $\overline{PROG}$	$48t_{CLCL}$		
t_{EHSH}	P2.7 ($\overline{ENABLE}$) high to V_{PP}	$48t_{CLCL}$		
t_{SHGL}	V_{PP} setup to $\overline{PROG}$ low	10		µs
t_{GHSL}	V_{PP} hold after $\overline{PROG}$	10		µs
t_{GLGH}	$\overline{PROG}$ width	90	110	µs
t_{AVQV}	Address to data valid		$48t_{CLCL}$	
t_{ELQZ}	$\overline{ENABLE}$ low to data valid		$48t_{CLCL}$	
t_{EHQZ}	Data float after $\overline{ENABLE}$	0	$48t_{CLCL}$	
t_{GHGL}	$\overline{PROG}$ high to $\overline{PROG}$ low	10		µs

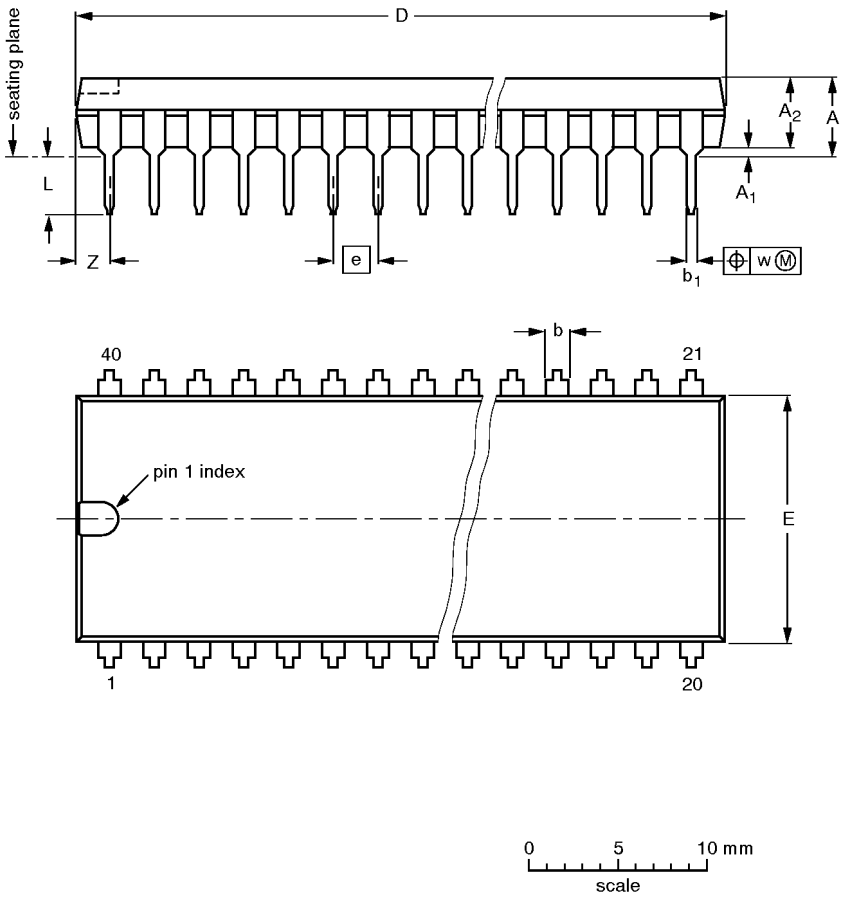


NOTE:

* FOR PROGRAMMING VERIFICATION SEE FIGURE 17.
FOR VERIFICATION CONDITIONS SEE FIGURE 19.

Figure 20. EPROM Programming and Verification

DIP40: plastic dual in-line package; 40 leads (600 mil) **SOT129-1**



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

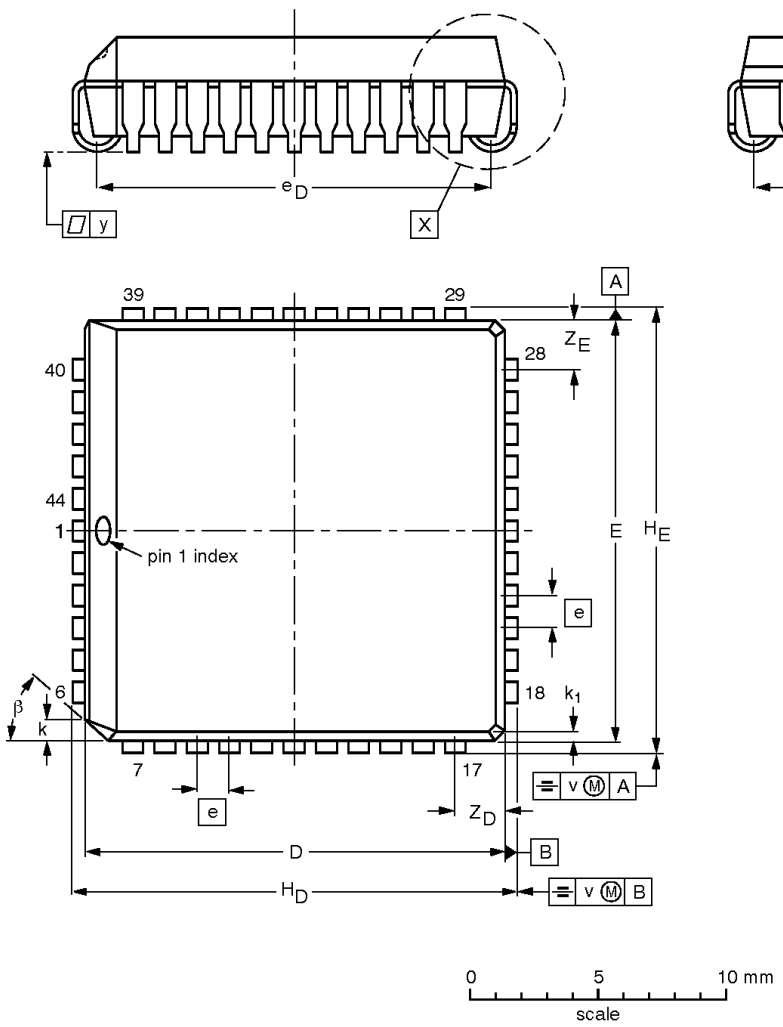
UNIT	A max.	A_1 min.	A_2 max.	b	b_1	c	D (1)	E (1)	e	e_1	L	M_E	M_H	w	Z (1) max.
mm	4.7	0.51	4.0	1.70 1.14	0.53 0.38	0.36 0.23	52.50 51.50	14.1 13.7	2.54	15.24	3.60 3.05	15.80 15.24	17.42 15.90	0.254	2.25
inches	0.19	0.020	0.16	0.067 0.045	0.021 0.015	0.014 0.009	2.067 2.028	0.56 0.54	0.10	0.60	0.14 0.12	0.62 0.60	0.69 0.63	0.01	0.089

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT129-1	051G08	MO-015AJ				~~92-11-17~~ 95-01-14

PLCC44: plastic leaded chip carrier; 44 leads **SOT187-2**



DIMENSIONS (millimetre dimensions are derived from the original inch dimensions)

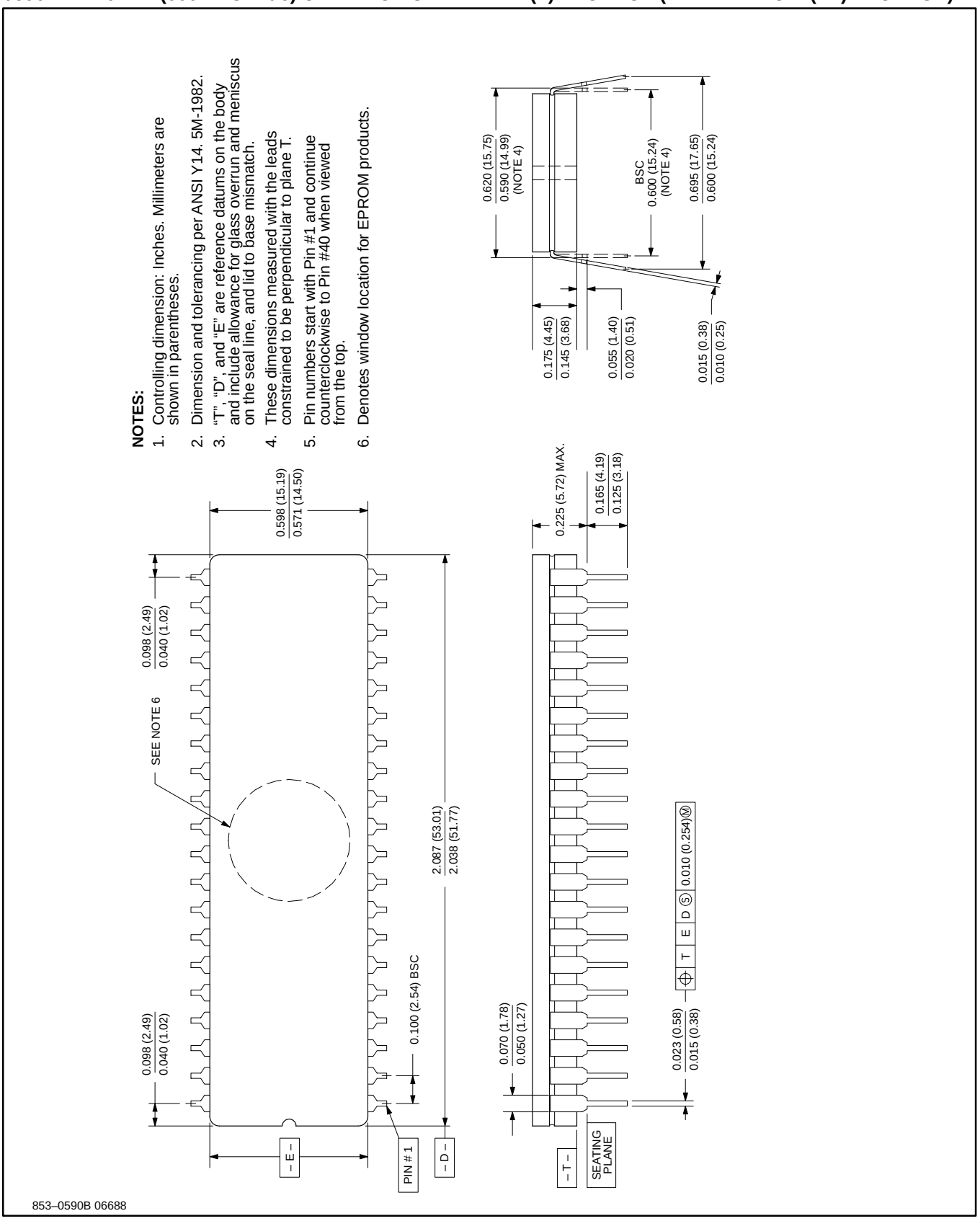
UNIT	A	A_1 min.	A_3	A_4 max.	b_p	b_1	$D^{(1)}$	$E^{(1)}$	e	e_D	e_E	H_D	H_E	k	k_1 max.	L_p	v	w	y	$Z_D^{(1)}$ max.	$Z_E^{(1)}$ max.	β
mm	4.57 4.19	0.51	0.25	3.05	0.53 0.33	0.81 0.66	16.66 16.51	16.66 16.51	1.27	16.00 14.99	16.00 14.99	17.65 17.40	17.65 17.40	1.22 1.07	0.51	1.44 1.02	0.18	0.18	0.10	2.16	2.16	45°
inches	0.180 0.165	0.020	0.01	0.12	0.021 0.013	0.032 0.026	0.656 0.650	0.656 0.650	0.05	0.630 0.590	0.630 0.590	0.695 0.685	0.695 0.685	0.048 0.042	0.020	0.057 0.040	0.007	0.007	0.004	0.085	0.085	

Note

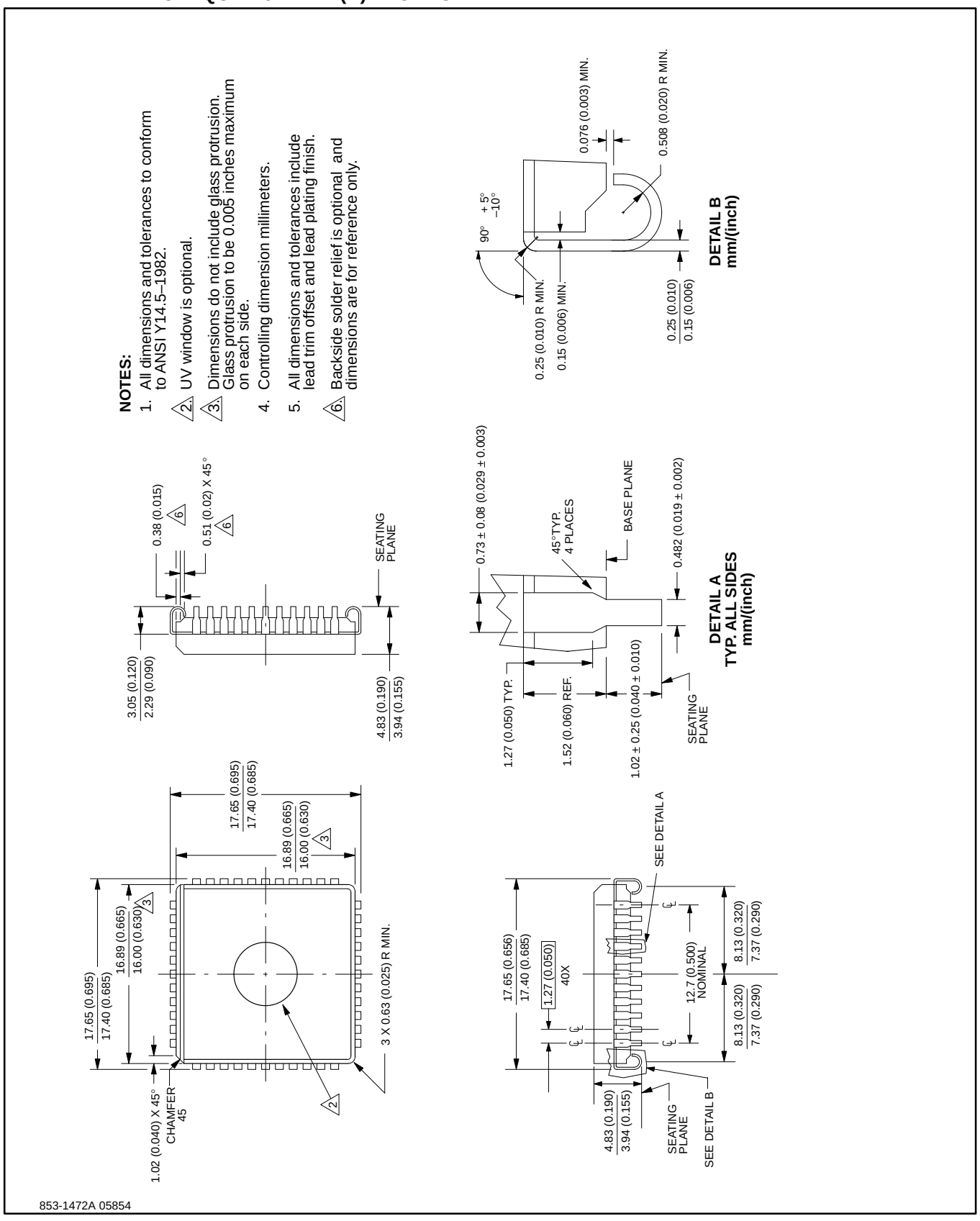
1. Plastic or metal protrusions of 0.01 inches maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT187-2	112E10	MO-047AC				~~92-11-17~~ 95-02-25

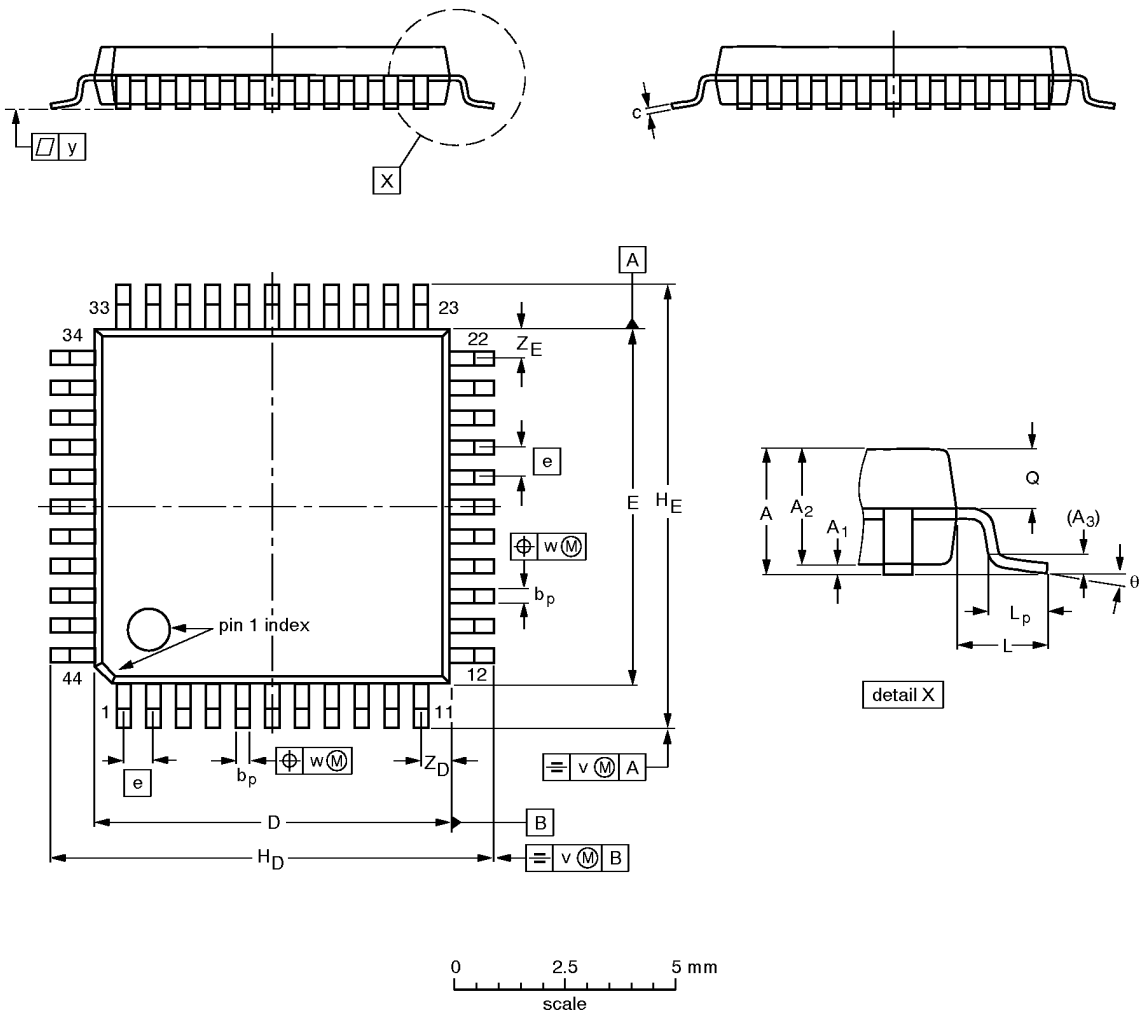
0590B 40-PIN (600 mils wide) CERAMIC DUAL IN-LINE (F) PACKAGE (WITH WINDOW (FA) PACKAGE)



1472A 44-PIN CERQUAD J-BEND (K) PACKAGE



QFP44: plastic quad flat package; 44 leads (lead length 1.3 mm); body 10 x 10 x 1.75 mm SOT307-2



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(1)}$	e	H_D	H_E	L	L_p	Q	v	w	y	$Z_D^{(1)}$	$Z_E^{(1)}$	θ
mm	2.10	0.25 0.05	1.85 1.65	0.25	0.40 0.20	0.25 0.14	10.1 9.9	10.1 9.9	0.8	12.9 12.3	12.9 12.3	1.3	0.95 0.55	0.85 0.75	0.15	0.15	0.1	1.2 0.8	1.2 0.8	10° 0°

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT307-2						~~92-11-17~~ 95-02-04

NOTES

DEFINITIONS

Data Sheet Identification	Product Status	Definition
Objective Specification	**Formative or in Design**	This data sheet contains the design target or goal specifications for product development. Specifications may change in any manner without notice.
Preliminary Specification	**Preproduction Product**	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.
Product Specification	**Full Production**	This data sheet contains Final Specifications. Philips Semiconductors reserves the right to make changes at any time without notice, in order to improve design and supply the best possible product.

Philips Semiconductors
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P.O. Box 3409
Sunnyvale, California 94088–3409
Telephone 800-234-7381

DATA SHEET

80C52/80C54/80C58
CMOS single-chip 8-bit microcontrollers

Product specification

1996 Aug 16

IC20 Data Handbook

Philips
Semiconductors

PHILIPS

DESCRIPTION

The 80C52/80C54/80C58 Single-Chip 8-Bit Microcontroller is manufactured in an advanced CMOS process and is a derivative of the 80C51 microcontroller family. The 80C52/80C54/80C58 has the same instruction set as the 80C51.

This device provides architectural enhancements that make it applicable in a variety of applications for general control systems. The 80C52 contains 8k × 8 ROM memory, the 80C54 contains 16k × 8 ROM memory, and 80C58 contains 32k × 8 ROM memory, a volatile 256 × 8 read/write data memory, four 8-bit I/O ports, three 16-bit timer/event counters, a multi-source, four-priority-level, nested interrupt structure, an enhanced UART and on-chip oscillator and timing circuits. For systems that require extra capability, the 80C52/54/58 can be expanded using standard TTL compatible memories and logic.

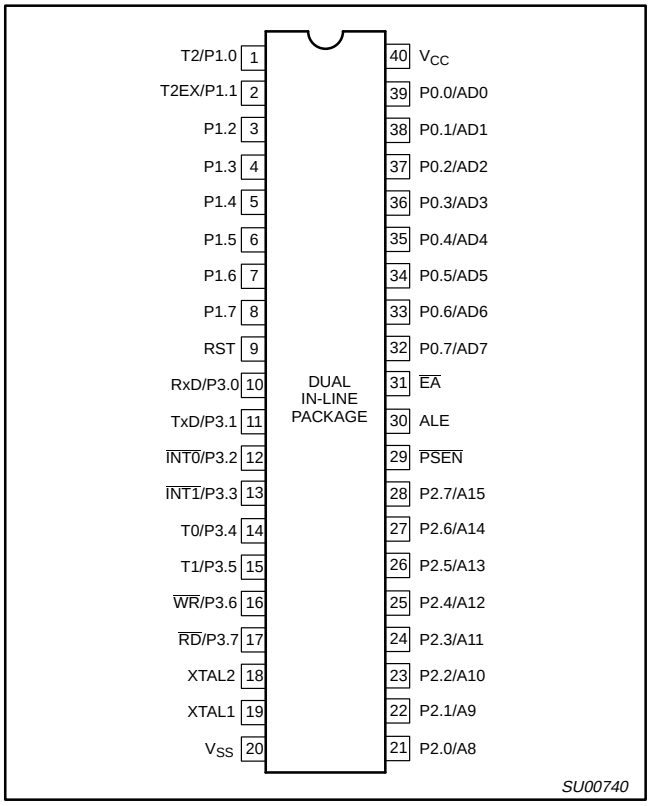
Its added features make it an even more powerful microcontroller for applications that require pulse width modulation, high-speed I/O and up/down counting capabilities such as motor control. It also has a more versatile serial channel that facilitates multiprocessor communications.

See 87C52/80C32 and 87C54/87C58 data sheets for EPROM and ROMless devices.

FEATURES

- 80C51 central processing unit
- Full static operation
- 8k × 8 ROM: 80C52;
  16k × 8 ROM: 80C54;
  32k × 8 ROM: 80C58;
  all capable of addressing external memory to 64k bytes
  - Two level program security system
  - 64 byte encryption array
- 256 × 8 RAM, expandable externally to 64k bytes
- Speed range up to 33MHz
- Operating voltage 5V ±10%
- Three 16-bit timer/counters
  - T2 is an up/down counter
- 6 interrupt sources
- 4 level priority
- Four 8-bit I/O ports
- Full-duplex enhanced UART
  - Framing error detection
  - Automatic address recognition
- Power control modes
  - Idle mode
  - Power-down mode
- Once (On Circuit Emulation) Mode
- Five package styles
- Programmable clock out
- Low EMI (Inhibit ALE)
- Second DPTR register
- Asynchronous port reset

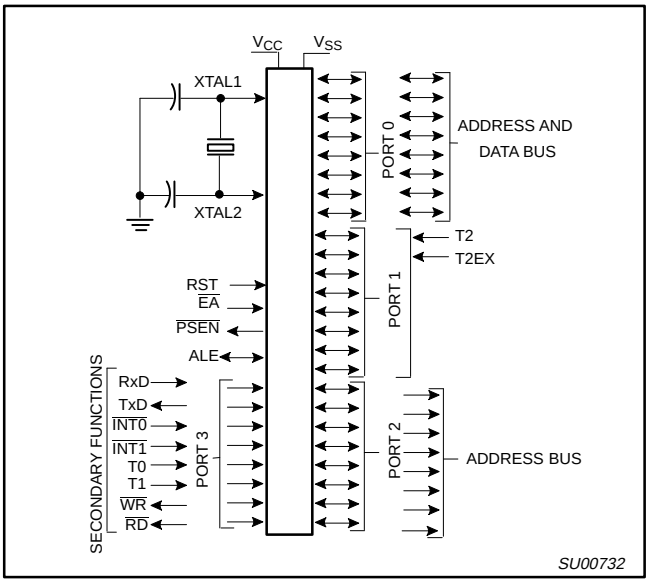
PIN CONFIGURATIONS



ORDERING INFORMATION

ROM 8k × 8	ROM 16k × 8	ROM 32k × 8	TEMPERATURE RANGE °C AND PACKAGE	FREQ MHz	DRAWING NUMBER
P80C52EBPN	P80C54EBPN	P80C58EBPN	0 to +70, Plastic Dual In-line Package	16	SOT129-1
P80C52EBAA	P80C54EBAA	P80C58EBAA	0 to +70, Plastic Leaded Chip Carrier	16	SOT187-2
P80C52EBBB	P80C54EBBB	P80C58EBBB	0 to +70, Plastic Quad Flat Pack	16	SOT307-2
P80C52EFPN	P80C54EFPN	P80C58EFPN	–40 to +85, Plastic Dual In-line Package	16	SOT129-1
P80C52EFAA	P80C54EFAA	P80C58EFAA	–40 to +85, Plastic Leaded Chip Carrier	16	SOT187-2
P80C52EFBB	P80C54EFBB	P80C58EFBB	–40 to +85, Plastic Quad Flat Pack	16	SOT307-2
P80C52IBP N	P80C54IBP N	P80C58IBP N	0 to +70, Plastic Dual In-line Package	24	SOT129-1
P80C52IBA A	P80C54IBA A	P80C58IBA A	0 to +70, Plastic Leaded Chip Carrier	24	SOT187-2
P80C52IBB B	P80C54IBB B	P80C58IBB B	0 to +70, Plastic Quad Flat Pack	24	SOT307-2
P80C52IFP N	P80C54IFP N	P80C58IFP N	–40 to +85, Plastic Dual In-line Package	24	SOT129-1
P80C52IFA A	P80C54IFA A	P80C58IFA A	–40 to +85, Plastic Leaded Chip Carrier	24	SOT187-2
P80C52IFB B	P80C54IFB B	P80C58IFB B	–40 to +85, Plastic Quad Flat Pack	24	SOT307-2
P80C52NBAA	P80C54NBAA	P80C58NBAA	0 to +70, Plastic Leaded Chip Carrier	33	SOT187-2
P80C52NBPN	P80C54NBPN	P80C58NBPN	0 to +70, Plastic Dual In-line Package	33	SOT129-1
P80C52NBBB	P80C54NBBB	P80C58NBBB	0 to +70, Plastic Quad Flat Pack	33	SOT307-2
P80C52NFAA	P80C54NFAA	P80C58NFAA	–40 to +85, Plastic Leaded Chip Carrier	33	SOT187-2
P80C52NFPN	P80C54NFPN	P80C58NFPN	–40 to +85, Plastic Dual In-line Package	33	SOT129-1
P80C52NFBB	P80C54NFBB	P80C58NFBB	–40 to +85, Plastic Quad Flat Pack	33	SOT307-2

LOGIC SYMBOL



BLOCK DIAGRAM

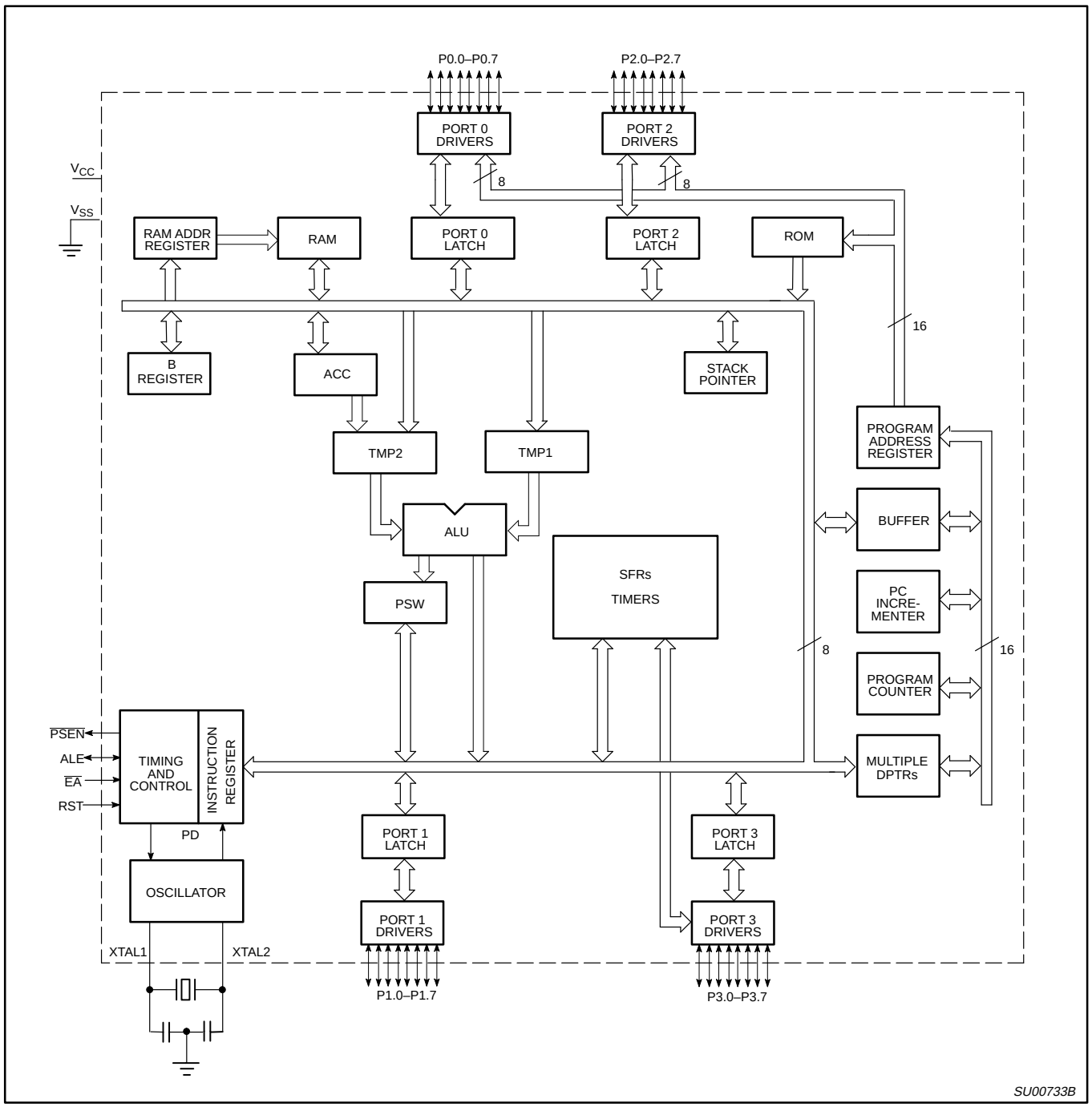
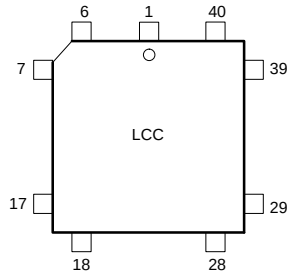


Table 1. 80C52/80C54/80C58 Special Function Registers

SYMBOL	DESCRIPTION	DIRECT ADDRESS	BIT ADDRESS, SYMBOL, OR ALTERNATIVE PORT FUNCTION MSB							LSB	RESET VALUE
ACC*	Accumulator	E0H	E7	E6	E5	E4	E3	E2	E1	E0	00H
AUXR#	Auxiliary	8EH	–	–	–	–	–	–	–	AO	xxxxxxx0B
AUXR1#	Auxiliary 1	A2H	–	–	–	–	–	–	–	DPS	xxxxxxx0B
B*	B register	F0H	F7	F6	F5	F4	F3	F2	F1	F0	00H
DPTR:	Data Pointer (2 bytes)										
DPH	Data Pointer High	83H									00H
DPL	Data Pointer Low	82H									00H
			AF	AE	AD	AC	AB	AA	A9	A8	
IE*	Interrupt Enable	A8H	EA	EC	ET2	ES	ET1	EX1	ET0	EX0	00H
			BF	BE	BD	BC	BB	BA	B9	B8	
IP*	Interrupt Priority	B8H	–	–	PT2	PS	PT1	PX1	PT0	PX0	x0000000B
			B7	B6	B5	B4	B3	B2	B1	B0	
IPH#	Interrupt Priority High	B7H	–	–	PT2H	PSH	PT1H	PX1H	PT0H	PX0H	x0000000B
			87	86	85	84	83	82	81	80	
P0*	Port 0	80H	AD7	AD6	AD5	AD4	AD3	AD2	AD1	AD0	FFH
			97	96	95	94	93	92	91	90	
P1*	Port 1	90H	–	–	–	–	–	–	T2EX	T2	FFH
			A7	A6	A5	A4	A3	A2	A1	A0	
P2*	Port 2	A0H	AD15	AD14	AD13	AD12	AD11	AD10	AD9	AD8	FFH
			B7	B6	B5	B4	B3	B2	B1	B0	
P3*	Port 3	B0H	$\overline{RD}$	$\overline{WR}$	T1	T0	$\overline{INT1}$	$\overline{INT0}$	TxD	RxD	FFH
PCON#[1]	Power Control	87H	SMOD1	SMOD0	–	POF[2]	GF1	GF0	PD	IDL	00xx0000B
			D7	D6	D5	D4	D3	D2	D1	D0	
PSW*	Program Status Word	D0H	CY	AC	F0	RS1	RS0	OV	–	P	00H
RACAP2H#	Timer 2 Capture High	CBH									00H
RACAP2L#	Timer 2 Capture Low	CAH									00H
SADDR#	Slave Address	A9H									00H
SADEN#	Slave Address Mask	B9H									00H
SBUF	Serial Data Buffer	99H									xxxxxxxxB
			9F	9E	9D	9C	9B	9A	99	98	
SCON*	Serial Control	98H	SM0/FE	SM1	SM2	REN	TB8	RB8	TI	RI	00H
SP	Stack Pointer	81H									07H
			8F	8E	8D	8C	8B	8A	89	88	
TCON*	Timer Control	88H	TF1	TR1	TF0	TR0	IE1	IT1	IE0	IT0	00H
			CF	CE	CD	CC	CB	CA	C9	C8	
T2CON*	Timer 2 Control	C8H	TF2	EXF2	RCLK	TCLK	EXEN2	TR2	C/$\overline{T2}$	CP/$\overline{RL2}$	00H
T2MOD#	Timer 2 Mode Control	C9H	–	–	–	–	–	–	T2OE	DCEN	xxxxxx00B
TH0	Timer High 0	8CH									00H
TH1	Timer High 1	8DH									00H
TH2#	Timer High 2	CDH									00H
TL0	Timer Low 0	8AH									00H
TL1	Timer Low 1	8BH									00H
TL2#	Timer Low 2	CCH									00H
TMOD	Timer Mode	89H	GATE	C/$\overline{T}$	M1	M0	GATE	C/$\overline{T}$	M1	M0	00H

* SFRs are bit addressable.
\# SFRs are modified from or added to the 80C51 SFRs.
– Reserved bits.
1. Reset value depends on reset source.
2. Bit will not be affected by Reset. POF is not present in 80C52.

PLASTIC LEADED CHIP CARRIER PIN FUNCTIONS



Pin	Function	Pin	Function	Pin	Function
1	NC*	16	P3.4/T0	31	P2.7/A15
2	P1.0/T2	17	P3.5/T1	32	$\overline{PSEN}$
3	P1.1/T2EX	18	P3.6/$\overline{WR}$	33	ALE
4	P1.2	19	P3.7/$\overline{RD}$	34	NC*
5	P1.3	20	XTAL2	35	$\overline{EA}$
6	P1.4	21	XTAL1	36	P0.7/AD7
7	P1.5	22	V_{SS}	37	P0.6/AD6
8	P1.6	23	NC*	38	P0.5/AD5
9	P1.7	24	P2.0/A8	39	P0.4/AD4
10	RST	25	P2.1/A9	40	P0.3/AD3
11	P3.0/RxD	26	P2.2/A10	41	P0.2/AD2
12	NC*	27	P2.3/A11	42	P0.1/AD1
13	P3.1/TxD	28	P2.4/A12	43	P0.0/AD0
14	P3.2/$\overline{INT0}$	29	P2.5/A13	44	V_{CC}
15	P3.3/$\overline{INT1}$	30	P2.6/A14		

* DO NOT CONNECT

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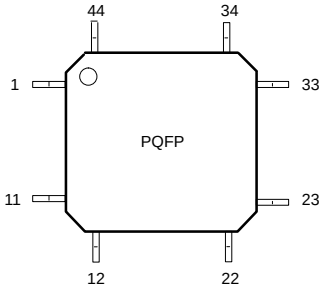
PLASTIC QUAD FLAT PACK PIN FUNCTIONS



Pin	Function	Pin	Function	Pin	Function
1	P1.5	16	V_{SS}	31	P0.6/AD6
2	P1.6	17	NC*	32	P0.5/AD5
3	P1.7	18	P2.0/A8	33	P0.4/AD4
4	RST	19	P2.1/A9	34	P0.3/AD3
5	P3.0/RxD	20	P2.2/A10	35	P0.2/AD2
6	NC*	21	P2.3/A11	36	P0.1/AD1
7	P3.1/TxD	22	P2.4/A12	37	P0.0/AD0
8	P3.2/$\overline{INT0}$	23	P2.5/A13	38	V_{CC}
9	P3.3/$\overline{INT1}$	24	P2.6/A14	39	NC*
10	P3.4/T0	25	P2.7/A15	40	P1.0/T2
11	P3.5/T1	26	$\overline{PSEN}$	41	P1.1/T2EX
12	P3.6/$\overline{WR}$	27	ALE	42	P1.2
13	P3.7/$\overline{RD}$	28	NC*	43	P1.3
14	XTAL2	29	$\overline{EA}$	44	P1.4
15	XTAL1	30	P0.7/AD7		

* DO NOT CONNECT

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PIN DESCRIPTIONS

MNEMONIC	PIN NUMBER DIP	PIN NUMBER LCC	PIN NUMBER QFP	TYPE	NAME AND FUNCTION
V_{SS}	20	22	16	I	**Ground:** 0V reference.
V_{CC}	40	44	38	I	**Power Supply:** This is the power supply voltage for normal, idle, and power-down operation.
P0.0–0.7	39–32	43–36	37–30	I/O	**Port 0:** Port 0 is an open-drain, bidirectional I/O port. Port 0 pins that have 1s written to them float and can be used as high-impedance inputs. Port 0 is also the multiplexed low-order address and data bus during accesses to external program and data memory. In this application, it uses strong internal pull-ups when emitting 1s. Port 0 also outputs the code bytes during program verification. External pull-ups are required during program verification.
P1.0–P1.7	1–8	2–9	40–44, 1–3	I/O	**Port 1:** Port 1 is an 8-bit bidirectional I/O port with internal pull-ups. Port 1 pins that have 1s written to them are pulled high by the internal pull-ups and can be used as inputs. As inputs, port 1 pins that are externally pulled low will source current because of the internal pull-ups. (See DC Electrical Characteristics: I_{IL}). Port 1 also receives the low-order address byte during program memory verification. Alternate functions include:
	1	2	40	I/O	**T2 (P1.0):** Timer/Counter 2 external count input/Clockout
	2	3	41	I	**T2EX (P1.1):** Timer/Counter 2 Reload/Capture/Direction Control
	3	4	42	I	
	4	5	43	I/O	
	5	6	44	I/O	
	6	7	1	I/O	
	7	8	2	I/O	
	8	9	3	I/O	
P2.0–P2.7	21–28	24–31	18–25	I/O	**Port 2:** Port 2 is an 8-bit bidirectional I/O port with internal pull-ups. Port 2 pins that have 1s written to them are pulled high by the internal pull-ups and can be used as inputs. As inputs, port 2 pins that are externally being pulled low will source current because of the internal pull-ups. (See DC Electrical Characteristics: I_{IL}). Port 2 emits the high-order address byte during fetches from external program memory and during accesses to external data memory that use 16-bit addresses (MOVX @DPTR). In this application, it uses strong internal pull-ups when emitting 1s. During accesses to external data memory that use 8-bit addresses (MOV @Ri), port 2 emits the contents of the P2 special function register.

PIN DESCRIPTIONS (Continued)

MNEMONIC	PIN NUMBER DIP	LCC	QFP	TYPE	NAME AND FUNCTION
P3.0–P3.7	10–17	11, 13–19	5, 7–13	I/O	**Port 3:** Port 3 is an 8-bit bidirectional I/O port with internal pull-ups. Port 3 pins that have 1s written to them are pulled high by the internal pull-ups and can be used as inputs. As inputs, port 3 pins that are externally being pulled low will source current because of the pull-ups. (See DC Electrical Characteristics: I_{IL}). Port 3 also serves the special features of the 80C51 family, as listed below:
	10	11	5	I	**RxD (P3.0):** Serial input port
	11	13	7	O	**TxD (P3.1):** Serial output port
	12	14	8	I	**$\overline{\text{INT0}}$ (P3.2):** External interrupt
	13	15	9	I	**$\overline{\text{INT1}}$ (P3.3):** External interrupt
	14	16	10	I	**T0 (P3.4):** Timer 0 external input
	15	17	11	I	**T1 (P3.5):** Timer 1 external input
	16	18	12	O	**$\overline{\text{WR}}$ (P3.6):** External data memory write strobe
	17	19	13	O	**$\overline{\text{RD}}$ (P3.7):** External data memory read strobe
RST	9	10	4	I	**Reset:** A high on this pin for two machine cycles while the oscillator is running, resets the device. An internal diffused resistor to V_{SS} permits a power-on reset using only an external capacitor to V_{CC}.
ALE	30	33	27	O	**Address Latch Enable:** Output pulse for latching the low byte of the address during an access to external memory. In normal operation, ALE is emitted at a constant rate of 1/6 the oscillator frequency, and can be used for external timing or clocking. Note that one ALE pulse is skipped during each access to external data memory. ALE can be disabled by setting SFR auxiliary.0. With this bit set, ALE will be active only during a MOVX instruction.
$\overline{\text{PSEN}}$	29	32	26	O	**Program Store Enable:** The read strobe to external program memory. When the 80C52/80C54/80C58 is executing code from the external program memory, $\overline{\text{PSEN}}$ is activated twice each machine cycle, except that two $\overline{\text{PSEN}}$ activations are skipped during each access to external data memory. $\overline{\text{PSEN}}$ is not activated during fetches from internal program memory.
$\overline{\text{EA}}$	31	35	29	I	**External Access Enable:** $\overline{\text{EA}}$ must be externally held low to enable the device to fetch code from external program memory locations 0000H and 7FFFH. If $\overline{\text{EA}}$ is held high, the device executes from internal program memory unless the program counter contains an address greater than 7FFFH. If security bit 1 is programmed, $\overline{\text{EA}}$ will be internally latched on Reset.
XTAL1	19	21	15	I	**Crystal 1:** Input to the inverting oscillator amplifier and input to the internal clock generator circuits.
XTAL2	18	20	14	O	**Crystal 2:** Output from the inverting oscillator amplifier.

NOTE:
To avoid “latch-up” effect at power-on, the voltage on any pin at any time must not be higher than V_{CC} + 0.5V or V_{SS} – 0.5V, respectively.

TIMER 2 OPERATION

Timer 2

Timer 2 is a 16-bit Timer/Counter which can operate as either an event timer or an event counter, as selected by C/T2* in the special function register T2CON (see Figure 1). Timer 2 has three operating modes:Capture, Auto-reload (up or down counting) ,and Baud Rate Generator, which are selected by bits in the T2CON as shown in Table 2.

Capture Mode

In the capture mode there are two options which are selected by bit EXEN2 in T2CON. If EXEN2=0, then timer 2 is a 16-bit timer or counter (as selected by C/T2* in T2CON) which, upon overflowing sets bit TF2, the timer 2 overflow bit. This bit can be used to generate an interrupt (by enabling the Timer 2 interrupt bit in the IE register/SFR table). If EXEN2= 1, Timer 2 operates as described above, but with the added feature that a 1- to -0 transition at external input T2EX causes the current value in the Timer 2 registers, TL2 and TH2, to be captured into registers RCAP2L and RCAP2H, respectively. In addition, the transition at T2EX causes bit EXF2 in T2CON to be set, and EXF2 like TF2 can generate an interrupt (which vectors to the same location as Timer 2 overflow interrupt. The Timer 2 interrupt service routine can interrogate TF2 and EXF2 to determine which event caused the interrupt). The capture mode is illustrated in Figure 2 (There is no reload value for TL2 and TH2 in this mode. Even when a capture event occurs from T2EX, the counter keeps on counting T2EX pin transitions or osc/12 pulses.).

Auto-Reload Mode (Up or Down Counter)

In the 16-bit auto-reload mode, Timer 2 can be configured (as either a timer or counter (C/T2* in T2CON)) then programmed to count up or down. The counting direction is determined by bit DCEN(Down Counter Enable) which is located in the T2MOD register (see Figure 3). When reset is applied the DCEN=0 which means Timer 2 will default to counting up. If DCEN bit is set, Timer 2 can count up or down depending on the value of the T2EX pin.

Figure 4 shows Timer 2 which will count up automatically since DCEN=0. In this mode there are two options selected by bit EXEN2 in T2CON register. If EXEN2=0, then Timer 2 counts up to 0FFFFH and sets the TF2 (Overflow Flag) bit upon overflow. This causes the Timer 2 registers to be reloaded with the 16-bit value in RCAP2L and RCAP2H.

The values in RCAP2L and RCAP2H are preset by software means. If EXEN2=1, then a 16-bit reload can be triggered either by an overflow or by a 1-to-0 transition at input T2EX. This transition also sets the EXF2 bit. The Timer 2 interrupt, if enabled, can be generated when either TF2 or EXF2 are 1.

In Figure 5 DCEN=1 which enables Timer 2 to count up or down. This mode allows pin T2EX to control the direction of count. When a logic 1 is applied at pin T2EX Timer 2 will count up. Timer 2 will overflow at 0FFFFH and set the TF2 flag, which can then generate an interrupt, if the interrupt is enabled. This timer overflow also causes the 16–bit value in RCAP2L and RCAP2H to be reloaded into the timer registers TL2 and TH2.

When a logic 0 is applied at pin T2EX this causes Timer 2 to count down. The timer will underflow when TL2 and TH2 become equal to the value stored in RCAP2L and RCAP2H. Timer 2 underflow sets the TF2 flag and causes 0FFFFH to be reloaded into the timer registers TL2 and TH2.

The external flag EXF2 toggles when Timer 2 underflows or overflows. This EXF2 bit can be used as a 17th bit of resolution if needed. The EXF2 flag does not generate an interrupt in this mode of operation.

(MSB) (LSB)

TF2	EXF2	RCLK	TCLK	EXEN2	TR2	C/$\overline{T2}$	CP/$\overline{RL2}$

Symbol	Position	Name and Significance
TF2	T2CON.7	Timer 2 overflow flag set by a Timer 2 overflow and must be cleared by software. TF2 will not be set when either RCLK or TCLK = 1.
EXF2	T2CON.6	Timer 2 external flag set when either a capture or reload is caused by a negative transition on T2EX and EXEN2 = 1. When Timer 2 interrupt is enabled, EXF2 = 1 will cause the CPU to vector to the Timer 2 interrupt routine. EXF2 must be cleared by software. EXF2 does not cause an interrupt in up/down counter mode (DCEN = 1).
RCLK	T2CON.5	Receive clock flag. When set, causes the serial port to use Timer 2 overflow pulses for its receive clock in modes 1 and 3. RCLK = 0 causes Timer 1 overflow to be used for the receive clock.
TCLK	T2CON.4	Transmit clock flag. When set, causes the serial port to use Timer 2 overflow pulses for its transmit clock in modes 1 and 3. TCLK = 0 causes Timer 1 overflows to be used for the transmit clock.
EXEN2	T2CON.3	Timer 2 external enable flag. When set, allows a capture or reload to occur as a result of a negative transition on T2EX if Timer 2 is not being used to clock the serial port. EXEN2 = 0 causes Timer 2 to ignore events at T2EX.
TR2	T2CON.2	Start/stop control for Timer 2. A logic 1 starts the timer.
C/$\overline{T2}$	T2CON.1	Timer or counter select. (Timer 2) 0 = Internal timer (OSC/12) 1 = External event counter (falling edge triggered).
CP/$\overline{RL2}$	T2CON.0	Capture/Reload flag. When set, captures will occur on negative transitions at T2EX if EXEN2 = 1. When cleared, auto-reloads will occur either with Timer 2 overflows or negative transitions at T2EX when EXEN2 = 1. When either RCLK = 1 or TCLK = 1, this bit is ignored and the timer is forced to auto-reload on Timer 2 overflow.

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Figure 1. Timer/Counter 2 (T2CON) Control Register

Table 2. Timer 2 Operating Modes

RCLK + TCLK	CP/$\overline{RL2}$	TR2	MODE
0	0	1	16-bit Auto-reload
0	1	1	16-bit Capture
1	X	1	Baud rate generator
X	X	0	(off)

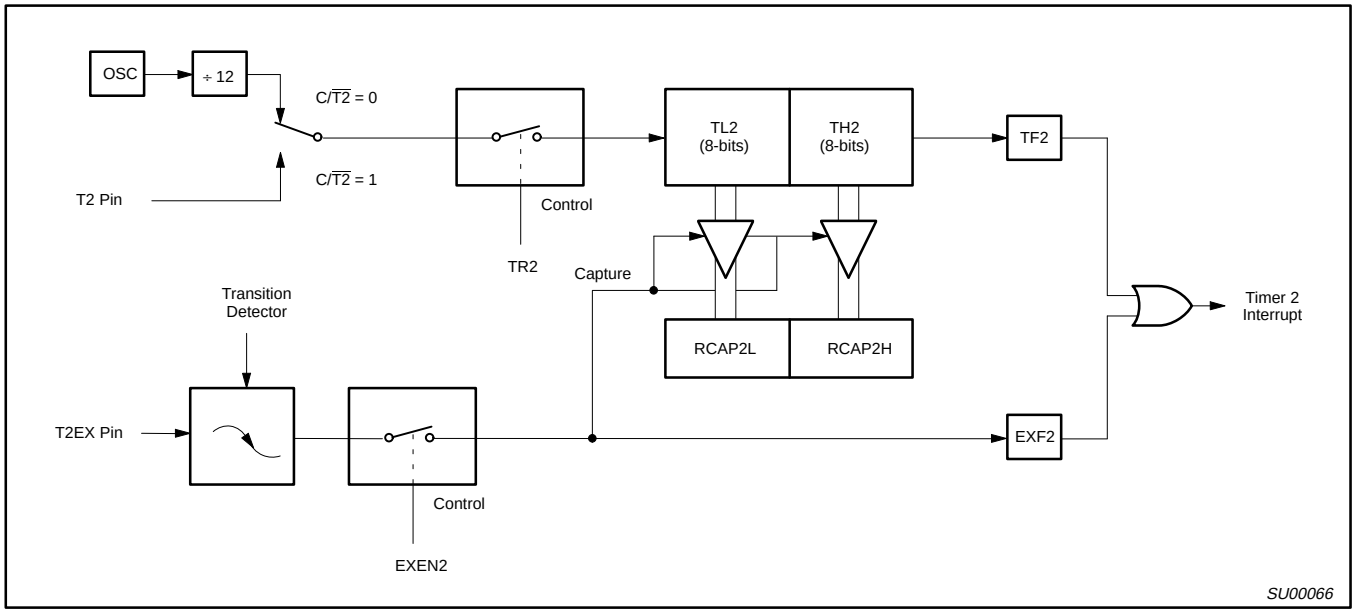

Figure 2. Timer 2 in Capture Mode

T2MOD Address = 0C9H Reset Value = XXXX XX00B

Not Bit Addressable

—	—	—	—	—	—	T2OE	DCEN
Bit 7	6	5	4	3	2	1	0

Symbol	Function
—	Not implemented, reserved for future use.*
T2OE	Timer 2 Output Enable bit. See details in Programmable Clock-Out.
DCEN	Down Count Enable bit. When set, this allows Timer 2 to be configured as an up/down counter.

* User software should not write 1s to reserved bits. These bits may be used in future 8051 family products to invoke new features. In that case, the reset or inactive value of the new bit will be 0, and its active value will be 1. The value read from a reserved bit is indeterminate.

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Figure 3. Timer 2 Mode (T2MOD) Control Register

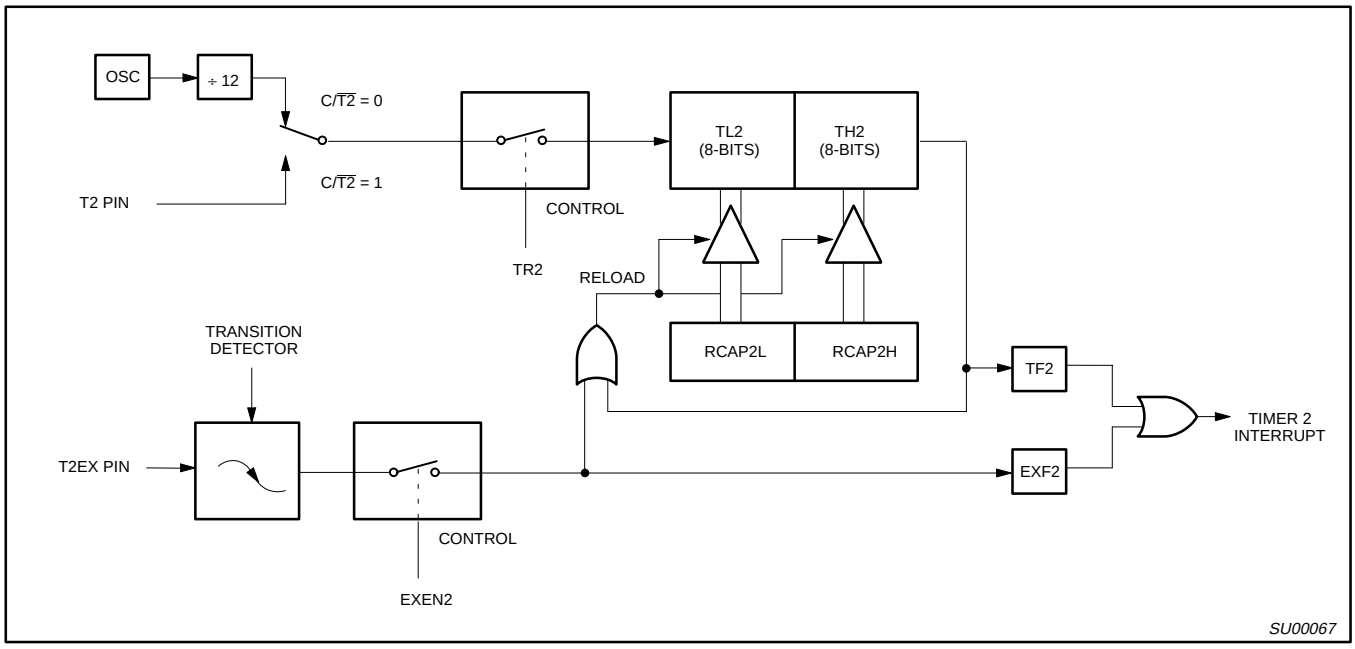

Figure 4. Timer 2 in Auto-Reload Mode (DCEN = 0)

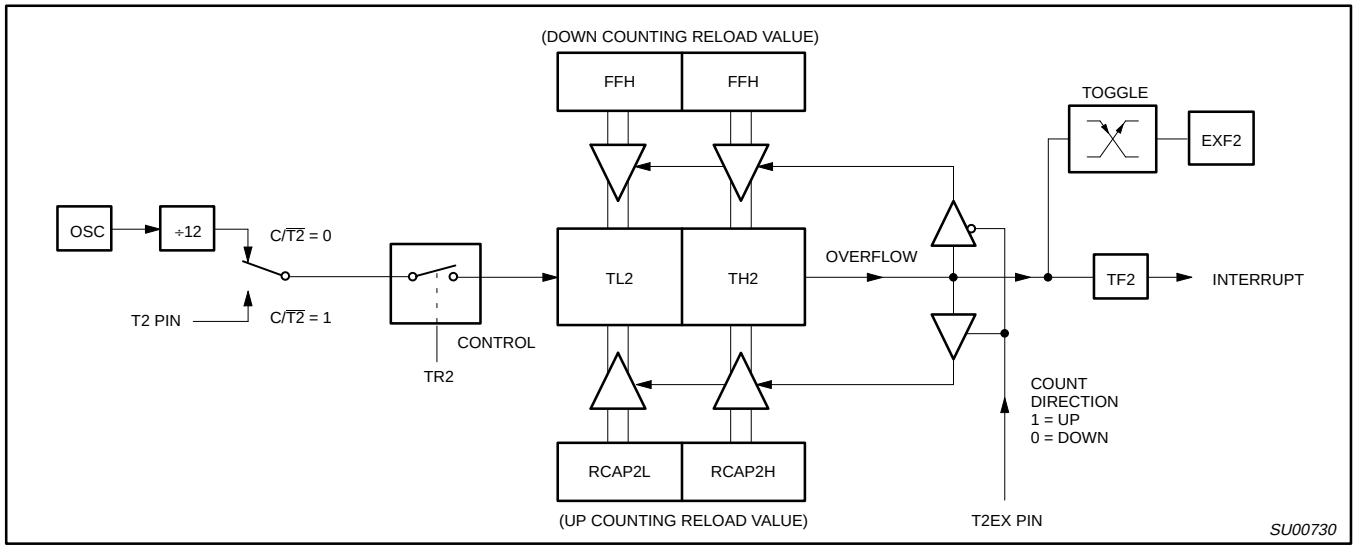

Figure 5. Timer 2 Auto Reload Mode (DCEN = 1)

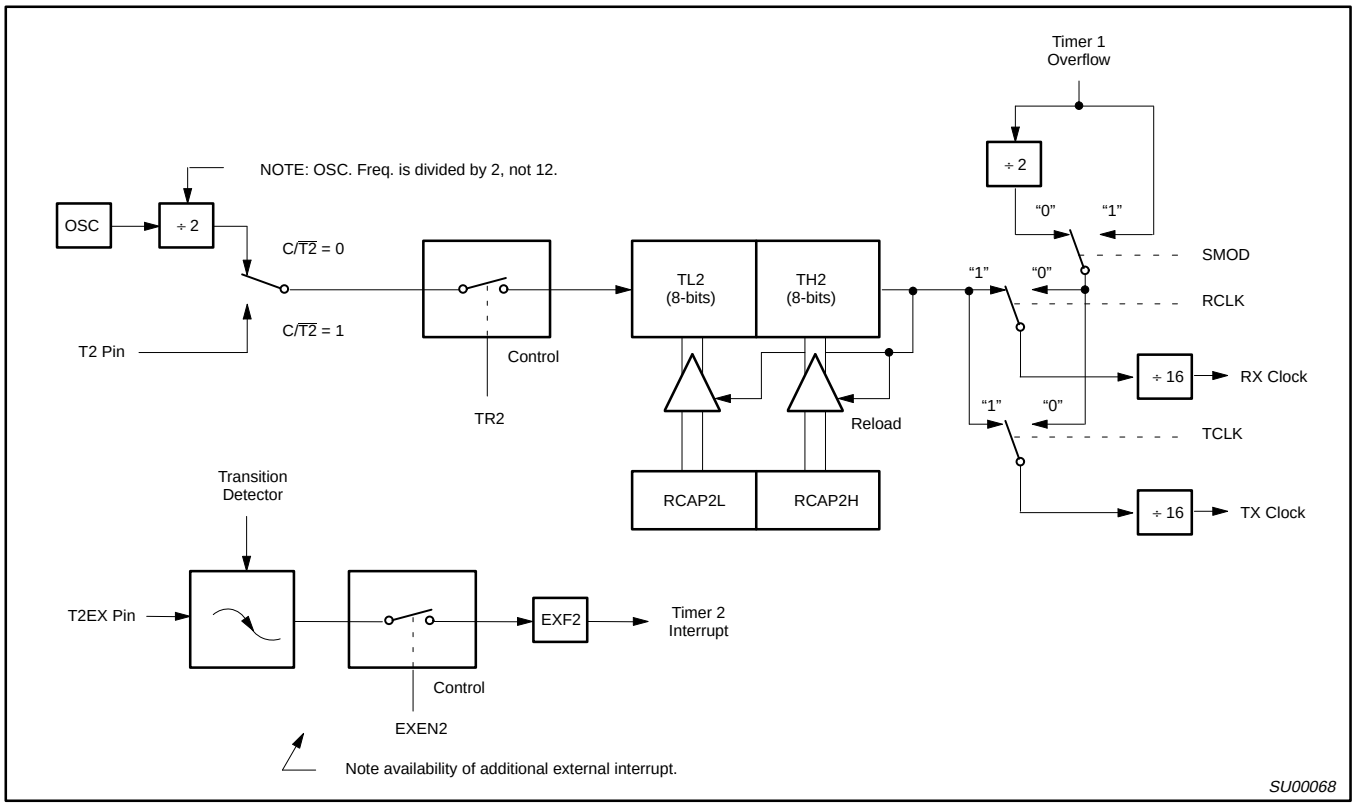

Figure 6. Timer 2 in Baud Rate Generator Mode

Table 3. Timer 2 Generated Commonly Used Baud Rates

Baud Rate	Osc Freq	Timer 2	
		RCAP2H	RCAP2L
375K	12MHz	FF	FF
9.6K	12MHz	FF	D9
2.8K	12MHz	FF	B2
2.4K	12MHz	FF	64
1.2K	12MHz	FE	C8
300	12MHz	FB	1E
110	12MHz	F2	AF
300	6MHz	FD	8F
110	6MHz	F9	57

Baud Rate Generator Mode

Bits TCLK and/or RCLK in T2CON (Table 2) allow the serial port transmit and receive baud rates to be derived from either Timer 1 or Timer 2. When TCLK= 0, Timer 1 is used as the serial port transmit baud rate generator. When TCLK= 1, Timer 2 is used as the serial port transmit baud rate generator. RCLK has the same effect for the serial port receive baud rate. With these two bits, the serial port can have different receive and transmit baud rates – one generated by Timer 1, the other by Timer 2.

Figure 6 shows the Timer 2 in baud rate generation mode. The baud rate generation mode is like the auto-reload mode,in that a rollover in TH2 causes the Timer 2 registers to be reloaded with the 16-bit value in registers RCAP2H and RCAP2L, which are preset by software.

The baud rates in modes 1 and 3 are determined by Timer 2's overflow rate given below:

$$\text{Modes 1 and 3 Baud Rates} = \frac{\text{Timer 2 Overflow Rate}}{16}$$

The timer can be configured for either "timer" or "counter" operation. In many applications, it is configured for "timer" operation (C/T2*=0). Timer operation is different for Timer 2 when it is being used as a baud rate generator.

Usually, as a timer it would increment every machine cycle (i.e., 1/12 the oscillator frequency). As a baud rate generator, it increments every state time (i.e., 1/2 the oscillator frequency). Thus the baud rate formula is as follows:

$$\text{Modes 1 and 3 Baud Rates} = \frac{\text{Oscillator Frequency}}{[32 \times [65536 - (\text{RCAP2H, RCAP2L})]]}$$

Where: (RCAP2H, RCAP2L)= The content of RCAP2H and RCAP2L taken as a 16-bit unsigned integer.

The Timer 2 as a baud rate generator mode shown in Figure 6, is valid only if RCLK and/or TCLK = 1 in T2CON register. Note that a rollover in TH2 does not set TF2, and will not generate an interrupt. Thus, the Timer 2 interrupt does not have to be disabled when Timer 2 is in the baud rate generator mode. Also if the EXEN2 (T2 external enable flag) is set, a 1-to-0 transition in T2EX (Timer/counter 2 trigger input) will set EXF2 (T2 external flag) but will not cause a reload from (RCAP2H, RCAP2L) to (TH2,TL2). Therefore when Timer 2 is in use as a baud rate generator, T2EX can be used as an additional external interrupt, if needed.

When Timer 2 is in the baud rate generator mode, one should not try to read or write TH2 and TL2. As a baud rate generator, Timer 2 is incremented every state time (osc/2) or asynchronously from pin T2; under these conditions, a read or write of TH2 or TL2 may not be accurate. The RCAP2 registers may be read, but should not be written to, because a write might overlap a reload and cause write and/or reload errors. The timer should be turned off (clear TR2) before accessing the Timer 2 or RCAP2 registers.

Table 3 shows commonly used baud rates and how they can be obtained from Timer 2.

Summary Of Baud Rate Equations

Timer 2 is in baud rate generating mode. If Timer 2 is being clocked through pin T2(P1.0) the baud rate is:

$$\text{Baud Rate} = \frac{\text{Timer 2 Overflow Rate}}{16}$$

If Timer 2 is being clocked internally, the baud rate is:

$$\text{Baud Rate} = \frac{f_{OSC}}{[32 \times [65536 - (\text{RCAP2H, RCAP2L})]]}$$

Where f_{OSC}= Oscillator Frequency

To obtain the reload value for RCAP2H and RCAP2L, the above equation can be rewritten as:

$$\text{RCAP2H, RCAP2L} = 65536 - \left(\frac{f_{OSC}}{32 \times \text{Baud Rate}}\right)$$

Timer/Counter 2 Set-up

Except for the baud rate generator mode, the values given for T2CON do not include the setting of the TR2 bit. Therefore, bit TR2 must be set, separately, to turn the timer on. see Table 4 for set-up of Timer 2 as a timer. Also see Table 5 for set-up of Timer 2 as a counter.

POWER OFF FLAG[3]

The Power Off Flag (POF) is set by on-chip circuitry when the V_{CC} level on the 80C54/80C58 rises from 0 to 5V. The POF bit can be set or cleared by software allowing a user to determine if the reset is the result of a power-on or a warm start after powerdown. The V_{CC} level must remain above 3V for the POF to remain unaffected by the V_{CC} level.

Table 4. Timer 2 as a Timer

MODE	T2CON	
	INTERNAL CONTROL (Note 1)	EXTERNAL CONTROL (Note 2)
16-bit Auto-Reload	00H	08H
16-bit Capture	01H	09H
Baud rate generator receive and transmit same baud rate	34H	36H
Receive only	24H	26H
Transmit only	14H	16H

Table 5. Timer 2 as a Counter

MODE	TMOD	
	INTERNAL CONTROL (Note 1)	EXTERNAL CONTROL (Note 2)
16-bit	02H	0AH
Auto-Reload	03H	0BH

NOTES:
1. Capture/reload occurs only on timer/counter overflow.
2. Capture/reload occurs on timer/counter overflow and a 1-to-0 transition on T2EX (P1.1) pin except when Timer 2 is used in the baud rate generator mode.
3. POF not present in 80C52.

OSCILLATOR CHARACTERISTICS

XTAL1 and XTAL2 are the input and output, respectively, of an inverting amplifier. The pins can be configured for use as an on-chip oscillator.

To drive the device from an external clock source, XTAL1 should be driven while XTAL2 is left unconnected. There are no requirements on the duty cycle of the external clock signal, because the input to the internal clock circuitry is through a divide-by-two flip-flop. However, minimum and maximum high and low times specified in the data sheet must be observed.

Reset

A reset is accomplished by holding the RST pin high for at least two machine cycles (24 oscillator periods), while the oscillator is running. To insure a good power-on reset, the RST pin must be high long enough to allow the oscillator time to start up (normally a few milliseconds) plus two machine cycles. At power-on, the voltage on V_{CC} and RST must come up at the same time for a proper start-up. Ports 1, 2, and 3 will asynchronously be driven to their reset condition when a voltage above V_{IH1} (min.) is applied to RESET.

Idle Mode

In the idle mode (see Table 6), the CPU puts itself to sleep while all of the on-chip peripherals stay active. The instruction to invoke the idle mode is the last instruction executed in the normal operating mode before the idle mode is activated. The CPU contents, the on-chip RAM, and all of the special function registers remain intact during this mode. The idle mode can be terminated either by any enabled interrupt (at which time the process is picked up at the interrupt service routine and continued), or by a hardware reset which starts the processor in the same manner as a power-on reset.

Power-Down Mode

To save even more power, a Power Down mode (see Table 6) can be invoked by software. In this mode, the oscillator is stopped and the instruction that invoked Power Down is the last instruction executed. The on-chip RAM and Special Function Registers retain their values until the Power Down mode is terminated.

On the 80C52/54/58 either a hardware reset or external interrupt can be used to exit from Power Down. Reset redefines all the SFRs but does not change the on-chip RAM. An external interrupt allows both the SFRs and the on-chip RAM to retain their values.

To properly terminate Power Down the reset or external interrupt should not be executed before V_{CC} is restored to its normal operating level and must be held active long enough for the oscillator to restart and stabilize (normally less than 10ms).

With an external interrupt, INT0 and INT1 must be enabled and configured as level-sensitive. Holding the pin low restarts the oscillator but bringing the pin back high completes the exit. Once the interrupt is serviced, the next instruction to be executed after RETI will be the one following the instruction that put the device into Power Down.

Design Consideration

- When the idle mode is terminated by a hardware reset, the device normally resumes program execution, from where it left off, up to two machine cycles before the internal rest algorithm takes control. On-chip hardware inhibits access to internal RAM in this event, but access to the port pins is not inhibited. To eliminate the possibility of an unexpected write when Idle is terminated by reset, the instruction following the one that invokes Idle should not be one that writes to a port pin or to external memory.

ONCE™ Mode

The ONCE ("On-Circuit Emulation") Mode facilitates testing and debugging of systems using the 80C52/54/58 without removing the device from the circuit. The ONCE Mode is invoked by:

1. Pull ALE low while the device is in reset and $\overline{PSEN}$ is high;
2. Hold ALE low as RST is deactivated.

While the device is in ONCE Mode, the Port 0 pins go into a float state, and the other port pins and ALE and $\overline{PSEN}$ are weakly pulled high. The oscillator circuit remains active. While the 80C52/54/58 is in this mode, an emulator or test CPU can be used to drive the circuit. Normal operation is restored when a normal reset is applied.

Programmable Clock-Out

The 80C52/54/58 has a new feature. A 50% duty cycle clock can be programmed to come out on P1.0. This pin, besides being a regular I/O pin, has two alternate functions. It can be programmed:

1. to input the external clock for Timer/Counter 2, or
2. to output a 50% duty cycle clock ranging from 61Hz to 4MHz at a 16MHz operating frequency.

To configure the Timer/Counter 2 as a clock generator, bit C/T2 (in T2CON) must be cleared and bit T2OE in T2MOD must be set. Bit TR2 (T2CON.2) also must be set to start the timer.

The Clock-Out frequency depends on the oscillator frequency and the reload value of Timer 2 capture registers (RCAP2H, RCAP2L) as shown in this equation:

$$\frac{\text{Oscillator Frequency}}{4 \times (65536 - \text{RCAP2H, RCAP2L})}$$

In the Clock-Out mode Timer 2 roll-overs will not generate an interrupt. This is similar to when it is used as a baud-rate generator. It is possible to use Timer 2 as a baud-rate generator and a clock generator simultaneously. Note, however, that the baud-rate and the Clock-Out frequency will be the same.

Table 6. External Pin Status During Idle and Power-Down Mode

MODE	PROGRAM MEMORY	ALE	$\overline{PSEN}$	PORT 0	PORT 1	PORT 2	PORT 3
Idle	Internal	1	1	Data	Data	Data	Data
Idle	External	1	1	Float	Data	Address	Data
Power-down	Internal	0	0	Data	Data	Data	Data
Power-down	External	0	0	Float	Data	Data	Data

Enhanced UART

The UART operates in all of the usual modes that are described in the first section of *Data Handbook IC20, 80C51-Based 8-Bit Microcontrollers*. In addition the UART can perform framing error detect by looking for missing stop bits, and automatic address recognition. The 80C52/54/58 UART also fully supports multiprocessor communication as does the standard 80C51 UART.

When used for framing error detect the UART looks for missing stop bits in the communication. A missing bit will set the FE bit in the SCON register. The FE bit shares the SCON.7 bit with SM0 and the function of SCON.7 is determined by PCON.6 (SMOD0) (see Figure 7). If SMOD0 is set then SCON.7 functions as FE. SCON.7 functions as SM0 when SMOD0 is cleared. When used as FE SCON.7 can only be cleared by software. Refer to Figure 8.

Automatic Address Recognition

Automatic Address Recognition is a feature which allows the UART to recognize certain addresses in the serial bit stream by using hardware to make the comparisons. This feature saves a great deal of software overhead by eliminating the need for the software to examine every serial address which passes by the serial port. This feature is enabled by setting the SM2 bit in SCON. In the 9 bit UART modes, mode 2 and mode 3, the Receive Interrupt flag (RI) will be automatically set when the received byte contains either the “Given” address or the “Broadcast” address. The 9 bit mode requires that the 9th information bit is a 1 to indicate that the received information is an address and not data. Automatic address recognition is shown in Figure 9.

The 8 bit mode is called Mode 1. In this mode the RI flag will be set if SM2 is enabled and the information received has a valid stop bit following the 8 address bits and the information is either a Given or Broadcast address.

Mode 0 is the Shift Register mode and SM2 is ignored.

Using the Automatic Address Recognition feature allows a master to selectively communicate with one or more slaves by invoking the Given slave address or addresses. All of the slaves may be contacted by using the Broadcast address. Two special Function Registers are used to define the slave’s address, SADDR, and the address mask, SADEN. SADEN is used to define which bits in the SADDR are to b used and which bits are “don’t care”. The SADEN mask can be logically ANDed with the SADDR to create the “|Given” address which the master will use for addressing each of the slaves. Use of the Given address allows multiple slaves to be recognized while excluding others. The following examples will help to show the versatility of this scheme:

Slave 0	SADDR	=	1100 0000
	SADEN	=	1111 1101
	Given	=	1100 00X0
Slave 1	SADDR	=	1100 0000
	SADEN	=	1111 1110
	Given	=	1100 000X

In the above example SADDR is the same and the SADEN data is used to differentiate between the two slaves. Slave 0 requires a 0 in bit 0 and it ignores bit 1. Slave 1 requires a 0 in bit 1 and bit 0 is ignored. A unique address for Slave 0 would be 1100 0010 since slave 1 requires a 0 in bit 1. A unique address for slave 1 would be 1100 0001 since a 1 in bit 0 will exclude slave 0. Both slaves can be selected at the same time by an address which has bit 0 = 0 (for slave 0) and bit 1 = 0 (for slave 1). Thus, both could be addressed with 1100 0000.

In a more complex system the following could be used to select slaves 1 and 2 while excluding slave 0:

Slave 0	SADDR	=	1100 0000
	SADEN	=	1111 1001
	Given	=	1100 0XX0
Slave 1	SADDR	=	1110 0000
	SADEN	=	1111 1010
	Given	=	1110 0X0X
Slave 2	SADDR	=	1110 0000
	SADEN	=	1111 1100
	Given	=	1110 00XX

In the above example the differentiation among the 3 slaves is in the lower 3 address bits. Slave 0 requires that bit 0 = 0 and it can be uniquely addressed by 1110 0110. Slave 1 requires that bit 1 = 0 and it can be uniquely addressed by 1110 and 0101. Slave 2 requires that bit 2 = 0 and its unique address is 1110 0011. To select Slaves 0 and 1 and exclude Slave 2 use address 1110 0100, since it is necessary t make bit 2 = 1 to exclude slave 2.

The Broadcast Address for each slave is created by taking the logical OR of SADDR and SADEN. Zeros in this result are teated as don’t-cares. In most cases, interpreting the don’t-cares as ones, the broadcast address will be FF hexadecimal.

Upon reset SADDR (SFR address 0A9H) and SADEN (SFR address 0B9H) are leaded with 0s. This produces a given address of all “don’t cares” as well as a Broadcast address of all “don’t cares”. this effectively disables the Automatic Addressing mode and allows the microcontroller to use standard 80C51 type UART drivers which do not make use of this feature.

SCON Address = 98H Reset Value = 0000 0000B

Bit Addressable

	SM0/FE	SM1	SM2	REN	TB8	RB8	TI	RI
Bit:	7	6	5	4	3	2	1	0

(SMOD0 = 0/1)*

Symbol	Function
FE	Framing Error bit. This bit is set by the receiver when an invalid stop bit is detected. The FE bit is not cleared by valid frames but should be cleared by software. The SMOD0 bit must be set to enable access to the FE bit.
SM0	Serial Port Mode Bit 0, (SMOD0 must = 0 to access bit SM0)
SM1	Serial Port Mode Bit 1

SM0	SM1	Mode	Description	Baud Rate**
0	0	0	shift register	$f_{OSC}/12$
0	1	1	8-bit UART	variable
1	0	2	9-bit UART	$f_{OSC}/64$ or $f_{OSC}/32$
1	1	3	9-bit UART	variable

SM2	Enables the Automatic Address Recognition feature in Modes 2 or 3. If SM2 = 1 then RI will not be set unless the received 9th data bit (RB8) is 1, indicating an address, and the received byte is a Given or Broadcast Address. In Mode 1, if SM2 = 1 then RI will not be activated unless a valid stop bit was received, and the received byte is a Given or Broadcast Address. In Mode 0, SM2 should be 0.
REN	Enables serial reception. Set by software to enable reception. Clear by software to disable reception.
TB8	The 9th data bit that will be transmitted in Modes 2 and 3. Set or clear by software as desired.
RB8	In modes 2 and 3, the 9th data bit that was received. In Mode 1, if SM2 = 0, RB8 is the stop bit that was received. In Mode 0, RB8 is not used.
TI	Transmit interrupt flag. Set by hardware at the end of the 8th bit time in Mode 0, or at the beginning of the stop bit in the other modes, in any serial transmission. Must be cleared by software.
RI	Receive interrupt flag. Set by hardware at the end of the 8th bit time in Mode 0, or halfway through the stop bit time in the other modes, in any serial reception (except see SM2). Must be cleared by software.

NOTE:
*SMOD0 is located at PCON6.
**f_{OSC} = oscillator frequency

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Figure 7. SCON: Serial Port Control Register

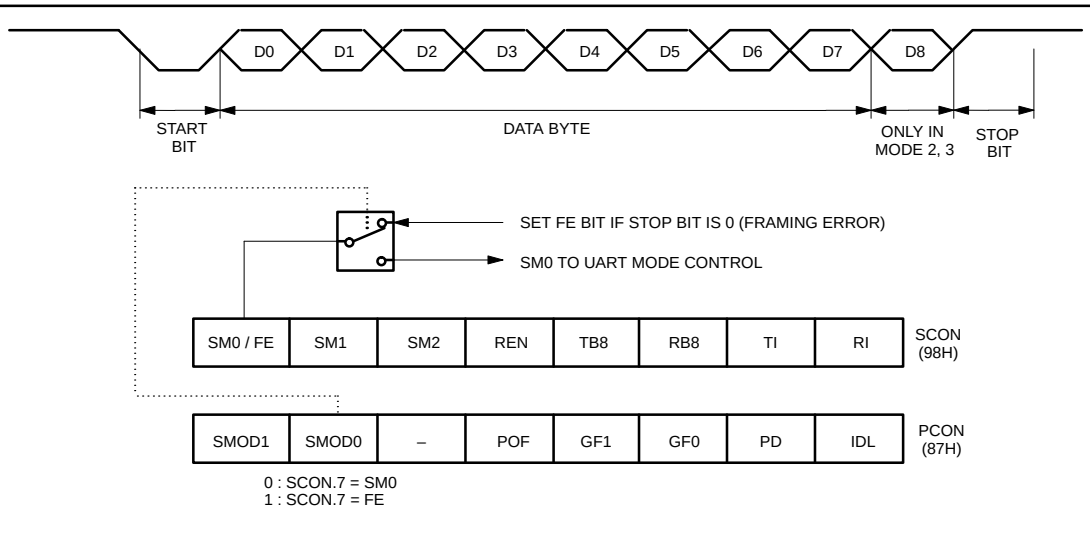

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Figure 8. UART Framing Error Detection

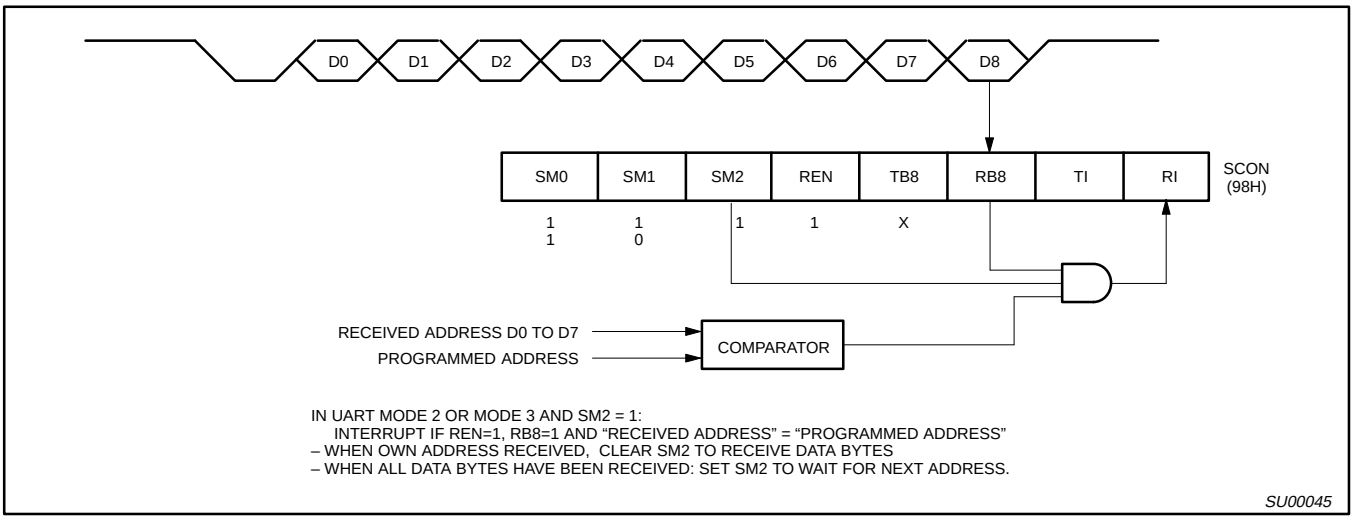

Figure 9. UART Multiprocessor Communication, Automatic Address Recognition

Interrupt Priority Structure

The 80C52/54/58 has a 6-source four-level interrupt structure. There are 3 SFRs associated with the interrupts on the 80C52/54/58. They are the IE and IP. (See Figures 10 and 11.) In addition, there is the IPH (Interrupt Priority High) register that makes the four-level interrupt structure possible. The IPH is located at SFR address B7H. The structure of the IPH register and a description of its bits is shown below:

IPH (Interrupt Priority High) (B7H)

7	6	5	4	3	2	1	0
–	–	PT2H	PSH	PT1H	PX1H	PT0H	PX0H

IPH.0 PX0H External interrupt 0 priority high
IPH.1 PT0H Timer 0 interrupt priority high
IPH.2 PX1H External interrupt 1 priority high
IPH.3 PT1H Timer 1 interrupt priority high
IPH.4 PSH Serial Port interrupt high
IPH.5 PT2H Timer 2 interrupt priority high
IPH.6 — Not implemented
IPH.7 — Not implemented

The function of the IPH SFR is simple and when combined with the IP SFR determines the priority of each interrupt. The priority of each interrupt is determined as shown in the following table:

PRIORITY BITS		INTERRUPT PRIORITY LEVEL
IPH.x	IP.x	
0	0	Level 0 (lowest priority)
0	1	Level 1
1	0	Level 2
1	1	Level 3 (highest priority)

The priority scheme for servicing the interrupts is the same as that for the 80C51, except there are four interrupt levels on the 80C52/54/58 rather than two as on the 80C51. An interrupt will be serviced as long as an interrupt of equal or higher priority is not already being serviced. If an interrupt of equal or higher level priority is being serviced, the new interrupt will wait until it is finished before being serviced. If a lower priority level interrupt is being serviced, it will be stopped and the new interrupt serviced. When the new interrupt is finished, the lower priority level interrupt that was stopped will be completed.

Table 7. Interrupt Table

SOURCE	POLLING PRIORITY	REQUEST BITS	HARDWARE CLEAR?	VECTOR ADDRESS
X0	1	IE0	N (L)[1] Y (T)[2]	03H
T0	2	TP0	Y	0BH
X1	3	IE1	N (L) Y (T)	13H
T1	4	TF1	Y	1BH
SP	5	R1, TI	N	23H
T2	6	TF2, EXF2	N	2BH
PCA	7	CF, CCFn n = 0–4	N	33H

NOTES:
1. L = Level activated
2. T = Transition activated

	7	6	5	4	3	2	1	0
IE0 (A8H)	EA	—	ET2	ES	ET1	EX1	ET0	EX0

Enable Bit = 1 enables the interrupt.
Enable Bit = 0 disables it.

BIT	SYMBOL	FUNCTION
IE.7	EA	Global disable bit. If EA = 0, all interrupts are disabled. If EA = 1, each interrupt can be individually enabled or disabled by setting or clearing its enable bit.
IE.6	—	
IE.5	ET2	Timer 2 interrupt enable bit.
IE.4	ES	Serial Port interrupt enable bit.
IE.3	ET1	Timer 1 interrupt enable bit.
IE.2	EX1	External interrupt 1 enable bit.
IE.1	ET0	Timer 0 interrupt enable bit.
IE.0	EX0	External interrupt 0 enable bit.

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Figure 10. IE Registers

	7	6	5	4	3	2	1	0
IP0 (B8H)	—	—	PT2	PS	PT1	PX1	PT0	PX0

Priority Bit = 1 assigns high priority
Priority Bit = 0 assigns low priority

BIT	SYMBOL	FUNCTION
IP.7	—	Not implemented, reserved for future use.
IP.6	—	
IP.5	PT2	Timer 2 interrupt priority bit.
IP.4	PS	Serial Port interrupt priority bit.
IP.3	PT1	Timer 1 interrupt priority bit.
IP.2	PX1	External interrupt 1 priority bit.
IP.1	PT0	Timer 0 interrupt priority bit.
IP.0	PX0	External interrupt 0 priority bit.

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Figure 11. IP Registers

Reduced EMI Mode

The AO bit (AUXR.0) in the AUXR register when set disables the ALE output.

80C52/80C54/80C58 Reduced EMI Mode

AUXR (8EH)

7	6	5	4	3	2	1	0
–	–	–	–	–	–	–	AO

AO: Turns off ALE output.

Dual Data Pointer Register (DPTR)

The dual DPTR structure (see Figure 12) is a way by which the 80C52/54/58 will specify the address of an external data memory location. There are two 16-bit DPTR registers that address the external memory, and a single bit called DPS = AUXR1/bit0 that allows the program code to switch between them.

- Register Name: AUXR1#
- SFR Address: A2H
- Reset Value: xxxxxxx0B

7	6	5	4	3	2	1	0
–	–	–	–	–	–	–	DPS

Where:
DPS = AUXR1/bit0 = Switches between DPTR0 and DPTR1.

Select Reg	DPS
DPTR0	0
DPTR1	1

The DPS bit status whould be saved by software when switching between DPTR0 and DPTR1.

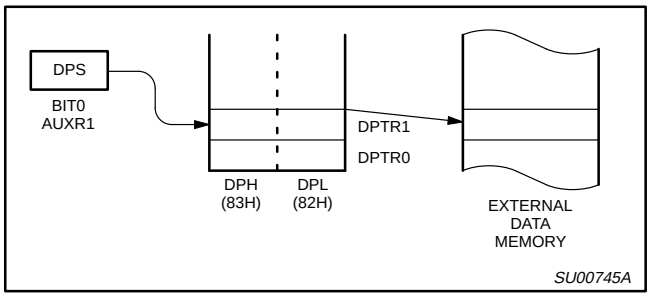


Figure 12. DPTR Structure

DPTR Instructions

The instructions that refer to DPTR refer to the data pointer that is currently selected using the AUXR1/bit 0 register. The six instructions that use the DPTR are as follows:

INC DPTR	Increments the data pointer by 1
MOV DPTR, #data16	Loads the DPTR with a 16-bit constant
MOV A, @ A+DPTR	Move code byte relative to DPTR to ACC
MOVX A, @ DPTR	Move external RAM (16-bit address) to ACC
MOVX @ DPTR , A	Move ACC to external RAM (16-bit address)
JMP @ A + DPTR	Jump indirect relative to DPTR

The data pointer can be accessed on a byte-by-byte basis by specifying the Low or High byte in an instruction which accesses the SFRs. See application note AN458 for detailed operation

ABSOLUTE MAXIMUM RATINGS[1, 2, 3]

PARAMETER	RATING	UNIT
Operating temperature under bias	0 to +70 or –40 to +85	°C
Storage temperature range	–65 to +150	°C
Voltage on $\overline{EA}/V_{PP}$ pin to V_{SS}	0 to +13.0	V
Voltage on any other pin to V_{SS}	–0.5 to +6.5	V
Maximum I_{OL} per I/O pin	15	mA
Power dissipation (based on package heat transfer limitations, not device power consumption)	1.5	W

NOTES:
1. Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any conditions other than those described in the AC and DC Electrical Characteristics section of this specification is not implied.
2. This product includes circuitry specifically designed for the protection of its internal devices from the damaging effects of excessive static charge. Nonetheless, it is suggested that conventional precautions be taken to avoid applying greater than the rated maxima.
3. Parameters are valid over operating temperature range unless otherwise specified. All voltages are with respect to V_{SS} unless otherwise noted.

DC ELECTRICAL CHARACTERISTICS

T_{amb} = 0°C to +70°C or –40°C to +85°C, V_{CC} = 5.0V ±10%; V_{SS} = 0V

SYMBOL	PARAMETER	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP[1]	MAX	
V_{IL}	Input low voltage	4.5V < V_{CC} < 5.5V	–0.5		$0.2V_{CC}$–0.1	V
V_{IH}	Input high voltage (ports 0, 1, 2, 3, $\overline{EA}$)		$0.2V_{CC}$+0.9		V_{CC}+0.5	V
V_{IH1}	Input high voltage, XTAL1, RST		$0.7V_{CC}$		V_{CC}+0.5	V
V_{OL}	Output low voltage, ports 1, 2, 3[8]	V_{CC} = 4.5V I_{OL} = 1.6mA[2]			0.4	V
V_{OL1}	Output low voltage, port 0, ALE, $\overline{PSEN}$[8, 7]	V_{CC} = 4.5V I_{OL} = 3.2mA[2]			0.4	V
V_{OH}	Output high voltage, ports 1, 2, 3 [3]	V_{CC} = 4.5V I_{OH} = –30µA	V_{CC} – 0.7			V
V_{OH1}	Output high voltage (port 0 in external bus mode), ALE[9], $\overline{PSEN}$[3]	V_{CC} = 4.5V I_{OH} = –3.2mA	V_{CC} – 0.7			V
I_{IL}	Logical 0 input current, ports 1, 2, 3	V_{IN} = 0.4V	–1		–50	µA
I_{TL}	Logical 1-to-0 transition current, ports 1, 2, 3[6]	V_{IN} = 2.0V See note 4			–650	µA
I_{LI}	Input leakage current, port 0	0.45 < V_{IN} < V_{CC} – 0.3			±10	µA
I_{CC}	Power supply current (see Figure 20): Active mode @ 16MHz[5] Idle mode @ 16MHz[5] Power-down mode	See note 5 T_{amb} = 0 to +70°C T_{amb} = –40 to +85°C		 3	 16 4 50 75	 mA mA µA µA
R_{RST}	Internal reset pull-down resistor		40		225	kΩ
C_{IO}	Pin capacitance[10] (except $\overline{EA}$)				15	pF

NOTES:

1. Typical ratings are not guaranteed. The values listed are at room temperature, 5V.
2. Capacitive loading on ports 0 and 2 may cause spurious noise to be superimposed on the V_{OL}s of ALE and ports 1 and 3. The noise is due to external bus capacitance discharging into the port 0 and port 2 pins when these pins make 1-to-0 transitions during bus operations. In the worst cases (capacitive loading > 100pF), the noise pulse on the ALE pin may exceed 0.8V. In such cases, it may be desirable to qualify ALE with a Schmitt Trigger, or use an address latch with a Schmitt Trigger STROBE input. I_{OL} can exceed these conditions provided that no single output sinks more than 5mA and no more than two outputs exceed the test conditions.
3. Capacitive loading on ports 0 and 2 may cause the V_{OH} on ALE and $\overline{PSEN}$ to momentarily fall below the (V_{CC}–0.7) specification when the address bits are stabilizing.
4. Pins of ports 1, 2 and 3 source a transition current when they are being externally driven from 1 to 0. The transition current reaches its maximum value when V_{IN} is approximately 2V.
5. See Figures 21 through 24 for I_{CC} test conditions.
   Active Mode: $I_{CC} = 0.9 \times FREQ + 1.1$;
   Idle Mode: $I_{CC} = 0.18 \times FREQ + 1.0$; See Figure 20.
6. This value applies to T_{amb} = 0°C to +70°C. For T_{amb} = –40°C to +85°C, I_{TL} = –750µA.
7. Load capacitance for port 0, ALE, and $\overline{PSEN}$ = 100pF, load capacitance for all other outputs = 80pF.
8. Under steady state (non-transient) conditions, I_{OL} must be externally limited as follows:
   Maximum I_{OL} per port pin: 15mA (*NOTE: This is 85°C specification.)
   Maximum I_{OL} per 8-bit port: 26mA
   Maximum total I_{OL} for all outputs: 71mA
   If I_{OL} exceeds the test condition, V_{OL} may exceed the related specification. Pins are not guaranteed to sink current greater than the listed test conditions.
9. ALE is tested to V_{OH1}, except when ALE is off then V_{OH} is the voltage specification.
10. Pin capacitance is characterized but not tested. Pin capacitance is less than 25pF. Pin capacitance of ceramic package is less than 15pF (except $\overline{EA}$ it is 25pF).

AC ELECTRICAL CHARACTERISTICS

T_{amb} = 0°C to +70°C or –40°C to +85°C, V_{CC} = 5V ±10%, V_{SS} = 0V[1, 2, 3]

SYMBOL	FIGURE	PARAMETER	16MHz CLOCK		VARIABLE CLOCK		UNIT
			MIN	MAX	MIN	MAX	
$1/t_{CLCL}$	13	Oscillator frequency Speed versions : E			3.5	16	MHz
t_{LHLL}	13	ALE pulse width	85		$2t_{CLCL}$–40		ns
t_{AVLL}	13	Address valid to ALE low	22		t_{CLCL}–40		ns
t_{LLAX}	13	Address hold after ALE low	32		t_{CLCL}–30		ns
t_{LLIV}	13	ALE low to valid instruction in		150		$4t_{CLCL}$–100	ns
t_{LLPL}	13	ALE low to $\overline{PSEN}$ low	32		t_{CLCL}–30		ns
t_{PLPH}	13	$\overline{PSEN}$ pulse width	142		$3t_{CLCL}$–45		ns
t_{PLIV}	13	$\overline{PSEN}$ low to valid instruction in[4]		82		$3t_{CLCL}$–105	ns
t_{PXIX}	13	Input instruction hold after $\overline{PSEN}$	0		0		ns
t_{PXIZ}	13	Input instruction float after $\overline{PSEN}$		37		t_{CLCL}–25	ns
t_{AVIV}	13	Address to valid instruction in[4]		207		$5t_{CLCL}$–105	ns
t_{PLAZ}	13	$\overline{PSEN}$ low to address float		10		10	ns
Data Memory							
t_{RLRH}	14, 15	$\overline{RD}$ pulse width	275		$6t_{CLCL}$–100		ns
t_{WLWH}	14, 15	$\overline{WR}$ pulse width	275		$6t_{CLCL}$–100		ns
t_{RLDV}	14, 15	$\overline{RD}$ low to valid data in		147		$5t_{CLCL}$–165	ns
t_{RHDX}	14, 15	Data hold after $\overline{RD}$	0		0		ns
t_{RHDZ}	14, 15	Data float after $\overline{RD}$		65		$2t_{CLCL}$–60	ns
t_{LLDV}	14, 15	ALE low to valid data in		350		$8t_{CLCL}$–150	ns
t_{AVDV}	14, 15	Address to valid data in		397		$9t_{CLCL}$–165	ns
t_{LLWL}	14, 15	ALE low to $\overline{RD}$ or $\overline{WR}$ low	137	239	$3t_{CLCL}$–50	$3t_{CLCL}$+50	ns
t_{AVWL}	14, 15	Address valid to $\overline{WR}$ low or $\overline{RD}$ low	122		$4t_{CLCL}$–130		ns
t_{QVWX}	14, 15	Data valid to $\overline{WR}$ transition	13		t_{CLCL}–50		ns
t_{WHQX}	14, 15	Data hold after $\overline{WR}$	13		t_{CLCL}–50		ns
t_{QVWH}	15	Data valid to $\overline{WR}$ high	287		$7t_{CLCL}$–150		ns
t_{RLAZ}	14, 15	$\overline{RD}$ low to address float		0		0	ns
t_{WHLH}	14, 15	$\overline{RD}$ or $\overline{WR}$ high to ALE high	23	103	t_{CLCL}–40	t_{CLCL}+40	ns
External Clock							
t_{CHCX}	17	High time	20		20	t_{CLCL}–t_{CLCX}	ns
t_{CLCX}	17	Low time	20		20	t_{CLCL}–t_{CHCX}	ns
t_{CLCH}	17	Rise time		20		20	ns
t_{CHCL}	17	Fall time		20		20	ns
Shift Register							
t_{XLXL}	16	Serial port clock cycle time	750		$12t_{CLCL}$		ns
t_{QVXH}	16	Output data setup to clock rising edge	492		$10t_{CLCL}$–133		ns
t_{XHQX}	16	Output data hold after clock rising edge	8		$2t_{CLCL}$–117		ns
t_{XHDX}	16	Input data hold after clock rising edge	0		0		ns
t_{XHDV}	16	Clock rising edge to input data valid		492		$10t_{CLCL}$–133	ns

NOTES:
1. Parameters are valid over operating temperature range unless otherwise specified.
2. Load capacitance for port 0, ALE, and $\overline{PSEN}$ = 100pF, load capacitance for all other outputs = 80pF.
3. Interfacing the 80C52/54/58 to devices with float times up to 45ns is permitted. This limited bus contention will not cause damage to Port 0 drivers.
4. See application note AN457 for external memory interfacing.

AC ELECTRICAL CHARACTERISTICS

T_{amb} = 0°C to +70°C or –40°C to +85°C, V_{CC} = 5V ±10%, V_{SS} = 0V[1, 2, 3]

SYMBOL	FIGURE	PARAMETER	24MHz CLOCK		VARIABLE CLOCK[4]		33MHz CLOCK		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
$1/t_{CLCL}$	13	Oscillator frequency Speed versions : I (24MHz) : N (33MHz)	3.5	24	3.5	33	 3.5	 33	MHz
t_{LHLL}	13	ALE pulse width	43		$2t_{CLCL}$–40		21		ns
t_{AVLL}	13	Address valid to ALE low	17		t_{CLCL}–25		5		ns
t_{LLAX}	13	Address hold after ALE low	17		t_{CLCL}–25				ns
t_{LLIV}	13	ALE low to valid instruction in		102		$4t_{CLCL}$–65		55	ns
t_{LLPL}	13	ALE low to $\overline{PSEN}$ low	17		t_{CLCL}–25		5		ns
t_{PLPH}	13	$\overline{PSEN}$ pulse width	80		$3t_{CLCL}$–45		45		ns
t_{PLIV}	13	$\overline{PSEN}$ low to valid instruction in		65		$3t_{CLCL}$–60		30	ns
t_{PXIX}	13	Input instruction hold after $\overline{PSEN}$	0		0		0		ns
t_{PXIZ}	13	Input instruction float after $\overline{PSEN}$		17		t_{CLCL}–25		5	ns
t_{AVIV}	13	Address to valid instruction in		128		$5t_{CLCL}$–80		70	ns
t_{PLAZ}	13	$\overline{PSEN}$ low to address float		10		10		10	ns
Data Memory									
t_{RLRH}	14, 15	$\overline{RD}$ pulse width	150		$6t_{CLCL}$–100		82		ns
t_{WLWH}	14, 15	$\overline{WR}$ pulse width	150		$6t_{CLCL}$–100		82		ns
t_{RLDV}	14, 15	$\overline{RD}$ low to valid data in		118		$5t_{CLCL}$–90		60	ns
t_{RHDX}	14, 15	Data hold after $\overline{RD}$	0		0		0		ns
t_{RHDZ}	14, 15	Data float after $\overline{RD}$		55		$2t_{CLCL}$–28		32	ns
t_{LLDV}	14, 15	ALE low to valid data in		183		$8t_{CLCL}$–150		90	ns
t_{AVDV}	14, 15	Address to valid data in		210		$9t_{CLCL}$–165		105	ns
t_{LLWL}	14, 15	ALE low to $\overline{RD}$ or $\overline{WR}$ low	75	175	$3t_{CLCL}$–50	$3t_{CLCL}$+50	40	140	ns
t_{AVWL}	14, 15	Address valid to $\overline{WR}$ low or $\overline{RD}$ low	92		$4t_{CLCL}$–75		45		ns
t_{QVWX}	14, 15	Data valid to $\overline{WR}$ transition	12		t_{CLCL}–30		0		ns
t_{WHQX}	14, 15	Data hold after $\overline{WR}$	17		t_{CLCL}–25		5		ns
t_{QVWH}	15	Data valid to $\overline{WR}$ high	162		$7t_{CLCL}$–130		80		ns
t_{RLAZ}	14, 15	$\overline{RD}$ low to address float		0		0		0	ns
t_{WHLH}	14, 15	$\overline{RD}$ or $\overline{WR}$ high to ALE high	17	67	t_{CLCL}–25	t_{CLCL}+25	5	55	ns
External Clock									
t_{CHCX}	17	High time	17		17	t_{CLCL}–t_{CLCX}			ns
t_{CLCX}	17	Low time	17		17	t_{CLCL}–t_{CHCX}			ns
t_{CLCH}	17	Rise time		5		5			ns
t_{CHCL}	17	Fall time		5		5			ns
Shift Register									
t_{XLXL}	16	Serial port clock cycle time	505		$12t_{CLCL}$		360		ns
t_{QVXH}	16	Output data setup to clock rising edge	283		$10t_{CLCL}$–133		167		ns
t_{XHQX}	16	Output data hold after clock rising edge	3		$2t_{CLCL}$–80				ns
t_{XHDX}	16	Input data hold after clock rising edge	0		0		0		ns
t_{XHDV}	16	Clock rising edge to input data valid		283		$10t_{CLCL}$–133		167	ns

NOTES:
1. Parameters are valid over operating temperature range unless otherwise specified.
2. Load capacitance for port 0, ALE, and $\overline{PSEN}$ = 100pF, load capacitance for all other outputs = 80pF.
3. Interfacing the 80C52/54/58 to devices with float times up to 45ns is permitted. This limited bus contention will not cause damage to Port 0 drivers.
4. Variable clock is specified for oscillator frequencies greater than 16MHz to 33MHz. For frequencies equal or less than 16MHz, see 16MHz “AC Electrial Characteristics”, page 20.

EXPLANATION OF THE AC SYMBOLS

Each timing symbol has five characters. The first character is always 't' (= time). The other characters, depending on their positions, indicate the name of a signal or the logical status of that signal. The designations are:

A – Address
C – Clock
D – Input data
H – Logic level high
I – Instruction (program memory contents)
L – Logic level low, or ALE
P – $\overline{\text{PSEN}}$
Q – Output data
R – $\overline{\text{RD}}$ signal
t – Time
V – Valid
W – $\overline{\text{WR}}$ signal
X – No longer a valid logic level
Z – Float

Examples: t_{AVLL} = Time for address valid to ALE low.
t_{LLPL} =Time for ALE low to $\overline{\text{PSEN}}$ low.

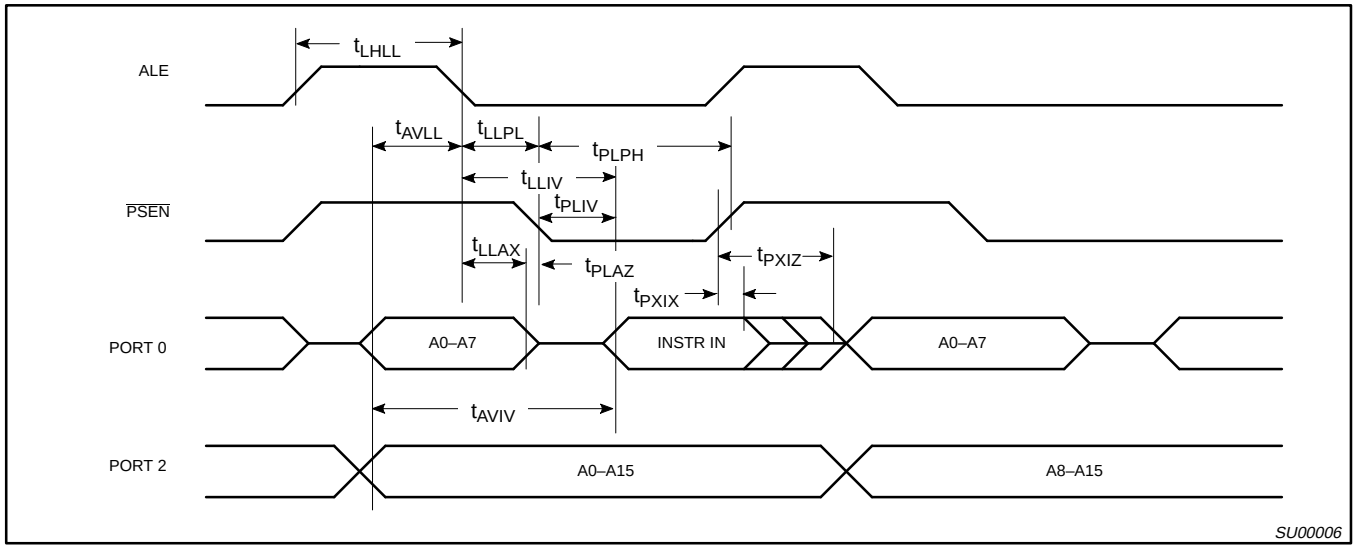


Figure 13. External Program Memory Read Cycle

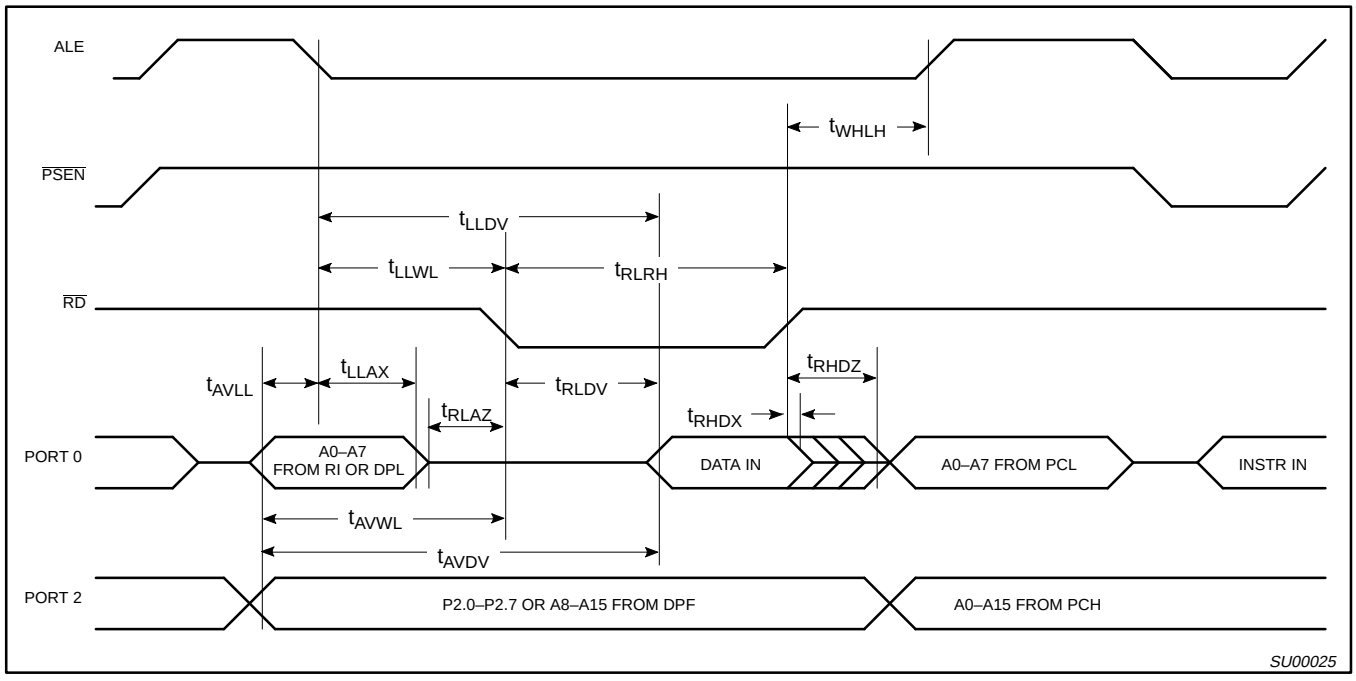


Figure 14. External Data Memory Read Cycle

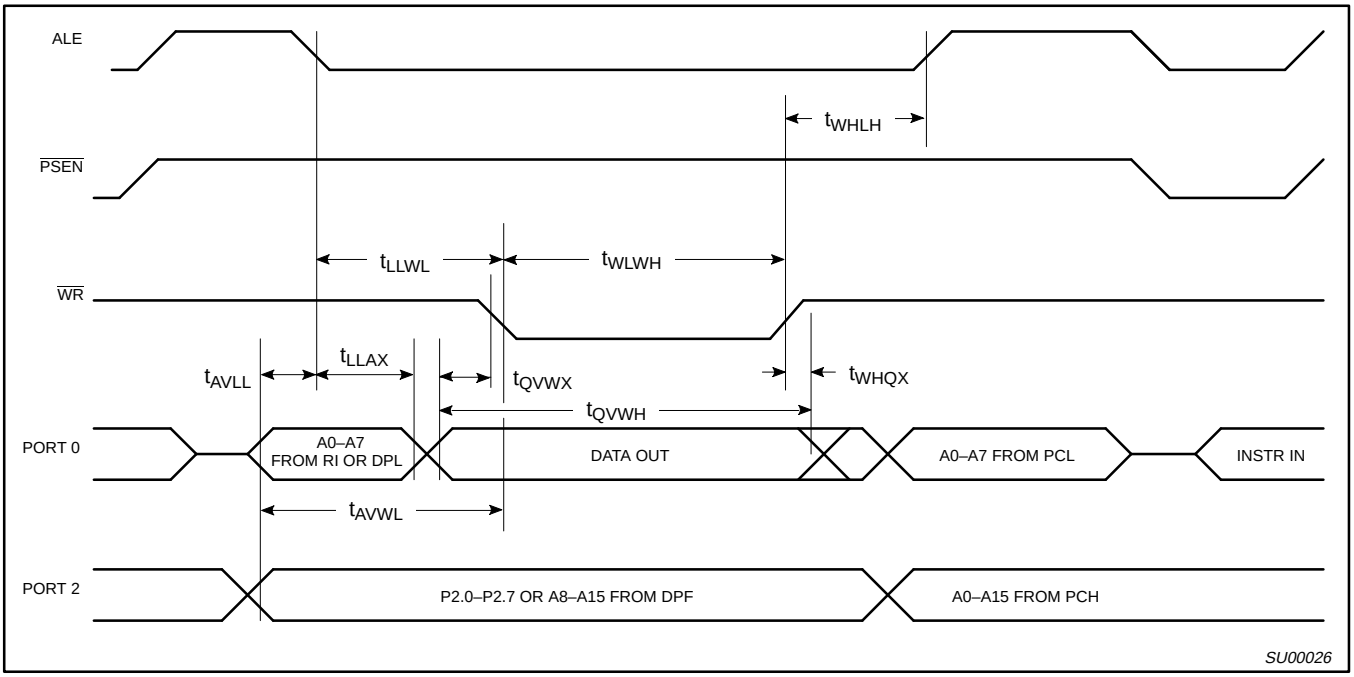


Figure 15. External Data Memory Write Cycle

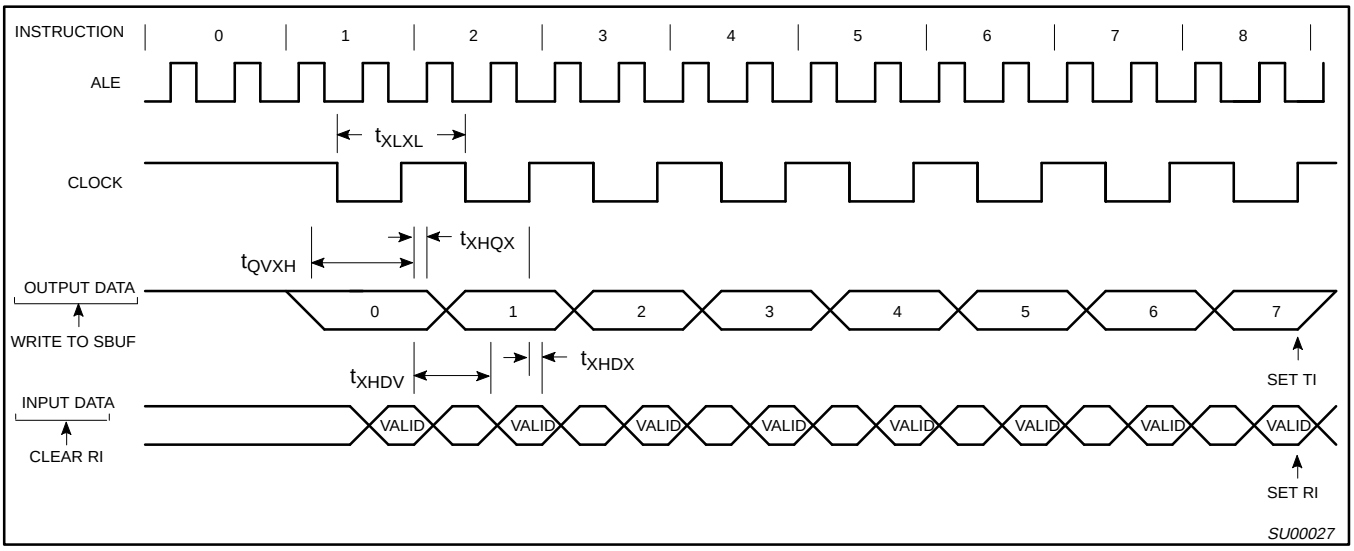


Figure 16. Shift Register Mode Timing

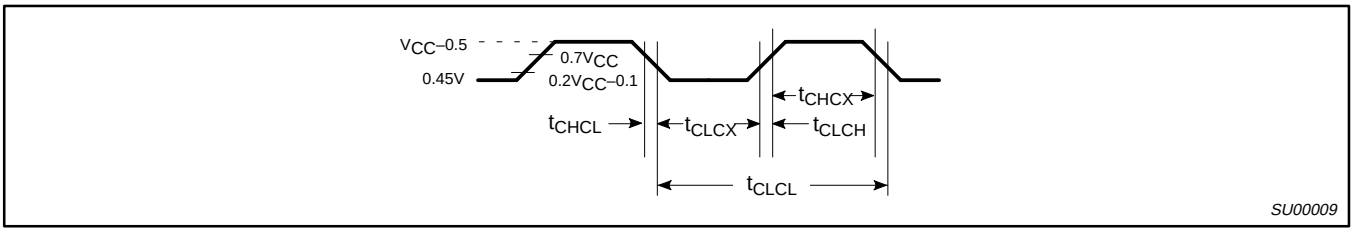


Figure 17. External Clock Drive

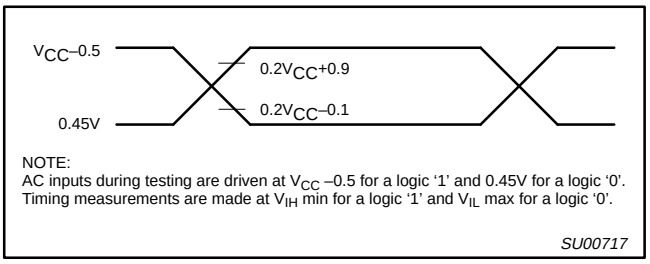


Figure 18. AC Testing Input/Output

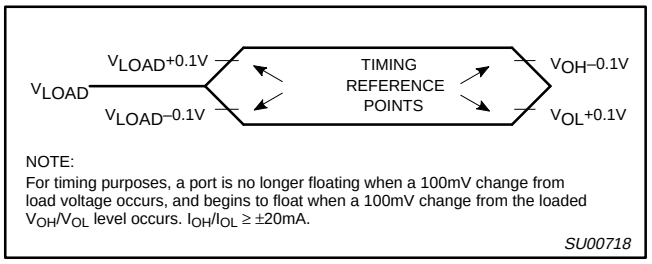


Figure 19. Float Waveform

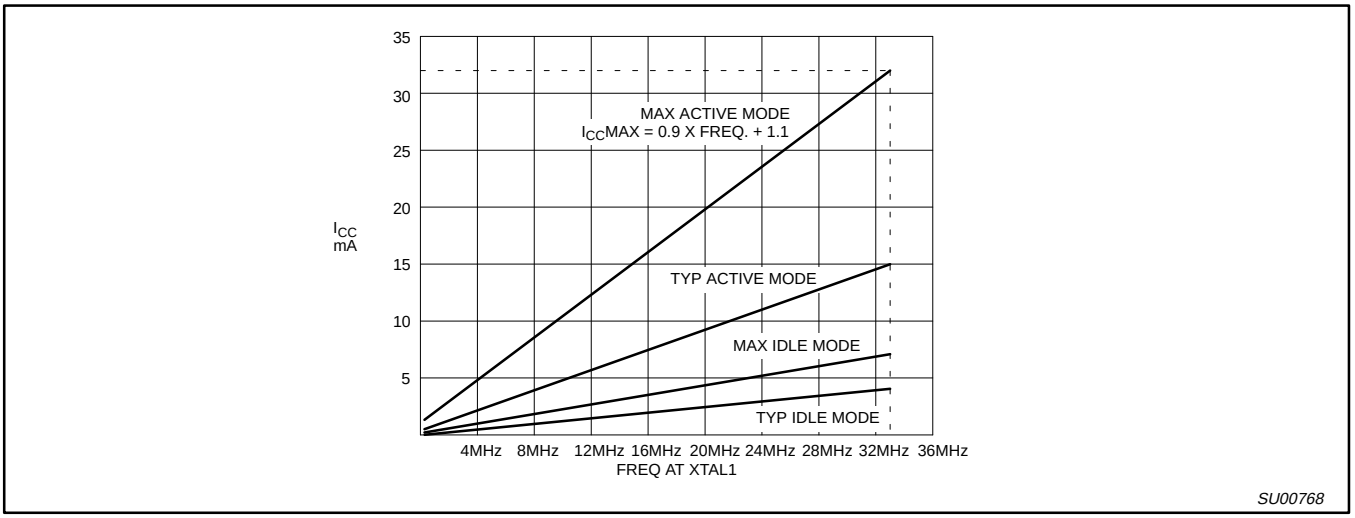


Figure 20. I_{CC} vs. FREQ
Valid only within frequency specifications of the device under test

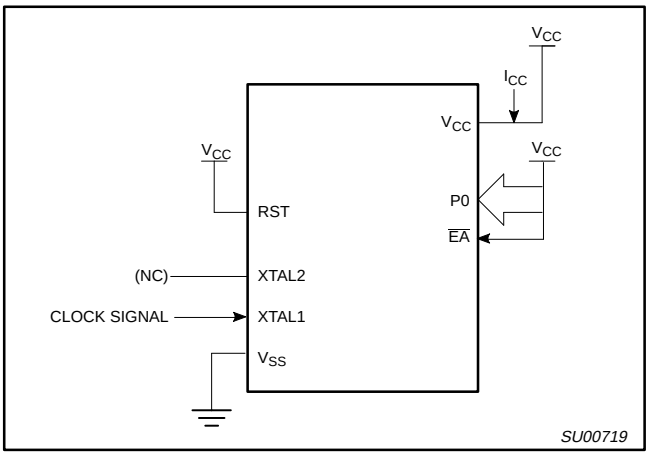


Figure 21. I_{CC} Test Condition, Active Mode
All other pins are disconnected

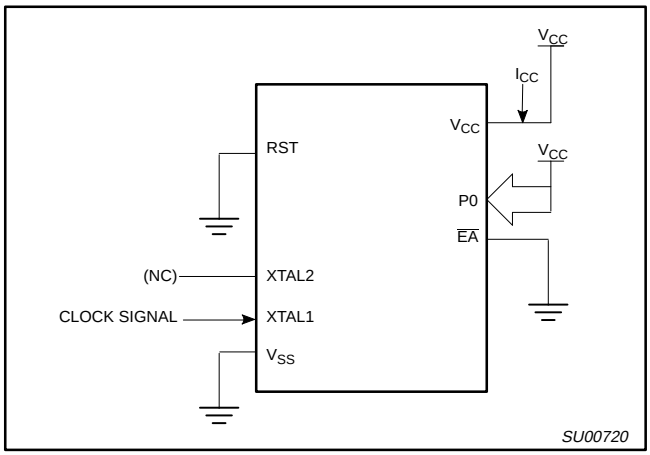


Figure 22. I_{CC} Test Condition, Idle Mode
All other pins are disconnected

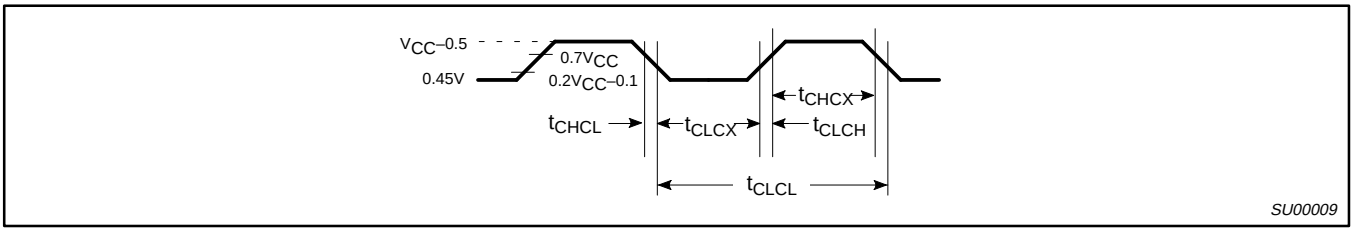


Figure 23. Clock Signal Waveform for I_{CC} Tests in Active and Idle Modes
$t_{CLCH} = t_{CHCL} = 5ns$

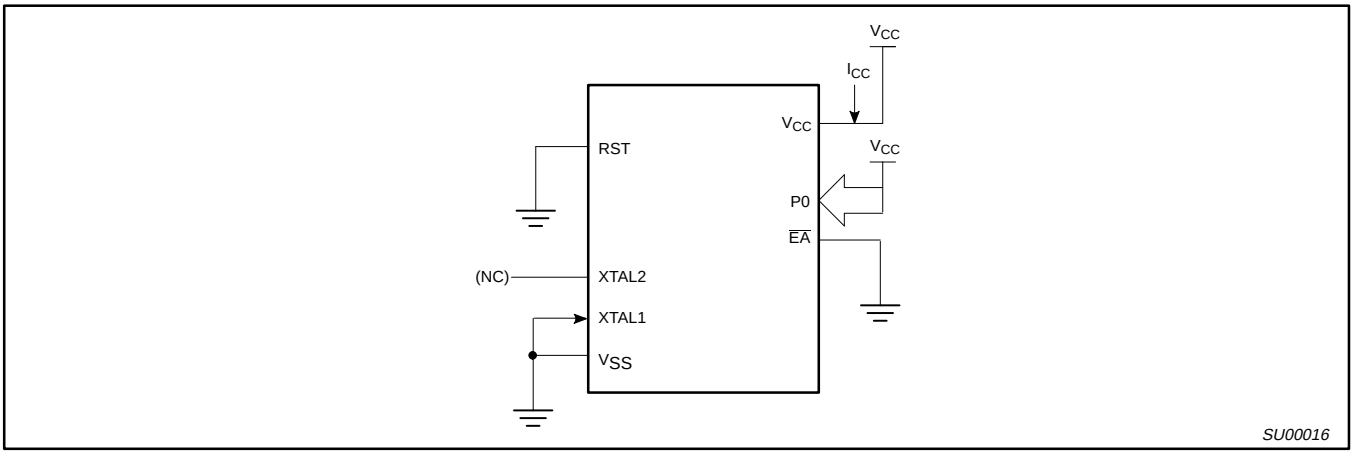


Figure 24. I_{CC} Test Condition, Power Down Mode
All other pins are disconnected. V_{CC} = 2V to 5.5V

Security Bits

With none of the security bits programmed the code in the program memory can be verified. If the encryption table is programmed, the code will be encrypted when verified. When only security bit 1 (see Table 8) is programmed, MOVC instructions executed from external program memory are disabled from fetching code bytes from the internal memory, $\overline{EA}$ is latched on Reset and all further programming of the EPROM is disabled. When security bits 1 and 2 are programmed, in addition to the above, verify mode is disabled.

Encryption Array

64 bytes of encryption array are initially unprogrammed (all 1s).

Table 8. Program Security Bits

PROGRAM LOCK BITS[1, 2]			
	SB1	SB2	PROTECTION DESCRIPTION
1	U	U	No Program Security features enabled. (Code verify will still be encrypted by the Encryption Array if programmed.)
2	P	U	MOVC instructions executed from external program memory are disabled from fetching code bytes from internal memory, $\overline{EA}$ is sampled and latched on Reset, and further programming of the EPROM is disabled.

NOTES:
1. P – programmed. U – unprogrammed.
2. Any other combination of the security bits is not defined.

80C52 ROM CODE SUBMISSION

When submitting ROM code for the 80C52, the following must be specified:
1. 8k byte user ROM data
2. 64 byte ROM encryption key
3. ROM security bits.

ADDRESS	CONTENT	BIT(S)	COMMENT
0000H to 1FFFH	DATA	7:0	User ROM Data
2000H to 201FH	KEY	7:0	ROM Encryption Key FFH = no encryption
2020H	SEC	0	ROM Security Bit 1 0 = enable security 1 = disable security
2020H	SEC	1	ROM Security Bit 2 0 = enable security 1 = disable security

Security Bit 1: When programmed, this bit has two effects on masked ROM parts:
1. External MOVC is disabled, and
2. $\overline{EA}$ is latched on Reset.

Security Bit 2: When programmed, this bit inhibits Verify User ROM.

If the ROM Code file does not include the options, the following information must be included with the ROM code.

For each of the following, check the appropriate box, and send to Philips along with the code:

Security Bit #1: ☐ Enabled ☐ Disabled

Security Bit #2: ☐ Enabled ☐ Disabled

Encryption: ☐ No ☐ Yes If Yes, must send key file.

80C54 ROM CODE SUBMISSION

When submitting ROM code for the 80C54, the following must be specified:

1. 16k byte user ROM data
2. 64 byte ROM encryption key
3. ROM security bits.

ADDRESS	CONTENT	BIT(S)	COMMENT
0000H to 3FFFH	DATA	7:0	User ROM Data
4000H to 401FH	KEY	7:0	ROM Encryption Key FFH = no encryption
4020H	SEC	0	ROM Security Bit 1 0 = enable security 1 = disable security
4020H	SEC	1	ROM Security Bit 2 0 = enable security 1 = disable security

Security Bit 1: When programmed, this bit has two effects on masked ROM parts:

1. External MOVC is disabled, and
2. $\overline{EA}$ is latched on Reset.

Security Bit 2: When programmed, this bit inhibits Verify User ROM.

If the ROM Code file does not include the options, the following information must be included with the ROM code.

For each of the following, check the appropriate box, and send to Philips along with the code:

Security Bit #1: ☐ Enabled ☐ Disabled

Security Bit #2: ☐ Enabled ☐ Disabled

Encryption: ☐ No ☐ Yes If Yes, must send key file.

80C58 ROM CODE SUBMISSION

When submitting ROM code for the 80C58, the following must be specified:

1. 32k byte user ROM data
2. 64 byte ROM encryption key
3. ROM security bits.

If submitting a file, the format is as follows:

ADDRESS	CONTENT	BIT(S)	COMMENT
0000H to 7FFFH	DATA	7:0	User ROM Data
8000H to 801FH	KEY	7:0	ROM Encryption Key FFH = no encryption
8020H	SEC	0	ROM Security Bit 1 0 = enable security 1 = disable security
8020H	SEC	1	ROM Security Bit 2 0 = enable security 1 = disable security

Security Bit 1: When programmed, this bit has two effects on masked ROM parts:

1. External MOVC is disabled, and
2. $\overline{EA}$ is latched on Reset.

Security Bit 2: When programmed, this bit inhibits Verify User ROM.

If the ROM code file does not include the options, the following information must be included with the ROM code.

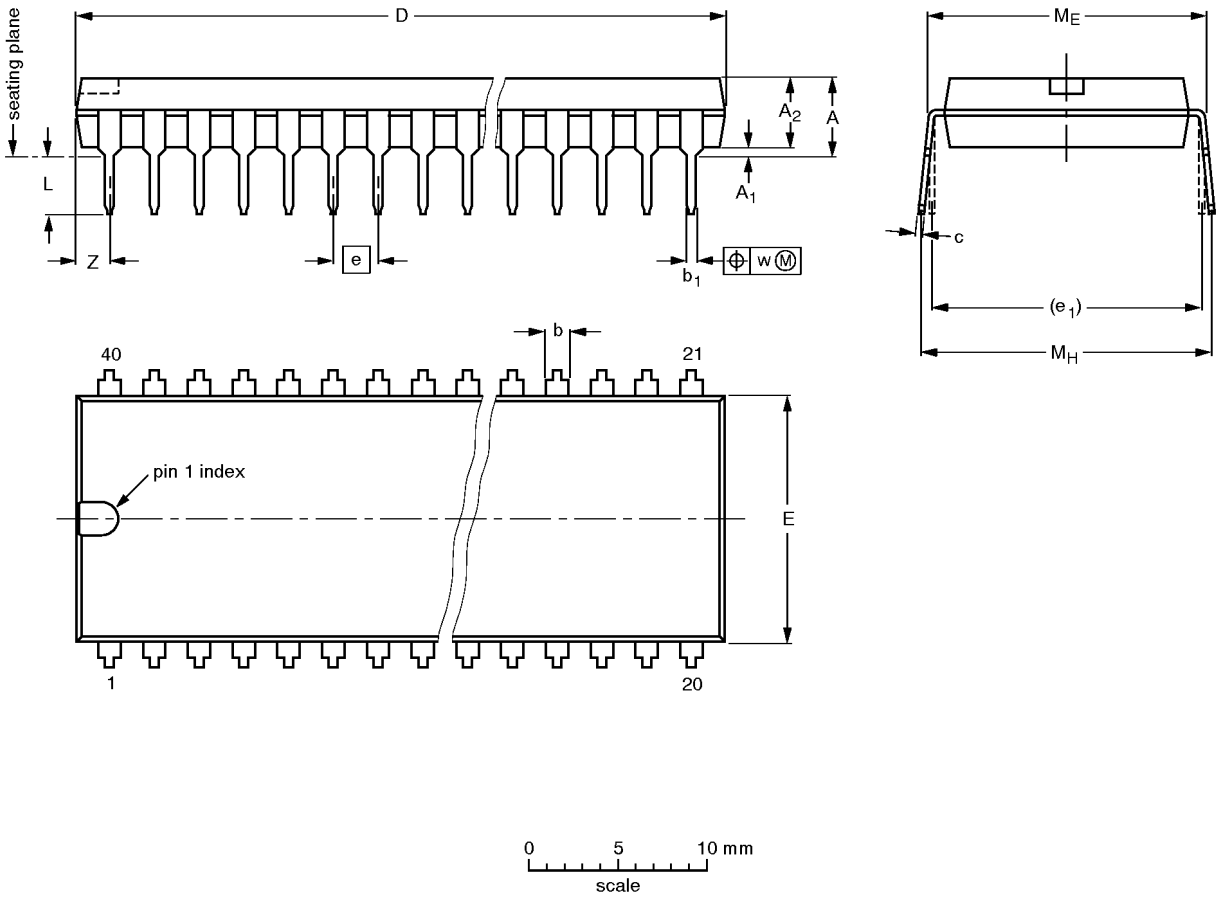
For each of the following check the appropriate box and send to Philips along with the code:

Security Bit #1: ☐ Enabled ☐ Disabled

Security Bit #2: ☐ Enabled ☐ Disabled

Encryption: ☐ No ☐ Yes If Yes, must send key file.

DIP40: plastic dual in-line package; 40 leads (600 mil) SOT129-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

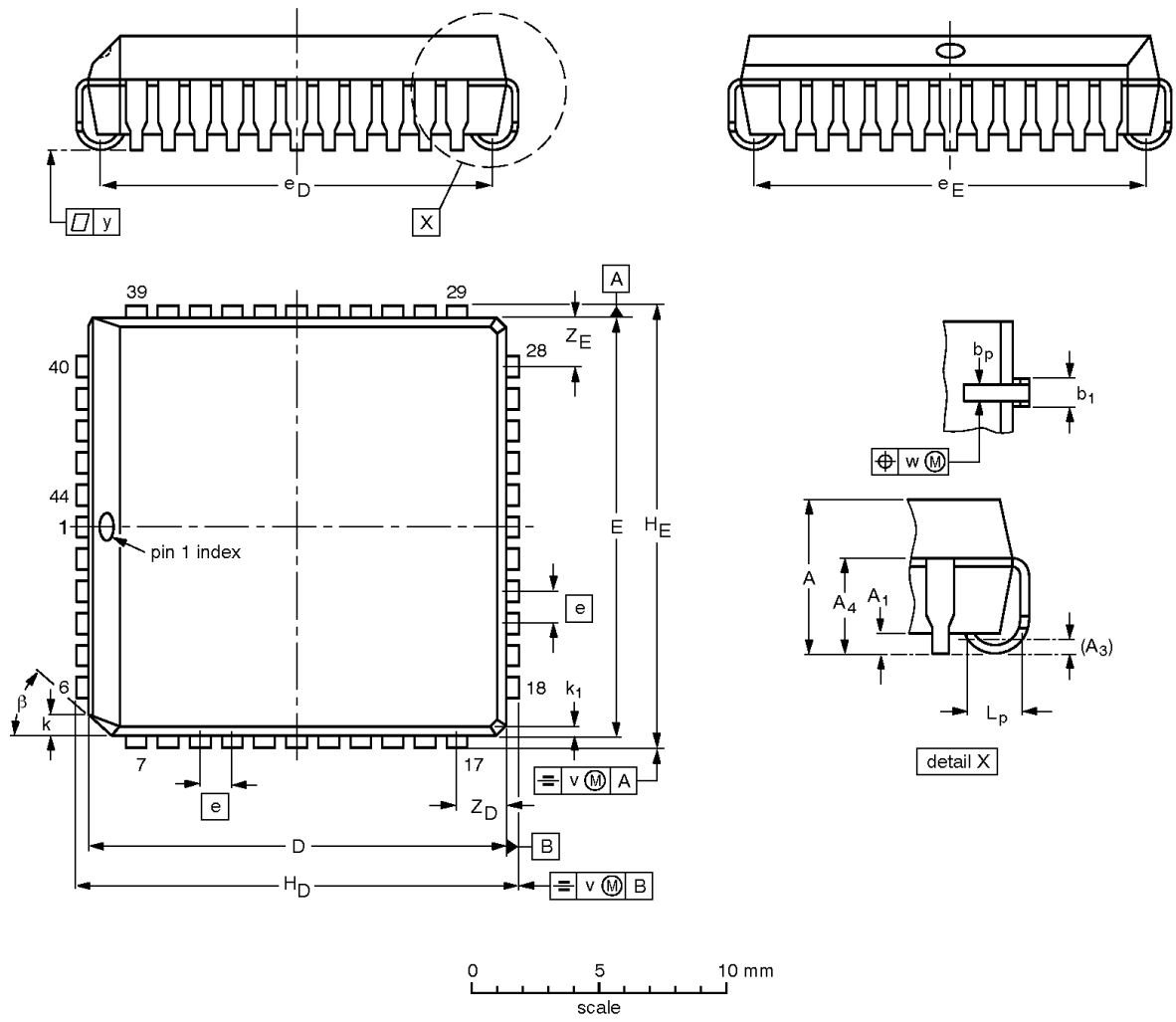
UNIT	A max.	A_1 min.	A_2 max.	b	b_1	c	D (1)	E (1)	e	e_1	L	M_E	M_H	w	Z (1) max.
mm	4.7	0.51	4.0	1.70 1.14	0.53 0.38	0.36 0.23	52.50 51.50	14.1 13.7	2.54	15.24	3.60 3.05	15.80 15.24	17.42 15.90	0.254	2.25
inches	0.19	0.020	0.16	0.067 0.045	0.021 0.015	0.014 0.009	2.067 2.028	0.56 0.54	0.10	0.60	0.14 0.12	0.62 0.60	0.69 0.63	0.01	0.089

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT129-1	051G08	MO-015AJ				~~92-11-17~~ 95-01-14

PLCC44: plastic leaded chip carrier; 44 leads SOT187-2



DIMENSIONS (millimetre dimensions are derived from the original inch dimensions)

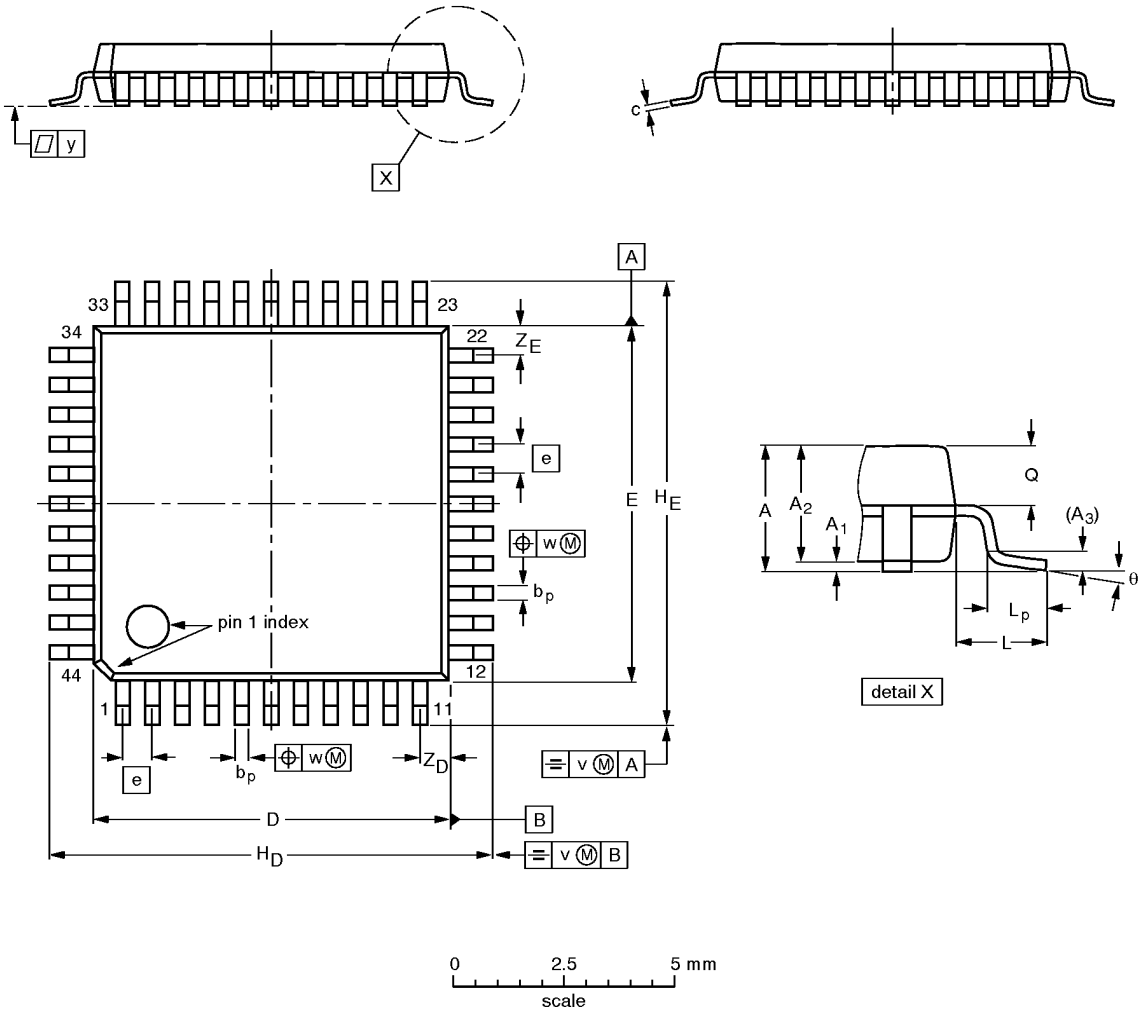
UNIT	A	A_1 min.	A_3	A_4 max.	b_p	b_1	$D^{(1)}$	$E^{(1)}$	e	e_D	e_E	H_D	H_E	k	k_1 max.	L_p	v	w	y	$Z_D^{(1)}$ max.	$Z_E^{(1)}$ max.	β
mm	4.57 4.19	0.51	0.25	3.05	0.53 0.33	0.81 0.66	16.66 16.51	16.66 16.51	1.27	16.00 14.99	16.00 14.99	17.65 17.40	17.65 17.40	1.22 1.07	0.51	1.44 1.02	0.18	0.18	0.10	2.16	2.16	45°
inches	0.180 0.165	0.020	0.01	0.12	0.021 0.013	0.032 0.026	0.656 0.650	0.656 0.650	0.05	0.630 0.590	0.630 0.590	0.695 0.685	0.695 0.685	0.048 0.042	0.020	0.057 0.040	0.007	0.007	0.004	0.085	0.085	

Note

1. Plastic or metal protrusions of 0.01 inches maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT187-2	112E10	MO-047AC				~~92-11-17~~ 95-02-25

QFP44: plastic quad flat package; 44 leads (lead length 1.3 mm); body 10 x 10 x 1.75 mm SOT307-2



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(1)}$	e	H_D	H_E	L	L_p	Q	v	w	y	$Z_D^{(1)}$	$Z_E^{(1)}$	θ
mm	2.10	0.25 0.05	1.85 1.65	0.25	0.40 0.20	0.25 0.14	10.1 9.9	10.1 9.9	0.8	12.9 12.3	12.9 12.3	1.3	0.95 0.55	0.85 0.75	0.15	0.15	0.1	1.2 0.8	1.2 0.8	10° 0°

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT307-2						~~92-11-17~~ 95-02-04

DEFINITIONS

Data Sheet Identification	Product Status	Definition
Objective Specification	**Formative or in Design**	This data sheet contains the design target or goal specifications for product development. Specifications may change in any manner without notice.
Preliminary Specification	**Preproduction Product**	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.
Product Specification	**Full Production**	This data sheet contains Final Specifications. Philips Semiconductors reserves the right to make changes at any time without notice, in order to improve design and supply the best possible product.

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